

MAX98397

Click here to ask an associate for production status of specific part numbers.

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

General Description

The MAX98397 is a high-efficiency, mono Class-DG speaker amplifier with industry-leading quiescent power, featuring integrated speaker current and voltage sensing (IVSENSE), a brownout-prevention engine (BPE), and dynamic-headroom tracking (DHT). The device also enables ultrasound applications by providing support for sample rates up to 192kHz, a higher passband (for $f_{\rm S} > 50 {\rm kHz})$, and a bypass path for the ultrasound signals through the amplifier so it is not attenuated by the audio processing. Precision output current monitoring (ISENSE) and voltage monitoring (VSENSE) enable speaker protection algorithms to be run by a host device. Spread-spectrum modulation (SSM) and edge rate control minimize EMI and eliminate the need for the output filtering found in traditional Class-D devices.

To achieve industry-leading quiescent power, the Class-DG architecture employs two supply rails; VBAT (3V to 5.5V) and PVDD (3V to 28V) to supply the speaker amplifier. The Class-DG amplifier switches between the two supply rails depending on the input signal level and/or the supply headroom.

For battery-powered applications, the BPE is designed to help prevent the possibility of a system brownout by reducing the device's contribution to the overall system power consumption. This is achieved by either attenuating or limiting the amplifier output when the device supply drops below a set of programmable BPE thresholds. Additionally, as the power-supply voltage varies due to sudden transients and declining battery life, DHT automatically optimizes the headroom available to the Class-DG amplifier to maintain consistent distortion and listening levels.

The device provides a PCM interface for audio data and a standard I²C interface for control data communication. The PCM interface supports audio playback using I²S, left-justified, and time-division multiplexing audio data formats. A unique clocking structure eliminates the need for an external system clock (MCLK) for PCM communication, which reduces pin count and simplifies board layout.

Thermal foldback, when enabled, automatically reduces the output power when the temperature exceeds a user-specified threshold. This allows for uninterrupted music playback even at high ambient temperatures. Traditional thermal protection is also available in addition to robust overcurrent protection.

The device is available in a 0.4mm pitch, 35-bump waferlevel package (WLP). The device operates over the extended -40°C to +85°C temperature range.

Applications

- Mobile Speakers and Smart Speakers
- Tablets, Laptop and Desktop Computers
- Soundbars
- Smart IOT

Benefits and Features

- Wide Input Supply Range (3V to 28V)
- Class-DG Operation Enables Industry Leading Quiescent Power
 - 21mW at V_{PVDD} = 20V, V_{VBAT} = 3.8V
 - 25.3mW at V_{PVDD} = 24V, V_{VBAT} = 5.0V
- Ultra-Low Noise Floor
 - 21.5µV_{RMS} Output Noise
 - 117.8dB Dynamic Range
- Low Distortion
 - -85dB THD+N at 3W into 8Ω , f = 1kHz
 - -85dB THD+N at 6W into 4Ω , f = 1kHz
 - -80dB THD+N at 1W into 8Ω , f = 6kHz, F_{SW} = 650kHz
- Output Power:
 - 42W into 8Ω , V_{PVDD} = 28V, THD+N = 1%
 - 26W into 4Ω , $V_{PVDD} = 16V$, THD+N = 1%
 - 51W into 8Ω, V_{PVDD} = 28V, THD+N = 10%
- 100W Peak Output Power into 4Ω, V_{PVDD} = 28V
- Speaker Amplifier Efficiency:
 - 83% at 1W into 8Ω, V_{PVDD} = 24V
 - 93% Peak Efficiency into 8Ω, V_{PVDD} = 24V
 - 81% at 1W into 4Ω , $V_{PVDD} = 24V$
 - 90% Peak Efficiency into 4Ω, V_{PVDD} = 24V
- Class-D EMI Reduction Enables Filterless Operation
- Spread-Spectrum Modulation and Switching-Edge Rate Control
- Integrated Speaker Current and Voltage Sense Do Not Require External Components
- Flexible Brownout-Prevention Engine
- I²S/16-Channel TDM and I²C Digital Interfaces
- Playback Support for 16-, 24-, and 32-Bit Data Words
- Playback and IV Paths Support Sample Rates up to 192kHz
- Audio Processing Bypass Path
- Dynamic Headroom Tracking (DHT) Maintains a Consistent Listening Experience
- Extensive Click-and-Pop Suppression
- 35-Bump WLP (0.4mm Pitch)

<u>Ordering Information</u> appears at end of data sheet. SMBus is a trademark of Intel Corp.

19-101757; Rev 0; 10/23

Simplified Block Diagram

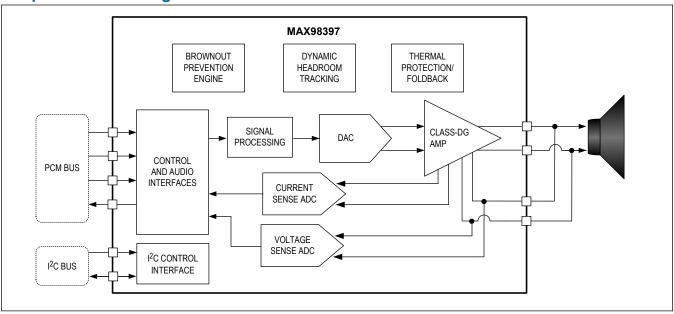


TABLE OF CONTENTS

General Description	
Applications	
Benefits and Features	
Simplified Block Diagram	
Absolute Maximum Ratings	
Package Information	
35 WLP	
Electrical Characteristics	
Typical Operating Characteristics	
Pin Configuration	
35 WLP	
Pin Description	
Detailed Description	
Device State Control	
Hardware-Shutdown State	
Software-Shutdown State	
Active State	
Device Sequencing	
Power-Supply Sequencing	
PCM Interface	
PCM Clock Configuration	
PCM Data Format Configuration	
I ² S/Left-Justified Mode	
TDM Modes	40
PCM Data Path Configuration	
PCM Data Input	
PCM Data Output	43
Data Output Channel-Interleaved I/V Sense Data	
Data Output Status Bits	45
Interrupts	46
Interrupt Bit Field Composition	46
Interrupt Output Configuration	46
Interrupt Sources	46
Speaker Path	48
Speaker Path Block Diagram	48
Speaker Playback Path	48
Speaker Path Noise Gate	
Speaker Path Dither	49
Speaker Path Data Inversion	49

28V Digital Input, Class-DG Amplifier with IV_{SENSE} , Ultra-Low I_Q , and Brownout Prevention

TABLE OF CONTENTS (CONTINUED)

Speaker Path DC Blocking Filter	. 49
Speaker Path Digital Volume Control	. 49
Speaker Path Digital Gain Control	. 49
Speaker Path DSP Data Feedback Path	. 49
Speaker-Safe Mode	. 49
Speaker Audio Processing Bypass Path	. 49
Bypass Path Data Inversion	. 49
Bypass Path Dither	. 50
Bypass Path DC Blocking Filter	. 50
Speaker Maximum Peak Output Voltage Scaling	. 50
Dynamic Headroom Tracking (DHT)	. 50
DHT Supply Tracking and Headroom	. 50
DHT Mode 1—Signal Distortion Limiter	. 53
DHT Mode 2—Signal Level Limiter	. 58
DHT Mode 3—Dynamic Range Compressor	. 60
DHT Mode 4—Dynamic Range Compressor with Signal Level Limiter	. 62
DHT Attenuation	. 64
DHT Attenuation Reporting	. 66
DHT Ballistics	. 66
Speaker Amplifier	. 67
Speaker Amplifier Operating Modes	. 67
Class-DG Mode Enabled	. 67
Delay for DG Mode	. 68
Class-DG Mode Disabled	. 68
IDLE Mode	. 68
Speaker Amplifier Ultra-Low EMI Filterless Operation	. 68
Speaker Amplifier Overcurrent Protection	. 69
Speaker Current and Voltage Sense ADC Path	. 69
Brownout-Prevention Engine	. 69
BPE State Controller and Level Thresholds	. 70
BPE Level Configuration Options	. 70
BPE Gain Attenuation Function	. 71
BPE Limiter Function	. 71
Brownout Interrupts	. 71
Measurement ADC	. 71
Measurement ADC Channel Optimal Mode	. 72
Measurement ADC Thermal Channel	. 72
Measurement ADC PVDD Channel	. 73
Measurement ADC VBAT Channel	. 73
	Speaker Path Digital Volume Control Speaker Path Digital Gain Control Speaker Path DSP Data Feedback Path Speaker-Safe Mode Speaker-Safe Mode Speaker Audio Processing Bypass Path Bypass Path Data Inversion Bypass Path Data Inversion Bypass Path Dither Speaker Maximum Peak Output Voltage Scaling Dynamic Headroom Tracking (DHT) DHT Supply Tracking and Headroom DHT Mode 1—Signal Distortion Limiter DHT Mode 2—Signal Level Limiter DHT Mode 3—Dynamic Range Compressor DHT Mode 3—Dynamic Range Compressor with Signal Level Limiter DHT Attenuation DHT Attenuation Reporting DHT Ballistics Speaker Amplifier Operating Modes Class-DG Mode Enabled Delay for DG Mode Class-DG Mode Disabled. IDLE Mode Speaker Amplifier Overcurrent Protection Speaker Current and Voltage Sense ADC Path Brownout-Prevention Engine BPE State Controller and Level Thresholds BPE Level Configuration Options BPE Limiter Function Brownout Interrupts Measurement ADC Measurement ADC Channel Optimal Mode Measurement ADC PVDD Channel

28V Digital Input, Class-DG Amplifier with $\mathsf{IV}_{\mathsf{SENSE}}, \mathsf{Ultra\text{-}Low} \; \mathsf{I}_{\mathsf{Q}}, \; \mathsf{and} \; \mathsf{Brownout} \; \mathsf{Prevention}$

TABLE OF CONTENTS (CONTINUED)

Measurement ADC VDDH Channel	74
Clock and Data Monitors	74
Input Data Monitor	74
Clock Monitor	75
Clock Activity and Frequency Detection	76
Clock Frame Error Detection	76
Speaker Monitor	77
Thermal Protection	77
Thermal Warning and Thermal Shutdown Configuration	77
Thermal Shutdown Recovery Configuration	77
Thermal Foldback	77
Tone Generator	78
Pink Noise Generator	78
Interchip Communication	78
ICC Operation and Data Format	79
Multiamplifier Grouping	79
ICC Over PCM Output (DOUT)	80
I ² C Serial Interface	81
Peripheral Address	81
Bit Transfer	82
START and STOP Conditions	82
Early STOP Conditions	82
Acknowledge	82
Write Data Format	83
Read Data Format	84
I ² C Register Map	85
Control Bit Field Types and Write Access Restrictions	85
Register Map	
Register Map	86
Register Details	
Applications Information	. 168
Layout and Grounding	. 168
Recommended External Components	
Bootstrap Capacitors	. 168
Typical Application Circuits	. 169
Typical Application Circuit	. 169
Ordering Information	. 169
Revision History	. 170

LIST OF FIGURES

Figure 1. Standard I ² S Mode	39
Figure 2. Left-Justified Mode	39
Figure 3. Left-Justified Mode (LRCLK Inverted)	40
Figure 4. Left-Justified Mode (BCLK Inverted)	40
Figure 5. TDM Modes	42
Figure 6. PCM Data Input	43
Figure 7. I ² S Mode with Interleaved Voltage and Current Data, Channel Length = 24 Bits, Zero Padding	45
Figure 8. Speaker Signal Path Diagram	48
Figure 9. Simplified Dynamic Headroom Tracking System Block Diagram	50
Figure 10. V _{TPO} and A _{TPO} Calculation Example	52
Figure 11. Signal Distortion Limiter with V _{MPO} ≤ V _{SUP} and +20% Headroom (SUP _{HR})	54
Figure 12. Signal Distortion Limiter with $V_{MPO} \le V_{SUP}$ and 0% Headroom (SUP _{HR})	55
Figure 13. Signal Distortion Limiter with $V_{MPO} \le V_{SUP}$ and -20% Headroom (SUP _{HR})	56
Figure 14. Signal Distortion Limiter with V_{MPO} > V_{SUP} and +20% Headroom (SUP $_{HR}$)	57
Figure 15. Signal Distortion Limiter with V_{MPO} > V_{SUP} and 0% Headroom (SUP $_{HR}$)	57
Figure 16. Signal Distortion Limiter with V_{MPO} > V_{SUP} and -20% Headroom (SUP $_{HR}$)	58
Figure 17. Signal Level Limiter with V _{TPO} > V _{SLL} as V _{SUP} Decreases	59
Figure 18. Signal Level Limiter with V _{TPO} < V _{SLL} Showing Amplifier Output Clipping	60
Figure 19. Dynamic Range Compression with Decreasing V_{SUP} and $SUP_{HR} \ge 0\%$	61
Figure 20. Dynamic Range Compressor with SUP _{HR} < 0% and Output Clipping	62
Figure 21. DHT DRC and SLL with Decreasing V _{SUP} (V _{TPO}), and SUP _{HR} ≥ 0%	63
Figure 22. DHT DRC and SLL with Decreasing V _{SUP} (V _{TPO}), and SUP _{HR} < 0%	64
Figure 23. Distortion Limiter Case with -20% Headroom and A _{MAX} Exceeded	65
Figure 24. Distortion Limiter Case with +20% Headroom and A _{MAX} Exceeded	66
Figure 25. BPE Block Diagram	70
Figure 26. Data Monitor Error Generation due to Input Data Stuck Error Detection	75
Figure 27. Monitor Error Generation due to Input Data Magnitude Error Detection	75
Figure 28. Clock Monitor LRCLK Rate Error Example with CMON_ERRTOL = 0x1	76
Figure 29. Clock Monitor Framing Error Example in TDM Mode with PCM_BSEL = 0x6 and CMON_BSELTOL =	
0x0	
Figure 30. ICC Multigroup Example with Two Groups and Four Total Devices	
Figure 31. I ² C Interface Timing Diagram	
Figure 32. I ² C START, STOP, and REPEATED START Conditions	
Figure 33. I ² C Acknowledge	
Figure 34. I ² C Writing One Byte of Data to the Peripheral	
Figure 35. I ² C Writing n-Bytes of Data to the Peripheral	
Figure 36. I ² C Controller Reading One Byte of Data from the Peripheral.	
Figure 37. I ² C Controller Reading n-Bytes of Data from the Peripheral	84

28V Digital Input, Class-DG Amplifier with IV_{SENSE} , Ultra-Low I_Q , and Brownout Prevention

LIST OF TABLES

Table 1. Typical Power-Up Sequence	37
Table 2. Typical Power-Down Sequence	37
Table 3. Sample Rate Selection For I/V Sense	38
Table 4. Supported I ² S/Left-Justified Mode Configurations	39
Table 5. Supported TDM Mode Configurations	40
Table 6. Supported PCM Data Output Types	44
Table 7. Interrupt Sources	46
Table 8. Noise Gate Threshold LSB Location by Input Data Configuration	49
Table 9. Brownout-Prevention Engine Levels	70
Table 10. Measurement ADC Channels Sample Rate in Optimal Modes	72
Table 11. I ² C Peripheral Address	81
Table 12. Control Bit Types and Write Access Restrictions	85
Table 13. Component List	168

Absolute Maximum Ratings

VBAT to PGND	0.3V to +6.0V
PVDD, VDDH_SNS to PGND	0.3V to +33V
PVDD to VBAT	0.3V to 33 - V _{VBAT} V
AGND, DGND to PGND	0.1V to +0.1V
AVDD to AGND	0.3V to +2.2V
DVDD to DGND	0.3V to +2.2V
OUTP, OUTN to PGND	0.3V to V _{PVDD} + 0.3V
OUTPSNS, OUTNSNS to PGND	0.3V to +33 V
VBOOTP to OUTP, VBOOTN to OUTN	0.3V to 2.2V
SDA, SCL, ADDR1, ADDR2 to DGND	0.3V to +6.0V

All Other Digital Pins to DGND0.	3V to V _{DVDD} + 0.3V
Short-Circuit Duration Between OUTP, Ol	JTN, and PGND or
PVDD or VBAT	Continuous
Short-Circuit Duration Between OUTP and C	OUTN Continuous
Continuous Power Dissipation for Multilayer	Board ($T_A = +70^{\circ}C$,
derate 21.59mW/°C above +70°C)	1726mW
Junction Temperature	+150°C
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +150°C
Soldering Temperature (reflow)	+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Package Information

35 WLP

00 1121			
Package Code	W352B2Z+1		
Outline Number	<u>21-100607</u>		
Land Pattern Number	Refer to Application Note 1891		
Thermal Resistance, Six-Layer EV Kit Board:			
Junction-to-Ambient (θ _{JA})	28°C/W		
Junction-to-Case Thermal Resistance (θ_{JC})	3°C/W		
Thermal Resistance, Four-Layer JEDEC Board:			
Junction-to-Ambient (θ _{JA})	46.33°C/W		
Junction-to-Case Thermal Resistance (θ_{JC})	3°C/W		

For the latest package outline information and land patterns (footprints), go to https://www.analog.com/en/design-center/packaging-quality-symbols-footprints/package-index. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to https://www.analog.com/en/technical-articles/thermal-characterization-of-ic-packages.

Electrical Characteristics

 $(V_{VBAT}=5.0V,V_{PVDD}=24V,V_{AVDD}=1.8V,V_{DVDD}=1.8V,C_{VBAT}=1x10\mu\text{F},1x0.1\mu\text{F},C_{PVDD}=1x220\mu\text{F},2x10\mu\text{F},2x0.1\mu\text{F},C_{AVDD}=1\mu\text{F},C_{DVDD}=1\mu\text{F},C_{VBOOTP}=0.1\mu\text{F},C_{VBOOTN}=0.1\mu\text{F},Z_{SPK}=0\text{pen},f_{S}=48\text{kHz},AC$ Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), $T_{A}=T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_{A}=+25^{\circ}\text{C}$ (Note 2))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
POWER SUPPLIES						
VBAT Power-Supply Operating Voltage Range	V _{VBAT}		3.0		5.5	V
VBAT Voltage	V _{VBAT}	Device is functional but parametric performance is not guaranteed	2.5			V

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CON	IDITIONS	MIN	TYP	MAX	UNITS
PVDD Power-Supply Operating Voltage Range	V _{PVDD}			3.0		28	V
PVDD Voltage	V _{PVDD}	Device is functional performance is not		2.8			V
AVDD Power-Supply Voltage Range	V _{AVDD}			1.71	1.8	1.89	V
DVDD Power-Supply Voltage Range	V _{DVDD}			1.71	1.8	1.89	V
VBAT Undervoltage Lockout	V _{VBAT_UVLO}	V _{VBAT} falling		2.26		2.36	V
PVDD Undervoltage Lockout	V _{PVDD_UVLO}	V _{PVDD} falling		2.54		2.64	V
AVDD Undervoltage Lockout	V _{AVDD_UVLO}	V _{AVDD} falling		1.61		1.67	V
AVDD POK Threshold	V _{AVDD_POK}	V _{AVDD} falling		1.28		1.65	V
DVDD Undervoltage Lockout	V _{DVDD_UVLO}	V _{DVDD} falling		1.61		1.67	V
DVDD POK Threshold	V _{DVDD_POK}	V _{DVDD} falling		1.28		1.66	V
VBAT UVLO Hysteresis		(<u>Note 3</u>)		90	110		mV
PVDD UVLO Hysteresis		(<u>Note 3</u>)		90	110		mV
Supply Ramp Rate PVDD				0.1		100	V/ms
POWER CONSUMPTION	l						
POWER CONSUMPTION	I / QUIESCENT F	POWER CONSUMP	TION				
			V _{PVDD} = 20V, V _{VBAT} = 3.8V, DG mode		21		
		All supplies, IV sense enabled	V _{PVDD} = 16V, V _{VBAT} = 3.8V, DG mode		20.1	23	
Total Power			V _{PVDD} = 24V, V _{VBAT} = 5.0V, DG mode		25.3	28.5	
Consumption	mption PQ All supplies, IV sense disabled All supplies, IV vPVDD = 20V, VVBAT = 3.8V, DG mode VPVDD = 16V, VVBAT = 3.8V, DG mode VPVDD = 24V, VVBAT = 5.0V, DG mode		15.5		- mW		
		V_{VBAT} = 3.8V, DG		15.5			
		V_{VBAT} = 5.0V, DG		19.8			

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CONE	OITIONS	MIN	TYP	MAX	UNITS
			V _{PVDD} = 24V, V _{VBAT} = 3.8V, DG mode, noise gate enabled		4.2		
Total Power Consumption	PQ	All supplies, IV sense disabled	V _{PVDD} = 16V, V _{VBAT} = 3.8V, DG mode, noise gate enabled		4.1		mW
			V _{PVDD} = 27V, V _{VBAT} = 5.0V, DG mode, noise gate enabled		4.3		
PVDD Quiescent Current	I _{Q_PVDD}	IV sense enabled, V = 5V, DG mode	_{PVDD} = 24V, V _{VBAT}		0.12	0.17	mA
AVDD Quiescent Current	I _{AVDD}	IV sense enabled, V = 5V, DG mode	_{PVDD} = 24V, V _{VBAT}		2.4	3	mA
DVDD Quiescent Current	I _{DVDD}	IV sense enabled, V = 5V, DG mode		3.6	4	mA	
VBAT Quiescent Current	I _{VBAT}	IV sense enabled, V = 5V, DG mode		2.33	2.6	mA	
POWER CONSUMPTIO	N / SOFTWARE S	HUTDOWN					
		VBAT = 3.8V, No Bottransactions, T _A = +			0.2	1.2	
VBAT Software	I _{SHDN_SW_VB}		VBAT = 3.8V, No BCLK/LRCLK/DIN transactions, $T_A = +85^{\circ}C$ (Note 3)			1.5	
Shutdown Supply Current	AT		VBAT = 5.0V, No BCLK/LRCLK/DIN transactions, T _A = +25°C			2.6	μA
		VBAT = 5.0V, No Bottransactions, T _A = +			3.0		
		PVDD = 5.0V, No Betransactions, T _A = +			0.2	1.5	
			PVDD = 5.0V, No BCLK/LRCLK/DIN ransactions, T _A = +85°C (<u>Note 3</u>)			2	
PVDD Software	I _{SHDN_SW_PV}	PVDD = 16V, No BCLK/LRCLK/DIN transactions, T _A = +25°C			0.8	4.2]
Shutdown Supply Current	DD DD	PVDD = 16V, No BO transactions, T _A = +				5.1	μA
		PVDD = 28V, No BC transactions, T _A = +	CLK/LRCLK/DIN		2	10	1
		PVDD = 28V, No BC transactions, T _A = +				10	

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
AVDD Software	I _{SHDN_SW_AV}	No BCLK/LRCLK/DIN transactions, T _A = +25°C		1.5	5	
Shutdown Supply Current	DD	No BCLK/LRCLK/DIN transactions, T _A = +85°C (<i>Note 3</i>)		1		- μΑ
DVDD Software	I _{SHDN_SW_DV}	No BCLK/LRCLK/DIN transactions, T _A = +25°C		2.4	7.6	- μΑ
Shutdown Supply Current	DD	No BCLK/LRCLK/DIN transactions, T _A = +85°C (<i>Note 3</i>)			38	
POWER CONSUMPTION	/ HARDWARE	SHUTDOWN				
		VBAT = 3.8V, T _A = +25°C		0.1	1	
VBAT Hardware	I _{SHDN_HW_VB}	VBAT = 3.8V, T _A = +85°C (<u>Note 3</u>)			1	
Shutdown Supply Current	AT	VBAT = 5.0V, T _A = +25°C		0.2	1.5	μA
Carron		VBAT = 5.0V, T _A = +85°C (<u>Note 3</u>)			2	1
		PVDD = 5.0V, T _A = +25°C		0.15	1.3	
		PVDD = 5.0V, T _A = +85°C (<u>Note 3</u>)			1.6	1
PVDD Hardware	I _{SHDN_HW_PV}	PVDD = 16V, T _A = +25°C		0.7	4.2	- - μA -
Shutdown Supply Current	DD	PVDD = 16V, T _A = +85°C (<u>Note 3</u>)			5	
Carrone		PVDD = 28V, T _A = +25°C		1.2	7.7	
		PVDD = 28V, T _A = +85°C (<u>Note 3</u>)			10	
AVDD Hardware	laught that his	T _A = +25°C		0.6	2.5	
Shutdown Supply Current	ISHDN_HW_AV DD	T _A = +85°C (<u>Note 3</u>)			5.5	μA
DVDD Hardware	TOTAL TIME DA	T _A = +25°C		1.45	5	
Shutdown Supply Current	ISHDN_HW_DV DD	T _A = +85°C (<u>Note 3</u>)			35	μA
Input Leakage Current	IVDDHSNS_LK	V _{VDDH_SNS} = 0V		0.01	1	μA
input Leakage Current	G _	V _{VDDH_SNS} = 28V		0.5	1	μΛ
TURN-ON/OFF TIME						
		From EN bit set to 1 to full operation, volume ramp disabled (<u>Note 4</u>)		1.5	3.0	ms
Turn-On Time	t _{ON}	From EN bit set to 1 to full operation, volume ramp enabled (<u>Note 4</u>)		3.0	6.0	ms
		Playback path re-enable: From SPK_EN bit set to 1 to full operation, EN = 1, volume ramp disabled		1		ms
Turn-Off Time		From full operation, EN bit set to 0 to software shutdown, volume ramp disabled		10	100	μs
	toff	From full operation, EN bit set to 0 to software shutdown, volume ramp enabled		2.3	5	ms
		From SPK_EN bit set to 0 to amplifier disabled, volume ramp disabled, EN = 1		10		μs

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	COND	ITIONS	MIN	TYP	MAX	UNITS
DIGITAL AUDIO PATH	1						
DIGITAL AUDIO PATH /	GAIN CONTROL	S / DIGITAL VOLUM	E CONTROL				
Digital Volume Control (Max)	A _{SPK_VOL}	SPK_VOL[6:0] = 0x0	00		0		dB
Digital Volume Control Step Size					0.5		dB
Digital Volume Control (Min)	A _{SPK_VOL}	SPK_VOL[6:0] = 0x8	34		-90		dB
DIGITAL AUDIO PATH /	FILTERING / DIC	SITAL HIGHPASS FIL	TER CHARACTERIS	TICS (<u>Note </u>	5)		
DC Attenuation				80			dB
DC Blocking Cut Off Frequency		All sample rates			1.872		Hz
DIGITAL AUDIO PATH /	FILTERING / DIC	SITAL FILTER CHAR	ACTERISTICS (LRCL	K < 50kHz) (Note 5		•
Valid Sample Rates				16		48	kHz
Passband Cutoff	f _{PLP}	Ripple < δ _P		0.452 x f _S			Hz
Passpariu Culoii		Droop < -3dB	0.457 x f _S			Hz	
Passband Ripple	δρ	f < f _{PLP} , referenced to signal level at 1kHz		-0.35		+0.35	dB
Stopband Cutoff	f _{SLP}	Attenuation > δ_S				0.49 x f _S	Hz
Stopband Attenuation	δ _S	f > f _{SLP}		75			dB
Max Group Delay		f = 1kHz			5.5		Samples
DIGITAL AUDIO PATH /	FILTERING / DIC	SITAL FILTER CHAR	ACTERISTICS (LRCL	K > 50kHz) (<u>Note 5</u>)		
Valid Sample Rates				88.2		192	kHz
	f _{PLP}		Ripple $< \delta_P$, $88.2kHz \le f_S \le$ 96kHz	0.227 x f _S			Hz
December 4 O 45"	f _{PLP}	SPK_WBAND_FIL	Droop < -3dB, $88.2kHz \le f_S \le$ 96kHz	0.314 x f _S			Hz
Passband Cutoff	f _{PLP}	T_EN = 0	Ripple $< \delta_P$, 176.4 kHz $\le f_S \le$ 192kHz	0.1135 x f _S			Hz
	f _{PLP}		Droop < -3dB cutoff, 176.4kHz \leq $f_S \leq$ 192kHz	0.232 x f _S			Hz
Passband Ripple	δρ	SPK_WBAND_FILT_EN = 0, f < f _{PLP} , referenced to signal level at 1kHz		-0.35		+0.35	dB
Stopband Cutoff	f _{SLP}	SPK_WBAND_FILT < δ _S			0.495 x f _S	Hz	
Stopband Attenuation	δ _S	SPK_WBAND_FILT	_EN = 0, f > f _{SLP}	80			dB

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	COND	ITIONS	MIN	TYP	MAX	UNITS
Max Group Delay		SPK_WBAND_FILT	_EN = 0, f = 1kHz		6		Samples
DIGITAL AUDIO PATH /	FILTERING / DI	GITAL FILTER CHAR	ACTERISTICS (LRCL	K > 50kHz) (<u>Note 5</u>)		
Valid Sample Rates				88.2		192	kHz
	f _{PLP}		Ripple $< \delta_P$, $88.2\text{kHz} \le f_S \le$ 96kHz	0.440 x f _S			Hz
Passband Cutoff		SPK_WBAND_FIL	Droop < -3dB, $88.2kHz \le f_S \le$ 96kHz	0.45 x f _S			Hz
Passpand Culon	f _{PLP}	17 19 Di CL	Ripple $< \delta_P$, 176.4kHz $\le f_S \le$ 192kHz	0.23 x f _S			Hz
			Droop < -3dB cutoff, 176.4kHz \leq $f_S \leq$ 192kHz	0.3 x f _S			Hz
Passband Ripple	δρ	SPK_WBAND_FILT referenced to signal	-0.5		+0.5	dB	
Stopband Cutoff	f _{SLP}	SPK_WBAND_FILT_EN = 1, attenuation $< \delta_S$				0.52 x f _S	Hz
Stopband Attenuation	δ _S	SPK_WBAND_FILT	-77			dB	
Max Group Delay		SPK_WBAND_FILT_EN = 1, f = 1kHz			5.5		Samples
Max Device-to-Device Group Delay Variability		f _{IN} = 1kHz			1		μs
CLASS-DG AMPLIFIER				•			•
Output Offset Voltage		T _A = +25°C, Z _{SPK} = DRE_EN = 0	8Ω + 33μΗ,	-3.5	±0.5	+3.5	mV
Output Offset Voltage	V _{OS}	T _A = +25°C, PVDD 1 33μH, DRE_EN = 0	mode, $Z_{SPK} = 8\Omega +$	-6	±0.5	+6	IIIV
Click and Dan Laval	V	per second, digital s	Peak voltage, A-weighted, 32 samples per second, digital silence used for input signal, ZSPK = $8\Omega + 33\mu$ H or $4\Omega + 33\mu$ H, into shutdown (<i>Note</i> 6)		-79		- dBV
Click-and-Pop Level	K _{CP}		ilence used for input 33μH or 4Ω + 33μH,		-69		ubv
	ηspk	$V_{PVDD} = 24V, V_{VBA}$ $1W, Z_L = 8\Omega + 33\mu H$	_T = 5.0V, P _{OUT} = I, f _{IN} = 1kHz		83		
Efficiency	na	$V_{PVDD} = 24V, V_{VBA}$ 5W, $Z_L = 8\Omega + 33\mu F$	_T = 5.0V, P _{OUT} = I, f _{IN} = 1kHz		90.5		%
	ηspk	$V_{PVDD} = 24V, V_{VBA}$ 1W, $Z_L = 4\Omega + 33\mu F$			81		

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	COND	ITIONS	MIN	TYP	MAX	UNITS
		$V_{PVDD} = 24V, Z_L = 8$ 1%, $f_{IN} = 1kHz$	3Ω + 33μH, THD+N ≤		33		
		$V_{PVDD} = 24V, Z_L = 8$ 10%, $f_{IN} = 1kHz$	***				
Outset Davis		$V_{PVDD} = 16V, Z_L = 20$ 1%, $f_{IN} = 1kHz$	V_{PVDD} = 16V, Z_L = 4Ω + 33μH, THD+N ≤ 1%, f_{IN} = 1kHz		26		w
Output Power	Роит	$V_{PVDD} = 16V, Z_L = 4$ 10%, $f_{IN} = 1kHz$	IΩ + 33µH, THD+N ≤		32		
		V _{PVDD} = 28V, Z _L = 8 1%, f _{IN} = 1kHz	3Ω + 33μH, THD+N ≤		42		
		$V_{PVDD} = 28V, Z_L = 8$ 10%, $f_{IN} = 1kHz$	3Ω + 33μH, THD+N ≤		51		
Peak Output Power	Роит_ек	$Z_L = 4\Omega + 33\mu H; PV$ period, peak signal)/ low-amplitude signal crest factor = 12dB; with T _J < +100°C an	1kHz (460 periods,) alternating signal; test duration = 1min		100		w
		f _{IN} = 1kHz, P _{OUT} = 3 (<u>Note 3</u>)	, , , , , , , , , , , , , , , , , , , ,		-85		
		f _{IN} = 1kHz, P _{OUT} = 6		-85			
Total Harmonic Distortion + Noise	THD+N	TRI FSW2X MOD	f_{IN} = 6kHz, P_{OUT} = 1W, Z_L = 8 Ω + 33 μ H		-82		dB
		E = 1	f_{IN} = 6kHz, P_{OUT} = 2W, Z_L = 4 Ω + 33 μ H		-80		
Intermodulation Distortion		ITU-R standard, f _{IN} = -3dBFS	= 19kHz/20kHz, V _{IN}		-65		dB
Output Noise	e _N	A-weighted			21.5		μV _{RMS}
Dynamic Range	DR	$Z_L = 8\Omega + 33\mu H$, me method, -60dBFS oureferenced to output A-weighted			117.8		dB
CLASS-DG AMPLIFIER /	POWER-SUPP	LY RIPPLE REJECTION	ON				
VBAT Supply DC Rejection	PSRR	V _{VBAT} = 3.0V to 5.5	V	66	85		dB
VDAT Cumple Data His			f _{RIPPLE} = 217Hz		85		
VBAT Supply Rejection AC	PSRR	V _{RIPPLE} = 100mV _{P-P}	f _{RIPPLE} = 1kHz		85		dB
		· - 1 -r	f _{RIPPLE} = 20kHz		70		
PVDD Supply DC Rejection	PSRR	SPK_MODE = 0x1 (PVDD mode)	V _{PVDD} = 3.0V to 28V	65	85		dB

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	COND	ITIONS	MIN TYP	MAX	UNITS	
PVDD Supply Rejection	PSRR	SPK_MODE = 0x1 (PVDD mode), V _{RIPPLE} = 100mV _{P-P}	f _{RIPPLE} = 217Hz	80		- dB	
AC	PSRR	SPK_MODE =	f _{RIPPLE} = 1kHz	80] ub	
		0x1(PVDD Mode), $V_{RIPPLE} =$ $100mV_{P-P}$	f _{RIPPLE} = 20kHz	70	70		
AVDD Supply DC Rejection	PSRR	V _{AVDD} = 1.71V to 1.	89V	90		dB	
AVDD Cumply Dejection			f _{RIPPLE} = 217Hz	90			
AVDD Supply Rejection AC	PSRR	$V_{RIPPLE} = 100 \text{mV}_{P-P}$	f _{RIPPLE} = 1kHz	90		dB	
		10011117-1	f _{RIPPLE} = 20kHz	60			
DVDD Supply DC Rejection	PSRR	V _{DVDD} = 1.71V to 1.	89V	90	dB		
5) (55 0 1 5 1 1)		.,	f _{RIPPLE} = 217Hz	90			
DVDD Supply Rejection AC	PSRR	$V_{RIPPLE} = 100 \text{mV}_{P-P}$	f _{RIPPLE} = 1khz	90		dB	
7.10		100m1P-P	f _{RIPPLE} = 20kHz	68			
CLASS-DG AMPLIFIER /	POWER-SUPP	LY INTERMODULATION	ON			•	
			V _{VBAT} , f _{RIPPLE} = 217Hz, V _{RIPPLE} = 100mV _{P-P}	-75			
Power-Supply		f _{IN} = 1kHz, P _{OUT} = 400mW	V _{PVDD} , f _{RIPPLE} = 217Hz, V _{RIPPLE} = 100mV _{P-P}	-75		10	
Intermodulation			V _{AVDD} , f _{RIPPLE} = 217Hz, V _{RIPPLE} = 100mV _{P-P}	-67		dB	
			V _{DVDD} , f _{RIPPLE} = 217Hz, V _{RIPPLE} = 100mV _{P-P}	-75			
Output Switching		TRI_FSW2X_MODE all sample rates	= 0, constant across	320		1/11=	
Frequency		TRI_FSW2X_MODE all sample rates	= 1, constant across	620		kHz	
Frequency Response Deviation		Across the bandwidt referenced to f _{IN} = 1		±0.25		dB	
Gain Error	A _{VERROR}			-0.5	+0.5	dB	
Channel-to-Channel Phase Error		Output phase shift be devices from 20Hz to sample rates and DA	20kHz, across all	1		0	
Minimum Load Resistance				3.2		Ω	

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Minimum Load Inductance		In series with a 3.2Ω load		0		μH	
Maximum Load Inductance		In series with a 3.2Ω load		470		μH	
Current Limit	I _{LIM}	PVDD mode	8.0	9.0		Α	
SPEAKER VOLTAGE A	DC		'				
Resolution				16		Bits	
Sample Rate	fs_vsnsadc		8		192	kHz	
Voltage Range	V _{SPK}			±30		V	
Dynamic Range	DNR	f _{IN} = 1kHz, AC measurement bandwidth = 20Hz to 20kHz, unweighted		84		dB	
Total Harmonic Distortion + Noise	THD+N	f _{IN} = 1kHz, V _{SPK} = 8V _{RMS}		-65		dB	
Differential Mode Gain		T _A = +25°C	0.98		1.02		
Differential Mode Gain Variability		Across supplies, T _A = -40°C to +85°C	-1		+1	%	
Common Mode Gain		T _A = +25°C (<i>Note 3</i>)			-45	dB	
		DC blocking filter enabled (Note 3)	-0.3		+0.3		
DC Offset Voltage		DC blocking filter disabled, PVDD = 16V, PVDD Mode, T _A = +25°C	-15		+15	mV	
DC Offset Variability		Across supplies, T _A = -40°C to +85°C		±15		mV	
Highpass Cutoff Frequency		-3dB limit across all sample rates			2	Hz	
SPEAKER VOLTAGE A	DC / DIGITAL FIL	TER CHARACTERISTICS (f_S < 50kHz) (N_C	ote 5)				
Passband Ripple		f _{IN} < f _{PLP} , referenced to signal level at 1kHz	-0.225		+0.225	dB	
Lowpass Filter Cutoff	f _{PLP}		0.445 x f _S			Hz	
Frequency		Droop < -3dB	0.455 x f _S			П	
Lowpass Filter Stopband Frequency	f _{SLP}	-40dB limit			0.58 x f _S	Hz	
Lowpass Filter Stopband Attenuation			40			dB	
Group Delay		f _{IN} = 1kHz		8		Samples	
SPEAKER VOLTAGE A	DC / DIGITAL FIL	TER CHARACTERISTICS (f _S > 50kHz) (<u>No</u>	ote 5)				
Passband Ripple	δρ	IVADC_WBAND_FILT_EN = 0, f _{IN} ≤ f _{PLP} , referenced to signal level at 1kHz	-0.225		+0.225	dB	

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	COND	ITIONS	MIN	TYP	MAX	UNITS
	f _{PLP}		Ripple $< \delta_P$, $88.2kHz \le f_S \le$ 96kHz	0.227 x f _S			
Lowpass Filter Cutoff		IVADC_WBAND_F	Droop < -3dB, $88.2kHz \le f_S \le$ 96kHz	0.31 x f _S			Hz
Frequency	f _{PLP}	ILT_EN = 0	Ripple $< \delta_P$, 176.4kHz \le f _S \le 192kHz	0.136 x f _S			
			Droop < -3dB, 176.4kHz ≤ f _S ≤ 192kHz	0.189 x f _S			
Lowpass Filter Stopband Frequency	f _{SLP}	IVADC_WBAND_F ILT_EN = 0	-40dB limit			0.48 x f _S	Hz
Lowpass Filter Stopband Attenuation		IVADC_WBAND_FIL	_T_EN = 0	40			dB
Group Delay		IVADC_WBAND_F ILT_EN = 0	f _{IN} = 1kHz		10		Samples
SPEAKER VOLTAGE A	DC / DIGITAL FIL	TER CHARACTERIS	TICS (f _S > 50kHz) (<u>N</u>	ote 5)			
Passband Ripple		IVADC_WBAND_FIL f _{PLP} , referenced to s		-0.5		+0.5	dB
	f _{PLP}		Ripple $< \delta_P$, $88.2kHz \le f_S \le$ 96kHz	0.459 x f _S			
Lowpass Filter Cutoff		IVADC_WBAND_F ILT_EN = 1	Droop < -3dB, $88.2kHz \le f_S \le$ 96kHz	0.475 x f _S			Hz
Frequency	f _{PLP}		Ripple $< \delta_P$, 176.4kHz $\le f_S \le$ 192kHz	0.227 x f _S			FIZ
			Droop < -3dB, 176.4kHz ≤ f _S ≤ 192kHz	0.31 x f _S			
Lowpass Filter	f	IVADC_WBAND_F	-40dB limit, 88.2kHz ≤ f _S ≤ 96kHz			0.58 x f _S	Hz
Stopband Frequency	f _{SLP}	ILT_EN = 1	-40dB limit, 176.4kHz ≤ f _S ≤ 192kHz			0.489 x f _S	HZ
Lowpass Filter Stopband Attenuation		IVADC_WBAND_FILT_EN = 1		40			dB
Group Delay		IVADC_WBAND_F ILT_EN = 1	f _{IN} = 1kHz		10		Samples
SPEAKER CURRENT A	DC						
Resolution					16		Bits

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Sample Rate	fs_ISNSADC		8		192	kHz
Current Range	I _{SPK}			±8.3		Α
Dynamic Range	DNR	f _{IN} = 1kHz, AC measurement bandwidth = 20Hz to 20kHz, unweighted		82		dB
Total Harmonic Distortion + Noise	THD+N	f _{IN} = 1kHz, I _{SPK} = 1A _{RMS}		-64		dB
Differential Mode Gain		T _A = +25°C	0.97		1.03	
Differential Mode Gain Variability		Across supplies, T _A = -40°C to +85°C (<u>Note 3</u>)	-2.5		+2.5	%
Common Mode Gain		T _A = +25°C			-46	dB
Highpass Cutoff Frequency		-3dB limit, across all sample rates			2	Hz
		DC blocking filter enabled, T _A = +25°C	-0.16		0.16	
DC Offset Current		DC blocking filter disabled, PVDD = 16V, PVDD mode, T _A = +25°C	-4.5		+4.5	mA
DC Offset Variability		Across supplies, T _A = -40°C to +85°C, DC blocking filter disabled		±12		mA
Voltage and Current Accuracy Drift Tracking		T _A = 0°C to +85°C, relative to +25°C		0.4		%
SPEAKER CURRENT A	DC / DIGITAL FIL	TER CHARACTERISTICS (f _S < 50kHz) (<u>No</u>	ote 5)			
Passband Ripple		f _{IN} ≤ f _{PLP}	-0.225		+0.225	dB
Lowpass Filter Cutoff	f _{PLP}		0.445 x f _S			Hz
Frequency		-3dB limit	0.455 x f _S			П
Lowpass Filter Stopband Frequency	f _{SLP}	-40dB limit			0.58 x f _S	Hz
Lowpass Filter Stopband Attenuation			40			dB
Max Group Delay		f _{IN} = 1kHz		8		Samples
SPEAKER CURRENT A	DC / DIGITAL FIL	TER CHARACTERISTICS (f _S > 50kHz) (<u>No</u>	ote 5)			
Passband Ripple	δ _P	IVADC_WBAND_FILT_EN = 0, f _{IN} ≤ f _{PLP}	-0.225		+0.225	dB

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	COND	ITIONS	MIN	TYP	MAX	UNITS
			Ripple $< \delta_P$, $88.2 \text{kHz} \le f_S \le$ 96 kHz	0.227 x f _S			
Lowpass Filter Cutoff	f=: -	IVADC_WBAND_F	Droop < -3dB, 88.2kHz ≤ f _S ≤ 96kHz	0.31 x f _S			Hz
Frequency	f _{PLP}	ILT_EN = 0	Ripple $< \delta_P$, 176.4kHz $\le f_S \le$ 192kHz	0.136 x f _S			П
			Droop < -3dB, 176.4kHz ≤ f _S ≤ 192kHz	0.189 x f _S			
Lowpass Filter Stopband Frequency	f _{SLP}	IVADC_WBAND_F ILT_EN = 0	-40dB limit, 88.2kHz ≤ f _S ≤ 96kHz			0.48 x f _S	Hz
Lowpass Filter Stopband Attenuation		IVADC_WBAND_FIL	40			dB	
Max Group Delay		IVADC_WBAND_FIL 1kHz	_T_EN = 0, f _{IN} =		10		Samples
SPEAKER CURRENT A	DC / DIGITAL FIL	TER CHARACTERIS	TICS (f _S > 50kHz) (<u>N</u> c	<u>ote 5</u>)			
Passband Ripple		IVADC_WBAND_FIL	T_EN = 1, f _{IN} ≤ f _{PLP}	-0.5		+0.5	dB
		f _{PLP} IVADC_WBAND_F - ILT_EN = 1	Ripple $< \delta_P$, $88.2kHz \le f_S \le$ 96kHz	0.459 x f _S			
Lowpass Filter Cutoff			-3dB limit, 88.2kHz ≤ f _S ≤ 96kHz	0.475 x f _S			
Frequency	f _{PLP}		Ripple $< \delta_P$, 176.4kHz $\le f_S \le$ 192kHz	0.227 x f _S			Hz
			-3dB limit, 176.4kHz ≤ f _S ≤ 192kHz	0.31 x f _S			
Lowpass Filter		IVADC_WBAND_F	-40dB limit, 88.2kHz ≤ f _S ≤ 96kHz			0.58 x f _S	11-
Stopband Frequency	f _{SLP}	ILT_EN = 1	-40dB limit, 176.4kHz ≤ f _S ≤ 192kHz			0.489 x f _S	Hz
Lowpass Filter Stopband Attenuation		IVADC_WBAND_FILT_EN = 1		40			dB
Max Group Delay		IVADC_WBAND_FIL 1kHz	_T_EN = 1, f _{IN} =		10		Samples
MEASUREMENT ADC	•	•		1			
Resolution					9		Bits

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
PVDD Channel Input Voltage Range			2.7		28	V
PVDD Channel Voltage Resolution				54.7		mV
PVDD Channel Measurement Accuracy		T _A = +25°C (<u>Note 3</u>)	-400		+400	mV
VBAT Channel Input Voltage Range			2.5		5.5	٧
VBAT Channel Voltage Resolution				11.4		mV
VBAT Channel Measurement Accuracy		T _A = +25°C (<u>Note 3</u>)	-83		+83	mV
VDDH_SNS Channel Input Voltage Range			2.5		28	V
VDDH_SNS Channel Voltage Resolution				54.7		mV
VDDH_SNS Channel Measurement Accuracy		T _A = +25°C (<u>Note 3</u>)	-400		+400	mV
Thermal Channel Resolution				1		°C
BROWNOUT-PROTECTION	ON ENGINE (BP	PE)				
BPE Attack Delay Time to Gain Change		MEAS_ADC_OPT_MODE = 0x2, MEAS_ADC_OPT_AVG = 0x0		12		μs
BPE Attack Delay Time to Interrupt				3		μs
THERMAL PROTECTION	l		·			
Thermal Shutdown Trigger Point		THERMSHDN_THRESH = 0x64	140	150	160	°C
DIGITAL I/O / INPUT — D	IN, BCLK, LRCI	LK, RESET, ICC, DOUT	·			
Input Voltage High	V_{IH}		0.7 x V _{DVDD}			V
Input Voltage Low	V_{IL}				0.3 x V _{DVDD}	V
Input Leakage Current			-1		+1	μA
Input Hysteresis	V _{HYS}		75			mV
Maximum Input Capacitance	C _{IN}			10		pF
Internal Pulldown Resistance	R _{PD}	BCLK, LRCLK, DIN, and ICC		3		ΜΩ
DIGITAL I/O / INPUT — S	DA, SCL, ADDR	R				
Input Voltage High	V _{IH}		0.7 x V _{DVDD}			V

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input Voltage Low	V _{IL}				$0.3 x$ V_{DVDD}	V
Input Leakage Current		T _A = +25°C, input high	-1		+1	μA
Input Hysteresis	V _{HYS}		75			mV
Maximum Input Capacitance	C _{IN}			10		pF
DIGITAL I/O / OPEN-DRA	AIN OUTPUT —	SDA, IRQ, LV_EN				
Output Voltage Low	V _{OL}	I _{SINK} = 3mA			0.4	V
Output High Leakage Current	Іон	T _A = +25°C	-1		+1	μA
DIGITAL I/O / PUSH-PUL	L OUTPUT — D	OUT, ICC, IRQ				
Output Voltage High	V _{OH}	I _{OH} = 3mA	V _{DVDD} - 0.3			٧
Output Voltage Low	V _{OL}	I _{OL} = 3mA			0.3	V
	urrent I _{OH}	Maximum-drive mode		8		
Output Current		High-drive mode		6		mA
Output Current	OH	Normal-drive mode		4		IIIA
		Reduced-drive mode		2		
PCM AUDIO INTERFACE	TIMING					
LRCLK Frequency Range	fLRCLK	All DAI operating modes	16		192	kHz
BCLK Frequency Range	fnour	I ² S/left-justified modes	1.024		12.288	MHz
BOLK Frequency Nange	fBCLK	TDM mode	1.024		24.576	IVII IZ
BCLK Duty Cycle	DC		45		55	%
BCLK Period	tnouv	I ² S/left-justified only	80			ns
BOLK Fellou	^t BCLK	TDM mode	40			115
Maximum BCLK Input Low Frequency Jitter		Maximum allowable jitter before a -20dBFS, 20kHz input has a 1dB reduction in THD+N, RMS jitter ≤ 40kHz		0.2		ns
Maximum BCLK Input High Frequency Jitter		Maximum allowable jitter before a -60dBFS, 20kHz input has a 1dB reduction in THD+N, RMS jitter > 40kHz		1		ns
PCM AUDIO INTERFACE	TIMING / INTE	RFACE TIMING				
LRCLK to BCLK Active Edge Setup Time	^t SYNCSET		4			ns
LRCLK to BCLK Active Edge Hold Time	tsynchold		4			ns
DIN to BCLK Active Edge Setup Time	^t SETUP		4			ns
DIN to BCLK Active Edge Hold Time	tHOLD		4			ns

Electrical Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DIN Frame Delay after LRCLK Edge		Measured in number of BCLK cycles, set by selected TDM mode	0		2	cycles
PCM AUDIO INTERFACE	TIMING / INTE	RFACE TIMING / PCM DATA OUTPUT (DO	UT)			
BCLK Inactive Edge to DOUT Delay	t _{CLKTX}				14	ns
BCLK Active Edge to DOUT Hi-Z Delay	t _{HIZ}		4		18	ns
BCLK Inactive Edge to DOUT Active Delay	t _{ACTV}		0		14	ns
PCM AUDIO INTERFACE	TIMING / INTE	RFACE TIMING / INTERCHIP COMMUNICA	TION (ICC)			
ICC/DOUT to BCLK Active Edge Setup Time	^t SETUP		4			ns
ICC/DOUT to BCLK Active Edge Hold Time	tHOLD		4			ns
BCLK Inactive Edge to ICC Delay	t _{CLKTX}				14	ns
BCLK Active Edge to ICC Hi-Z Delay	t _{HIZ}		4		18	ns
BCLK Inactive Edge to ICC Active Delay	^t ACTV		0		14	ns
I ² C INTERFACE TIMING						
Serial Clock Frequency	f _{SCL}				1000	kHz
Bus Free Time Between STOP and START Conditions	t _{BUF}		0.5			μs
Hold Time (Repeated) START Condition	t _{HD,STA}		0.26			μs
SCL Pulse Width Low	t_{LOW}		0.5			μs
SCL Pulse Width High	^t HIGH		0.26			μs
Setup Time for a Repeated START Condition	t _{SU,STA}		0.26			μs
Data Hold Time	t _{HD,DAT}		0		450	ns
Data Setup Time	t _{SU,DAT}		50			ns
SDA and SCL Receiving Rise Time	t _R		20		120	ns
SDA and SCL Receiving Fall Time	t _F		20 x V _{DVDD} /5 .5V		120	ns
SDA Transmitting Fall Time	t _F		20 x V _{DVDD} /5 .5V		120	ns

Electrical Characteristics (continued)

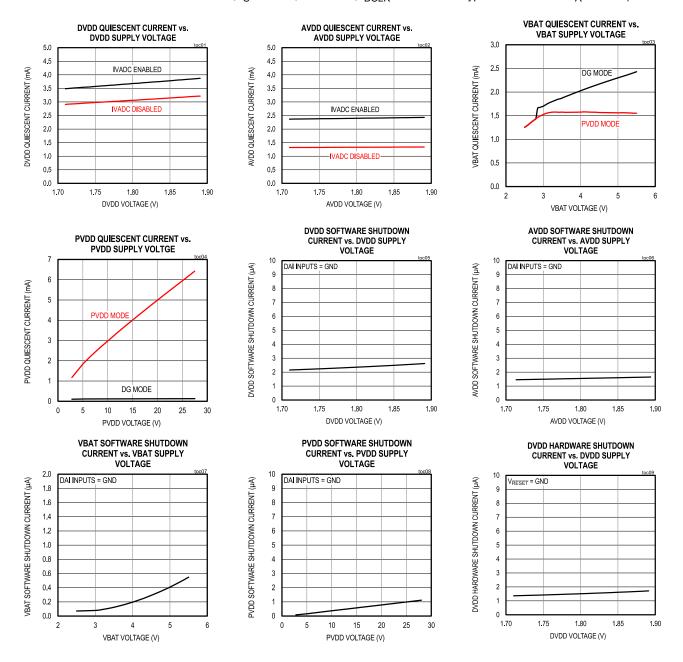
 $(V_{VBAT} = 5.0V, V_{PVDD} = 24V, V_{AVDD} = 1.8V, V_{DVDD} = 1.8V, C_{VBAT} = 1x10μF, 1x0.1μF, C_{PVDD} = 1x220μF, 2x10μF, 2x0.1μF, C_{AVDD} = 1μF, C_{DVDD} = 1μF, C_{VBOOTP} = 0.1μF, C_{VBOOTN} = 0.1μF, Z_{SPK} = Open, f_S = 48kHz, AC Measurement Bandwidth = 20Hz to 20kHz, SPK_GAIN_MAX = 0x12 (24dB), Data Width = 24-bit, SPK_MODE = 0x0 (DG), <math>T_A = T_{MIN}$ to T_{MAX} unless otherwise noted. Typical values are at $T_A = +25$ °C (Note 2))

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Setup Time for STOP Condition	tsu,sto		0.26			μs
Bus Capacitance	C _B				550	pF
Pulse Width of Suppressed Spike	t _{SP}		0		50	ns
RESET TIMING						
RESET Low	treset_low	Minimum low time for RESET to ensure device enters hardware shutdown		0.4		μs
Release from RESET	t _I ² C_READY	Time from RESET = 1 to I ² C-communication available (software shutdown)			1.5	ms

- Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.analog.com/en/technical-articles/thermal-characterization-of-ic-packages.
- Note 2: 100% production tested at T_A = +25°C. Specifications over temperature limits are guaranteed by design. Typical values are based on 1 sigma characterization data unless otherwise noted.
- **Note 3:** Minimum and/or maximum limit is guaranteed by design and by statistical analysis of device characterization data. The specification is not guaranteed by production testing.
- Note 4: Assumes device is fully programmed (SPK_EN = 1) and EN = 1 is the last I²C write in the sequence.
- Note 5: Digital filter performance is invariant over temperature and is production tested at T_A = +25°C.
- Note 6: Applies to all transitions in/out of full operation with noise gate enabled/disabled. Does not include state transitions due to fault conditions.

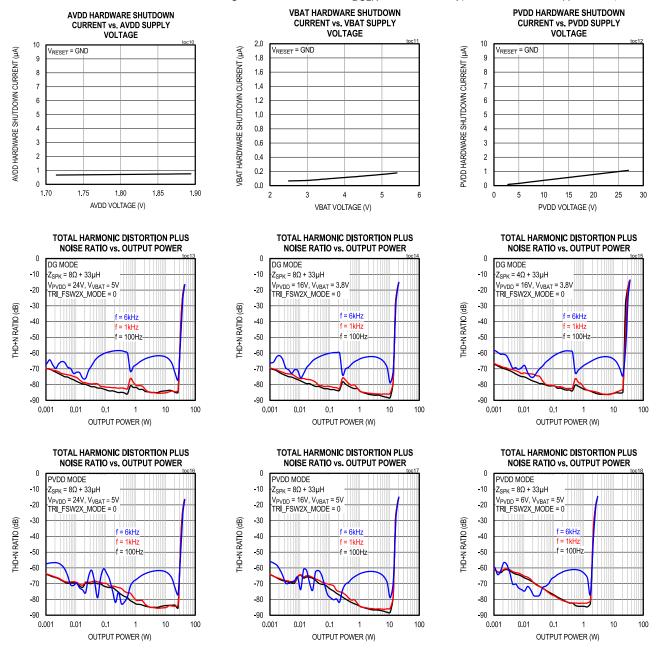
Typical Operating Characteristics

 $(V_{VBAT}=5.0V,V_{DVDD}=1.8V,V_{AVDD}=1.8V,V_{GND}=0V,V_{PGND}=0V,V_{PVDD}=24V,C_{VBAT}=10\mu\text{F}+0.1\mu\text{F},C_{PVDD}=0.1\mu\text{F}+10\mu\text{F}+220\mu\text{F},C_{DVDD}=1\mu\text{F},C_{AVDD}=1\mu\text{F},C_{VBOOT}$ P= 0.1 μ F, C_{VBOOT} N= 0.1 μ F, A_V = 24dB, Z_{SPK} = ∞ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, f_S = 48kHz, 24-bit data, f_{BCLK} = 3.072MHz. Typical values are at T_A = +25°C)



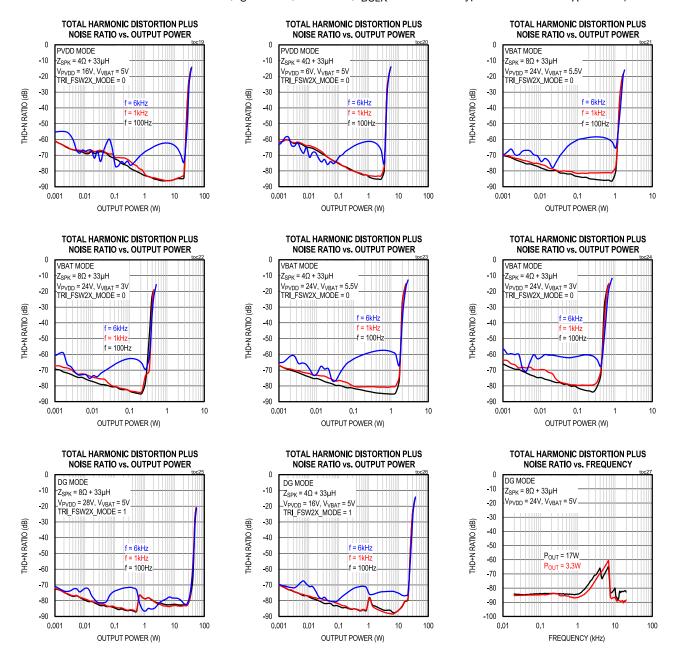
Typical Operating Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{DVDD} = 1.8V, V_{AVDD} = 1.8V, V_{GND} = 0V, V_{PGND} = 0V, V_{PVDD} = 24V, C_{VBAT} = 10μF + 0.1μF, C_{PVDD} = 0.1μF + 10μF + 220μF, C_{DVDD} = 1μF, C_{AVDD} = 1μF, C_{VBOOT} _P = 0.1μF, C_{VBOOT} _N = 0.1μF, A_V = 24dB, Z_{SPK} = ∞ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, <math>f_S = 48kHz$, 24-bit data, $f_{BCLK} = 3.072MHz$. Typical values are at $T_A = +25$ °C)



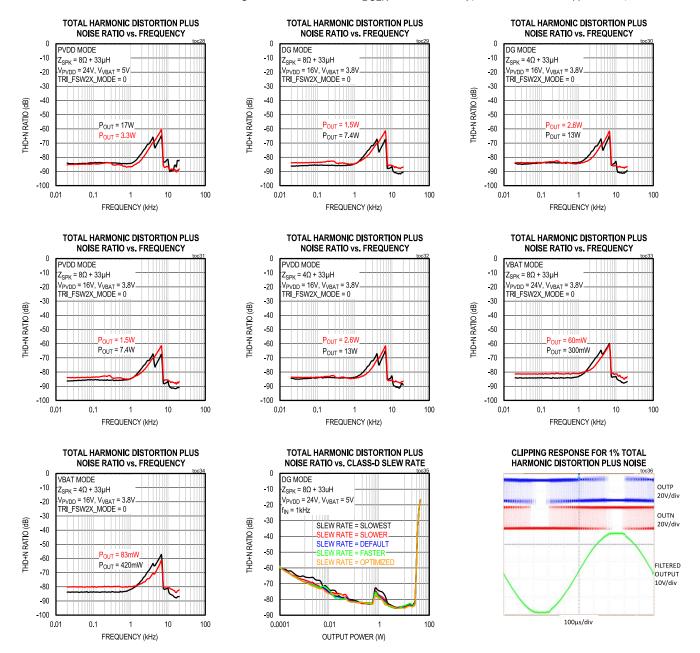
Typical Operating Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{DVDD} = 1.8V, V_{AVDD} = 1.8V, V_{GND} = 0V, V_{PGND} = 0V, V_{PVDD} = 24V, C_{VBAT} = 10μF + 0.1μF, C_{PVDD} = 0.1μF + 10μF + 220μF, C_{DVDD} = 1μF, C_{AVDD} = 1μF, C_{VBOOT} _P = 0.1μF, C_{VBOOT} _N = 0.1μF, A_V = 24dB, Z_{SPK} = ∞ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, <math>f_S = 48kHz$, 24-bit data, $f_{BCLK} = 3.072MHz$. Typical values are at $T_A = +25$ °C)



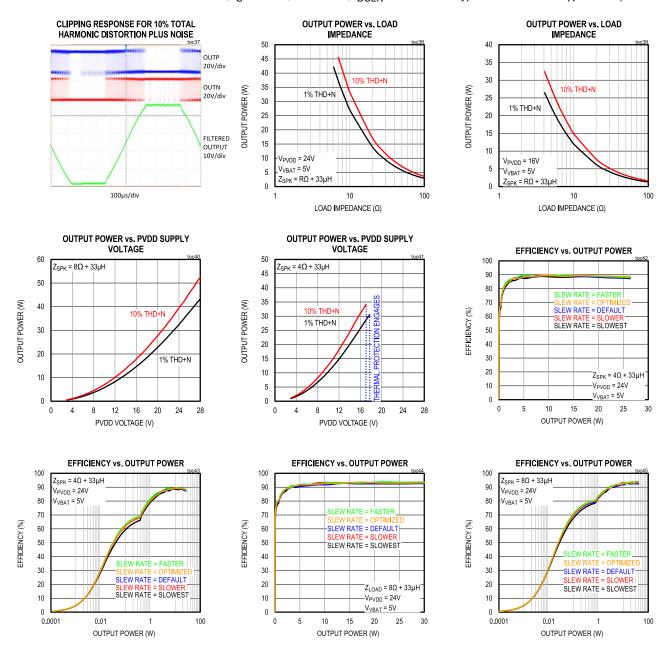
Typical Operating Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{DVDD} = 1.8V, V_{AVDD} = 1.8V, V_{GND} = 0V, V_{PGND} = 0V, V_{PVDD} = 24V, C_{VBAT} = 10μF + 0.1μF, C_{PVDD} = 0.1μF + 10μF + 220μF, C_{DVDD} = 1μF, C_{AVDD} = 1μF, C_{VBOOT} _P = 0.1μF, C_{VBOOT} _N = 0.1μF, A_V = 24dB, Z_{SPK} = ∞ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, <math>f_S = 48kHz$, 24-bit data, $f_{BCLK} = 3.072MHz$. Typical values are at $T_A = +25$ °C)



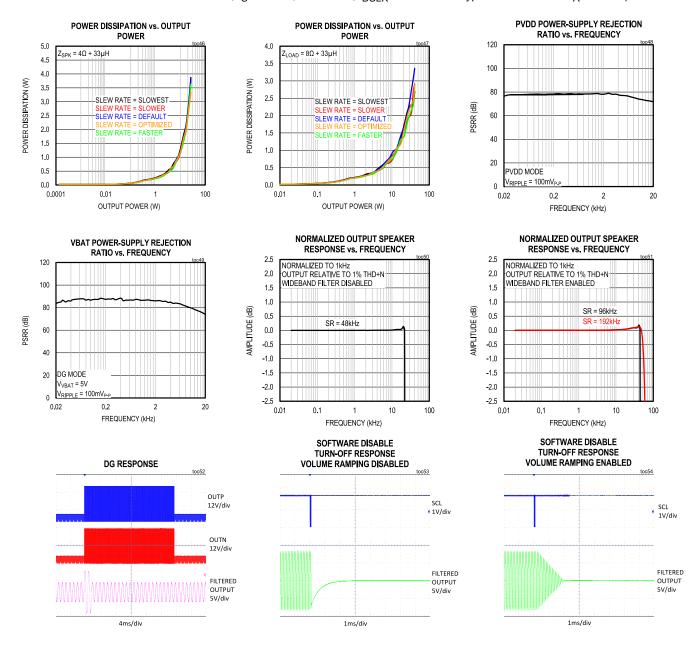
Typical Operating Characteristics (continued)

 $(V_{VBAT}=5.0V,V_{DVDD}=1.8V,V_{AVDD}=1.8V,V_{GND}=0V,V_{PGND}=0V,V_{PVDD}=24V,C_{VBAT}=10\mu\text{F}+0.1\mu\text{F},C_{PVDD}=0.1\mu\text{F}+10\mu\text{F}+220\mu\text{F},C_{DVDD}=1\mu\text{F},C_{AVDD}=1\mu\text{F},C_{VBOOT}_{P}=0.1\mu\text{F},C_{VBOOT}_{N}=0.1\mu\text{F},A_{V}=24d\text{B},Z_{SPK}=\infty$ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, $f_{S}=48\text{kHz}$, 24-bit data, $f_{BCLK}=3.072\text{MHz}$. Typical values are at $T_{A}=+25^{\circ}\text{C}$)



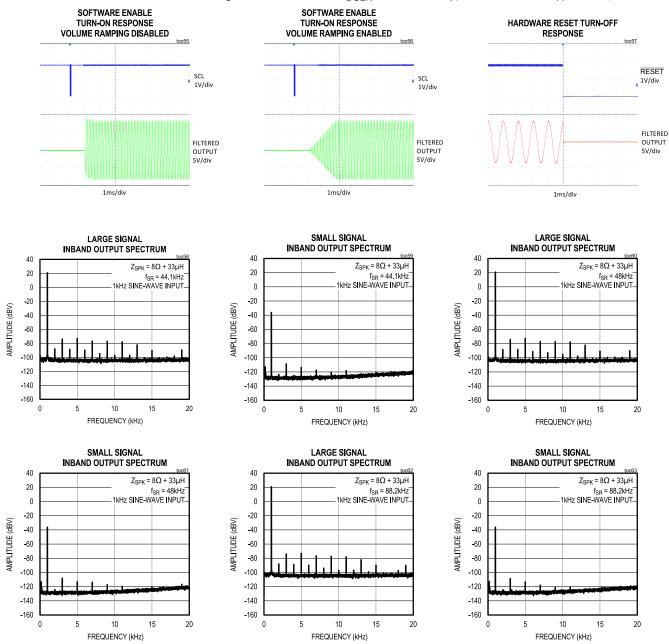
Typical Operating Characteristics (continued)

 $(V_{VBAT}=5.0V,V_{DVDD}=1.8V,V_{AVDD}=1.8V,V_{GND}=0V,V_{PGND}=0V,V_{PVDD}=24V,C_{VBAT}=10\mu\text{F}+0.1\mu\text{F},C_{PVDD}=0.1\mu\text{F}+10\mu\text{F}+220\mu\text{F},C_{DVDD}=1\mu\text{F},C_{AVDD}=1\mu\text{F},C_{VBOOT}_{P}=0.1\mu\text{F},C_{VBOOT}_{N}=0.1\mu\text{F},A_{V}=24d\text{B},Z_{SPK}=\infty$ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, $f_{S}=48\text{kHz}$, 24-bit data, $f_{BCLK}=3.072\text{MHz}$. Typical values are at $T_{A}=+25^{\circ}\text{C}$)



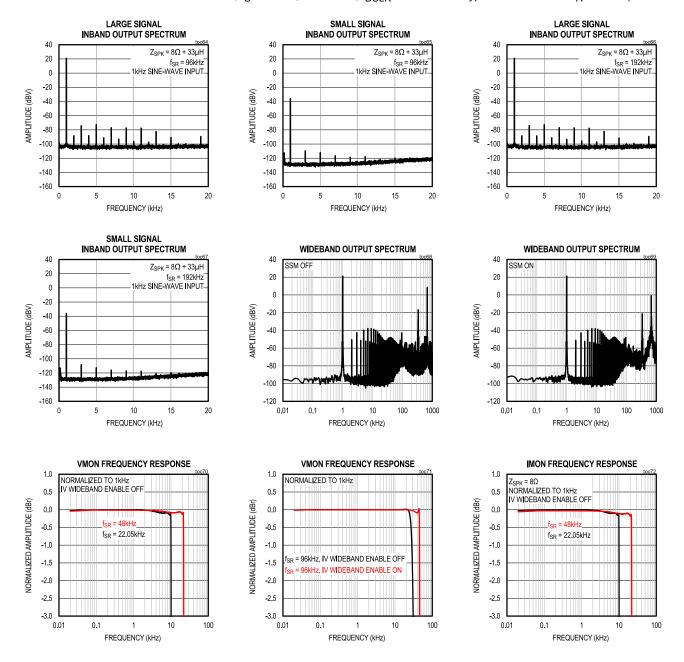
Typical Operating Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{DVDD} = 1.8V, V_{AVDD} = 1.8V, V_{GND} = 0V, V_{PGND} = 0V, V_{PVDD} = 24V, C_{VBAT} = 10μF + 0.1μF, C_{PVDD} = 0.1μF + 10μF + 220μF, C_{DVDD} = 1μF, C_{AVDD} = 1μF, C_{VBOOT} _P = 0.1μF, C_{VBOOT} _N = 0.1μF, A_V = 24dB, Z_{SPK} = ∞ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, f_S = 48kHz, 24-bit data, f_{BCLK} = 3.072MHz. Typical values are at T_A = +25°C)$



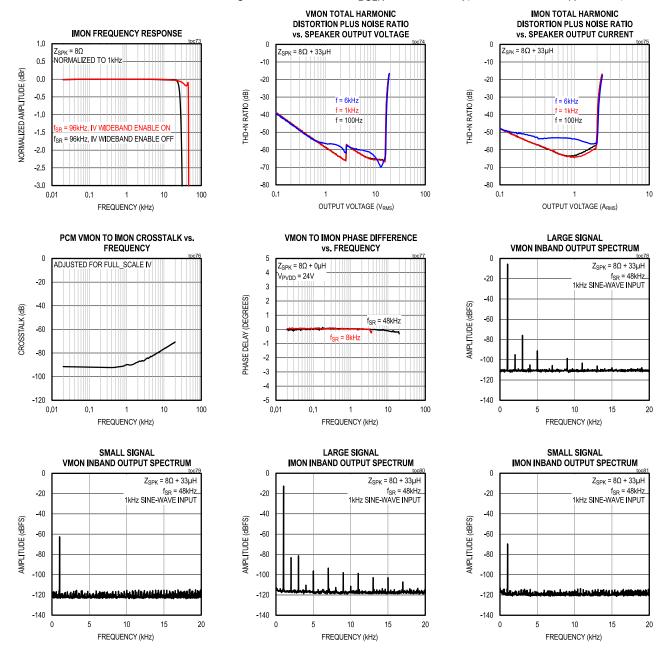
Typical Operating Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{DVDD} = 1.8V, V_{AVDD} = 1.8V, V_{GND} = 0V, V_{PGND} = 0V, V_{PVDD} = 24V, C_{VBAT} = 10μF + 0.1μF, C_{PVDD} = 0.1μF + 10μF + 220μF, C_{DVDD} = 1μF, C_{AVDD} = 1μF, C_{VBOOT} _P = 0.1μF, C_{VBOOT} _N = 0.1μF, A_V = 24dB, Z_{SPK} = ∞ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, <math>f_S = 48kHz$, 24-bit data, $f_{BCLK} = 3.072MHz$. Typical values are at $T_A = +25$ °C)



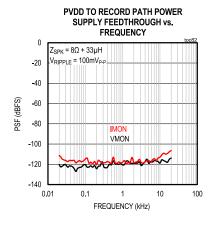
Typical Operating Characteristics (continued)

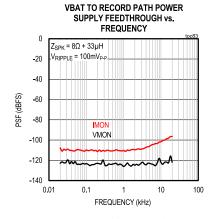
 $(V_{VBAT} = 5.0V, V_{DVDD} = 1.8V, V_{AVDD} = 1.8V, V_{GND} = 0V, V_{PGND} = 0V, V_{PVDD} = 24V, C_{VBAT} = 10μF + 0.1μF, C_{PVDD} = 0.1μF + 10μF + 220μF, C_{DVDD} = 1μF, C_{AVDD} = 1μF, C_{VBOOT} _P = 0.1μF, C_{VBOOT} _N = 0.1μF, A_V = 24dB, Z_{SPK} = ∞ between OUTP and OUTN, AC Measurement Bandwidth = 20Hz to 20kHz, <math>f_S = 48kHz$, 24-bit data, $f_{BCLK} = 3.072MHz$. Typical values are at $T_A = +25$ °C)

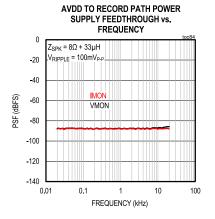


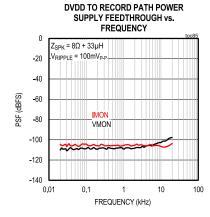
Typical Operating Characteristics (continued)

 $(V_{VBAT} = 5.0V, V_{DVDD} = 1.8V, V_{AVDD} = 1.8V, V_{GND} = 0V, V_{PGND} = 0V, V_{PVDD} = 24V, C_{VBAT} = 10\mu\text{F} + 0.1\mu\text{F}, C_{PVDD} = 0.1\mu\text{F} + 10\mu\text{F} + 220\mu\text{F}, C_{DVDD} = 1\mu\text{F}, C_{VBOOT} P = 0.1\mu\text{F}, C_{VBOOT} N = 0.1\mu\text{F}, A_{V} = 24d\text{B}, Z_{SPK} = \infty \text{ between OUTP and OUTN, AC Measurement Bandwidth} = 20Hz \text{ to } 20\text{kHz}, f_{S} = 48\text{kHz}, 24\text{-bit data, } f_{BCLK} = 3.072\text{MHz}. \text{ Typical values are at } T_{A} = +25^{\circ}\text{C})$



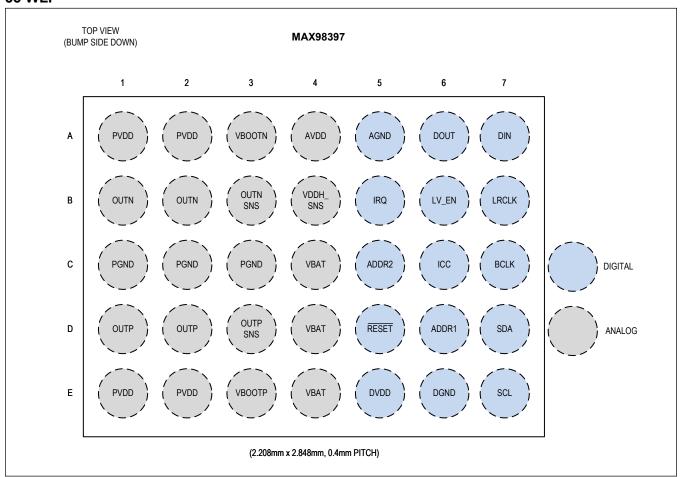






Pin Configuration

35 WLP



Pin Description

PIN	NAME	FUNCTION	REF SUPPLY	TYPE
E5	DVDD	Digital Core and Digital I/O Power Supply. Bypass to DGND with a 1µF capacitor.		Supply
E6	DGND	Digital Ground		Supply
A1, A2, E1, E2	PVDD	Speaker Amplifier Power Supply. Bypass each bump to PGND with a 0.1µF and 10µF capacitor placed as close as possible. Bypass the supply bus to PGND with a single 220µF bulk capacitor per device.	1	Supply
C1, C2, C3	PGND	Speaker Amplifier Ground	_	Supply
C4, D4, E4	VBAT	Battery Power Supply. Bypass to PGND with a 0.1μF and 10μF capacitor placed as close as possible.	_	Supply
A4	AVDD	Analog Power Supply. Bypass to AGND with a 1µF capacitor placed as close as possible.		Supply

28V Digital Input, Class-DG Amplifier with IV_{SENSE} , Ultra-Low I_Q , and Brownout Prevention

Pin Description (continued)

PIN	NAME	FUNCTION	REF SUPPLY	TYPE
A5	AGND	Analog Ground. Connect to the common ground plane of the application.	_	Supply
D5	RESET	Hardware Enable (Active-Low). Resets all digital portions of the device and all registers to default power-on reset (POR) settings.	DVDD	Digital Input
E3	VBOOTP	Bootstrap for High-Side Gate Drive. Connect 0.1µF capacitor between BOOTP and OUTP.	PVDD	_
A3	VBOOTN	Bootstrap for High-Side Gate Drive. Connect 0.1µF capacitor between BOOTN and OUTN.	PVDD	_
D1, D2	OUTP	Positive Speaker Amplifier Output	PVDD	Analog Output
D3	OUTPSNS	Speaker Amplifier Feedback Positive Input. Connect as close as possible to the positive terminal of the loudspeaker. This pin must form a complete loop with OUTP.	PVDD	Analog Output
B1, B2	OUTN	Negative Speaker Amplifier Output	PVDD	Analog Output
В3	OUTNSNS	Speaker Amplifier Feedback Negative Input. Connect as close as possible to the negative terminal of the loudspeaker. This pin must form a complete loop with OUTN.	PVDD	Analog Output
E7	SCL	I ² C-Compatible Serial-Clock. Connect a 1.5k Ω pullup resistor to DVDD for full logic-level swing.	DVDD	Digital I/O (Open-Drain
D7	SDA	I ² C-Compatible Serial Data. Connect a 1.5k Ω pullup resistor to DVDD for full logic-level swing.	DVDD	Digital I/O (Open-Drain
D6	ADDR1	I ² C Address Select Input 1. See the I ² C Serial Interface section for additional information.	DVDD	Digital Input
C5	ADDR2	I ² C Address Select Input 2. See the I ² C Serial Interface section for additional information.	DVDD	Digital Input
B5	IRQ	Hardware Interrupt Output. Interrupt polarity and pin-drive mode are configurable. Connect a $10k\Omega$ pullup resistor to DVDD for full logic-level swing in open-drain mode.	DVDD	Digital Outpu
C7	BCLK	PCM Interface BCLK Input. Internally pulled down to DGND through R _{PD} .	DVDD	Digital Input
В7	LRCLK	PCM Interface Frame Clock Input/Output. LRCLK frequency matches the PCM interface sample rate. Internally pulled down to DGND through R _{PD} .	DVDD	Digital Input
A7	DIN	PCM Interface Data Input. Internally pulled down to DGND through RPD.	DVDD	Digital Input
A6	DOUT	PCM Interface Data Output	DVDD	Digital Outpu
В6	LV_EN	Low Voltage Enable Output pin signals an external boost the active power supply used by the amplifier output stage. The pin is asserted when the amplifier uses VBAT as the supply for the output stage.	DVDD	Digital Oupu (Open-Drain
C6	ICC	Interchip Communication Data Bus. Optionally allows multiple devices to be grouped up to communicate with each other. Internally pulled down to DGND through R _{PD} .	DVDD	Digital I/O
B4	VDDH_SNS	External Supply Remote Sense Input Pin	_	Analog Input

Detailed Description

Device State Control

The device has three distinct power states: the hardware-shutdown state, the software-shutdown state, and the active state. When transitioning between states, the device always moves from the hardware-shutdown state to the software-shutdown state to the active state (or the reverse) based on the state transition requirements. Normal transitions between the software-shutdown state and active state are reversible without waiting for an in-progress transition to be completed. State transitions due to fault conditions, supply removal, and reset conditions are not reversible and are always completed (once initiated) to protect the device.

Hardware-Shutdown State

When the device is first powered up or after a hardware reset event, the device always initializes into the hardware shutdown state. In hardware shutdown, the device is configured to its lowest power state. Upon entering hardware shutdown, the device is globally placed into a reset condition. As a result, the I²C control interface is disabled, and all device registers are returned to their PoR states. When exiting the hardware shutdown, the device initializes and then transitions into the software-shutdown state. During this transition (as part of initialization), the OTP register trim settings are loaded. If the OTP load routine fails to complete successfully, an OTP_FAIL_* interrupt is generated once the device reaches the software-shutdown state.

When the hardware reset input (RESET) is asserted low, the device enters (or remains in) hardware shutdown. The device is also placed into hardware shutdown anytime the DVDD supply drops below its POK threshold. The device only exits hardware shutdown when the PVDD supply and DVDD supply are above their UVLO thresholds, and the hardware reset input (RESET) is asserted high. Once all of these conditions are met, the device automatically exits hardware shutdown and transitions into software shutdown.

Software-Shutdown State

The device enters the software-shutdown state after it transitions out of the hardware-shutdown state and when exiting the active state. In the software-shutdown state, all blocks are automatically disabled except for the I²C control interface. In the software-shutdown state, all device registers can be programmed without restriction, and all programmed register states are retained.

The global enable bit (EN) is used to transition the device into and out of software shutdown. When global enable (EN) is set high, the device transitions to the active state and a power-up done ($PWRUP_DONE_*$) interrupt is generated. When the device is in the active state and global enable (EN) is set low, the device transitions to the software-shutdown state and a power-down done ($PWRDN_DONE_*$) interrupt is generated. Additionally, the device is reset and enters software shutdown anytime the global reset bit (EN) is written with a 1.

By default, the device supply configuration is AVDD, PVDD, and VBAT pins being supplied with voltages, and in this scenario, regardless of the state of the global enable bit, the device cannot transition from the software-shutdown state to the active state until AVDD, PVDD, and VBAT are all above their UVLO thresholds. If DVDD, PVDD, or VBAT supplies drop below their UVLO levels, or if AVDD supply drops below its POK threshold while the device is in the active state, the device is forced back into the software-shutdown state. The AVDD and DVDD supplies drop below their UVLO thresholds while the device is in the active state, and an appropriate UVLO fault interrupt (AVDD_UVLO_* or DVDD_UVLO_* respectively) is generated.

While in the software-shutdown state, the AVDD, PVDD, and VBAT supplies can be powered down safely.

Recovery from Software Shutdown due to Supply Faults

The device provides two forms of fault recovery if either VBAT or PVDD drop below their UVLO thresholds while the device is in its active state. Based on the setting of the <u>VBAT_AUTORESTART_EN</u> and <u>PVDD_AUTORESTART_EN</u> bits, the individual supply fault recovery is either in manual mode or auto-restart mode.

If the bit is set low, then the supply UVLO fault recovery is in manual mode. In manual mode, when the supply drops below its UVLO threshold the device transitions into the software shutdown state (sets EN = 0) and generates the appropriate UVLO fault shutdown interrupt (VBAT UVLO SHDN * or PVDD UVLO SHDN * respectively). Even once the supply recovers (voltage levels exceed the UVLO thresholds), the device remains in the software shutdown state until

the global enable bit (EN) is set high by the host software and the AVDD supply is above its UVLO threshold.

If the bit is instead set high, then the supply UVLO fault recovery is in auto-restart mode. In auto-restart mode, when the supply drops below its UVLO threshold, the device is internally forced into software shutdown (<u>EN</u> state is preserved and remains high) and generates the appropriate UVLO fault shutdown interrupt (<u>VBAT_UVLO_SHDN_*</u> or <u>PVDD_UVLO_SHDN_*</u> respectively). Once the supply recovers (voltage levels exceed the UVLO thresholds), the device is no longer held in software shutdown and (if all other conditions are met) automatically restarts back into the active state. These recovery modes do not apply when the AVDD or DVDD supplies cause a UVLO fault while the device is in the active state. If DVDD drops below its POK thresholds, the device is reset and placed into hardware shutdown.

Active State

The device always enters the active state through a transition from the software-shutdown state. In the active state, all enabled device blocks are active and speaker amplifier playback is possible. In the active state, only dynamic register settings (or those restricted to disabled blocks) can be programmed safely.

The only non-fault state transitions to or from the active state are those initiated through the global enable bit (EN). All other transitions to or from the active state are the result of fault events and may result in audible glitches if they occur during active playback.

Device Sequencing

Table 1 and Table 2 show the recommended typical device power-up and power-down sequences.

Table 1. Typical Power-Up Sequence

STEP	ACTION	DETAILED DESCRIPTION		
1	Power-Up Core Supplies	Power the PVDD, VBAT, AVDD, and DVDD supplies above their UVLO thresholds.		
		For proper operation, V _{PVDD} > V _{VBAT} - 0.3V.		
2	Exit Hardware-Shutdown State	Assert the hardware reset input (RESET) to a logic high level. If RESET is tied to the DVDD supply, this step is combined with step 1.		
3	Enter Software-Shutdown State	The device finishes the transition and enters the software-shutdown state after the release from reset time (t ₁ 2 _{C_READY}) elapses.		
4	Program the Device Registers/Enable the External Clocks	The I ² C interface is active, and all registers can be freely configured. Start both external clocks before exiting the software shutdown state.		
5	Exit Software-Shutdown State	If volume ramping is disabled, the input audio data should be silent. Set the global enable to a logic high (EN = 1).		
6	Enter the Active State	The device enters the active state after the turn-on time (t _{ON}) elapses.		
7	Active State/Audio Playback	Dynamic bits (and those restricted to disabled blocks) can be programmed. The device is capable of audio playback in the active state.		

Table 2. Typical Power-Down Sequence

STEP	ACTION	DETAILED DESCRIPTION
1	Exit the Active State	If volume ramping is disabled, the input audio data should be silent. Set the global enable bit to a logic low (EN = 0)
2	Enter Software- Shutdown State	The device enters a software-shutdown state after the turn-off time (t _{OFF}) elapses.
3	Reprogram Device Registers/Disable the External Clocks	The device is fully programmable and can idle in the software shutdown state. The external clocks and the AVDD, PVDD, VBAT supplies can be disabled. To return to the active state, resume the power-up sequence from step 4.
4	Enter Hardware- Shutdown State	For full-hardware shutdown, disable the external clocks first. Assert the reset input (RESET) to ground or power-down DVDD.

28V Digital Input, Class-DG Amplifier with IV_{SENSE} , Ultra-Low I_Q , and Brownout Prevention

Power-Supply Sequencing

When powering-up the device, it is recommended that the Abs Max conditions for each pin are followed for device powersupply sequencing. If PVDD to VBAT absolute maximum setting cannot be followed during power-up, it is recommended that RESET be the last signal that is asserted in the system.

PCM Interface

The flexible PCM peripheral interface supports common audio playback sample rates from 16kHz to 192kHz and I/V sense ADC sample rates from 8kHz to 192kHz. The PCM interface also supports standard I²S, left-justified, and TDM data formats. The PCM interface is disabled and powered down when both the PCM data input (DIN) and PCM data output (DOUT) are disabled.

PCM Clock Configuration

The PCM peripheral interface requires the host to supply both BCLK and LRCLK. To configure the PCM interface clock inputs, the host must program both the device interface sample rate (<u>PCM_SR</u>) and the BCLK to LRCLK (<u>PCM_BSEL</u>) ratio. The PCM interface sample rate must be configured to match the frequency of the frame clock (LRCLK) using the <u>PCM_SR</u> registers. The speaker path sample rate is also set by the <u>PCM_SR</u> setting. However, the I/V sense ADC path sample rate (<u>IVADC_SR</u>) can be set to the same rate or a lower rate than the speaker path sample rate (<u>PCM_SR</u>) according to the restrictions in <u>Table 3</u>. When the I/V sense ADC path is set to a lower rate than the speaker amplifier path, the output data contains repeated samples.

Table 3. Sample Rate Selection For I/V Sense

N/A = Not Available N/S = Not Supported		I/V SENSE ADC SAMPLE RATE (kHz)												
		192	176.4	96	88.2	48	44.1	32	24	22.05	16	12	11.025	8
	192	1	N/S	2	N/S	4	N/S	6	8	N/S	12	16	N/S	24
	176.4	N/A	1	N/S	2	N/S	4	N/S	N/S	8	N/S	N/S	16	N/S
	96	N/A	N/A	1	N/S	2	N/S	3	4	N/S	6	8	N/S	12
PCM Interface	88.2	N/A	N/A	N/A	1	N/S	2	N/S	N/S	4	N/S	N/S	8	N/S
and Speaker	48	N/A	N/A	N/A	N/A	1	N/S	N/S	2	N/S	3	4	N/S	6
Path Sample	44.1	N/A	N/A	N/A	N/A	N/A	1	N/S	N/S	2	N/S	N/S	4	N/S
Rate (kHz)	32	N/A	N/A	N/A	N/A	N/A	N/A	1	N/S	N/S	2	N/S	N/S	4
	24	N/A	N/A	N/A	N/A	N/A	N/A	N/A	1	N/S	N/S	2	N/S	3
	22.05	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	1	N/S	N/S	2	N/S
	16	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	1	N/S	N/S	2

The device supports a range of BCLK to LRCLK clock ratios (<u>PCM_BSEL</u>) ranging from 32 to 512. However, based on the selected PCM interface sample rate (LRCLK frequency), the configured clock ratio cannot result in a BCLK frequency that exceeds 24.576MHz.

PCM Data Format Configuration

The device supports the standard I²S, left-justified, and TDM data formats, and the operating mode is configured using the *PCM_FORMAT* bit field.

I²S/Left-Justified Mode

I²S and left-justified formats support two channels that can be 16-, 24-, or 32-bits in length. The BCLK to LRCLK ratio (<u>PCM_BSEL</u>) must be configured to be twice the desired channel length. The audio data word size is configurable to 16-, 24-, or 32-bits in length (<u>PCM_CHANSZ</u>) but must be programmed to be less than or equal to the channel length. If the resulting channel length exceeds the configured data word size, then the data input LSBs are truncated and the data output LSBs are padded with either zero or Hi-Z data based on the <u>PCM_TX_EXTRA_HIZ</u> register bit setting.

Table 4. Supported I²S/Left-Justified Mode Configurations

CHANNELS	CHANNEL LENGTH	SUPPORTED DATA WORD SIZES (<u>PCM_CHANSZ</u>)	BCLK TO LRCLK RATIO (PCM_BSEL)
	16	16	32
2	24	16, 24	48
	32	16, 24, 32	64

With the default PCM settings, falling LRCLK indicates the start of a new frame and the left channel data (Channel 0) while rising LRCLK indicates the right channel data (Channel 1). In I²S mode, the MSB of the audio word is latched on the second active BCLK edge after an LRCLK transition. In left-justified mode, the MSB of the audio word is latched on the first active BCLK edge after an LRCLK transition.

The <u>PCM_BCLKEDGE</u> register bit selects either the rising or falling edge of BCLK as the active edge that is used for data capture (DIN) and data output (DOUT). The <u>PCM_CHANSEL</u> bit configures which LRCLK edge indicates the start of a new frame (Channel 0), and LRCLK transitions always align with the inactive BCLK edge. The data output is valid on the same active BCLK edge as the data input. The data output also transitions on the same edge as the data input.

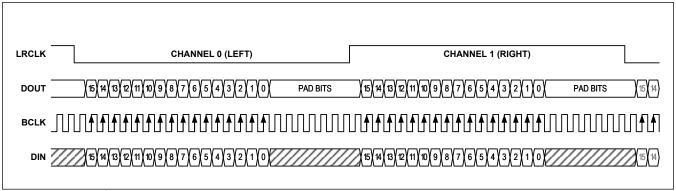


Figure 1. Standard I²S Mode

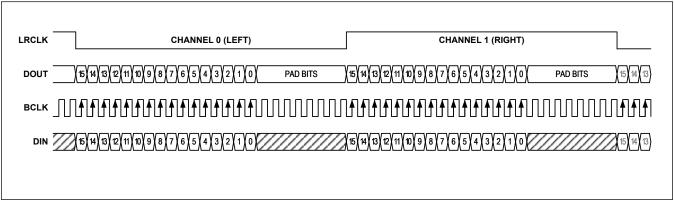


Figure 2. Left-Justified Mode

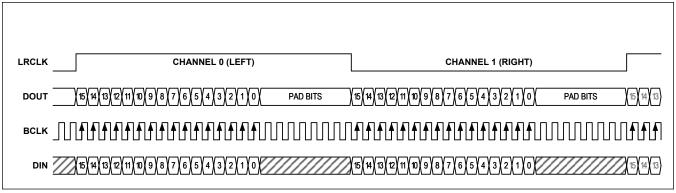


Figure 3. Left-Justified Mode (LRCLK Inverted)

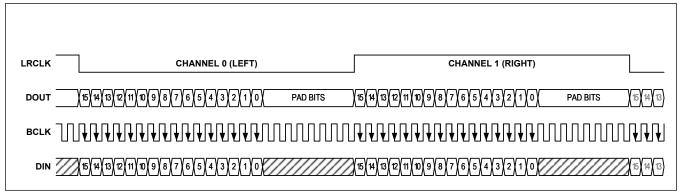


Figure 4. Left-Justified Mode (BCLK Inverted)

TDM Modes

The provided TDM modes support timing for up to 16 digital audio input channels (from DIN) each containing 16-, 24-, or 32-bits of data. The digital audio output (to DOUT) is structured into 8-bit slots, and the timing can support up to a maximum of 128 data output slots. The number of TDM input channels and output slots is determined by both the selected BCLK to LRCLK ratio (<u>PCM_BSEL</u>) and the selected data word and channel length (<u>PCM_CHANSZ</u>).

For a given valid configuration, the number of available data input channels per frame is calculated as follows:

Number of Available Data Input Channels = BCLK to LRCLK Ratio/Channel Length

For a given valid configuration, the number of available 8-bit data output slots per frame is calculated as follows:

Number of Available Data Output Slots = BCLK to LRCLK Ratio/8

<u>Table 5</u> shows the supported TDM mode configurations for each combination of input data channels and output data slots. In some configurations, the maximum PCM interface and speaker amplifier playback sample rate is limited to less than 96kHz to avoid violating the BCLK frequency limit of 24.576MHz.

Table 5. Supported TDM Mode Configurations

INPUT	OUTPUT DATA	DATA WORD SIZES	BCLK TO LRCLK RATIO	MAXIMUM SPEAKER PLAYBACK		
DATA CHANNELS	SLOTS	(<u>PCM_CHANSZ</u>)	(<u>PCM_BSEL</u>)	SAMPLE RATE (f _{LRCLK})		
	4	16	32			
2	6	24	48	192kHz		
	8	32	64			

Table 5. Supported TDM Mode Configurations (continued)

			•	•
3	15	32	125	
	8	16	64	
4	12	24	96	
	16	32	128	
5	15	24	125	
7	15	16	125	
	4	16	32	
2	6	24	48	
	8	32	64	
3	15	32	125	
	8	16	64	
4	12	24	96	
	16	32	128	
5	15	24	125	96kHz
7	15	16	125	90KHZ
/	31	32	250	
	16	16	128	
8	24	24	192	
	32	32	256	
10	31	24	250	
15	31	16	250	
16	32	16	256	
7	31	32	250	
10	31	24	250	
10	40	32	320	48kHz
15	31	16	250	HON IZ
16	48	24	384	
10	64	32	512	

With the default PCM interface settings, in TDM mode a rising frame clock (LRCLK) edge acts as the frame sync pulse and indicates the start of a new frame. The frame sync pulse width must be equal to at least one bit clock period however the falling edge can occur at any time as long as it does not violate the setup time of the next frame sync pulse rising edge. The PCM_CHANSEL bit can be used to invert the LRCLK edges (sync pulse) used to start a TDM frame.

In TDM mode, the MSB of the first audio word can be latched on the first (TDM Mode 0), second (TDM Mode 1), or third (TDM Mode 2) active BCLK edge after the sync pulse and is programmed by the PCM_BCLKEDGE register bit allows for the programmability of the BCLK edge that is used for data capture and data output. The data output is valid on the same active BCLK edge as the data input. The data output also transitions on the same edge as data input.

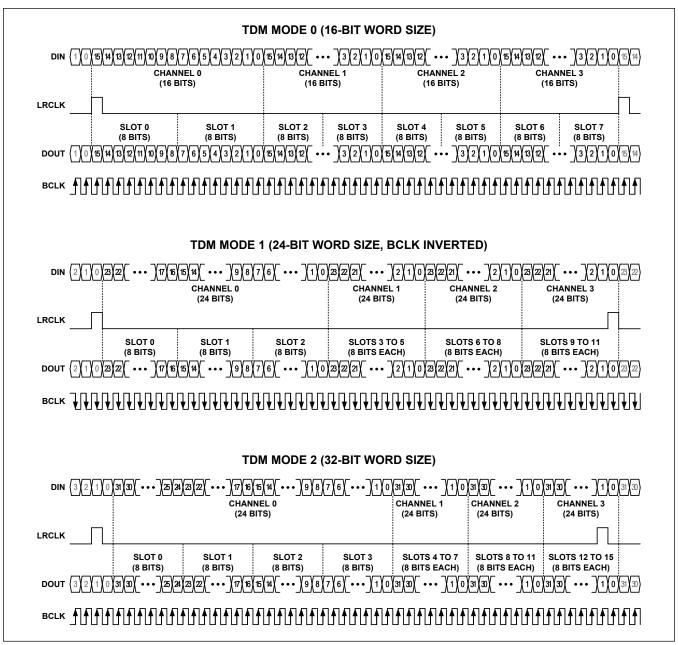


Figure 5. TDM Modes

PCM Data Path Configuration

The PCM interface data input (DIN) receives the source data for the speaker amplifier path, source data for the speaker audio processing bypass path, and the data output (DOUT) transmits the data from the I/V sense ADC path. In addition, the PCM data output can also transmit internal diagnostic data such as the speaker DSP monitor path, supply measurement ADC results, device status reporting, and the DHT attenuation level.

PCM Data Input

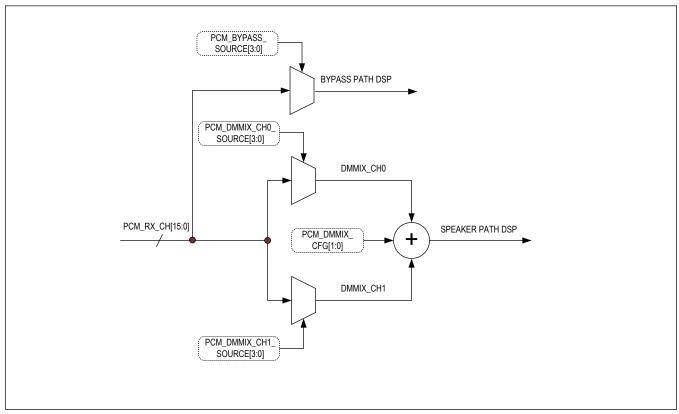


Figure 6. PCM Data Input

The PCM playback path is enabled with the <u>PCM_RX_EN</u> bit and can accept data from any valid input data channel. The device provides an input digital mono mixer that can route a single channel or can mix two PCM input channels to create a mono input to the speaker playback path. The <u>PCM_DMMIX_CFG</u> bit is used to configure the mixer, while the <u>PCM_DMMIX_CHO_SOURCE</u> and <u>PCM_DMMIX_CHI_SOURCE</u> bits select which of the 16 PCM input channels are used as the input to the mono mixer. In I²S and left-justified modes, only 2 input data channels are available while in TDM mode up to 16 channels of input data may be available. If the PCM playback path is disabled (<u>PCM_RX_EN</u> = 0), a zero code value is driven into the speaker amplifier path.

The device also supports an audio processing bypass path from the PCM input to the speaker amplifier output that bypasses the audio processing blocks like the volume control, DHT, BPE, and thermal foldback circuits. The audio processing bypass path is enabled by setting the <u>PCM_BYP_EN</u> bit field to 1. The PCM data input for the audio processing bypass path is selected with the <u>PCM_BYPASS_SOURCE</u> bit field. If the PCM audio processing bypass path is disabled (<u>PCM_BYP_EN</u> = 0), a zero code value is driven into the audio processing bypass path.

PCM Data Output

The PCM interface data output (DOUT) is enabled by the <u>PCM_TX_EN</u> bit field and can transmit any output data type onto any valid output channel or slot. In I²S and left-justified mode, only 2 data output channels are available in each output transmit frame (channels 0 and 1). In TDM mode, each output transmit frame can contain up to 64 sequential 8-bit data output slots, each of which is numbered from 0 up to a maximum of 63.

The PCM data output can transmit several different output data types. In I²S and left-justified modes, only the speaker amplifier output voltage sense, output current sense, ICC data, and DSP monitor output data types are available for data output transmission. If the word size of the data output type is longer than the output channel data word (<u>PCM_CHANSZ</u>), the lowest trailing bits are truncated. In I²S mode, both ICC data and IV sense data can be transmitted only when the

channel data word (<u>PCM_CHANSZ</u>) is 32 bits. In this mode the IV sense data and the ICC data are interleaved. See the <u>Data Output Channel-Interleaved I/V Sense Data</u> section for more details.

In TDM mode, all output data types are available and are individually assigned to data output slots. The output data types vary in word size from 3-bits to 32-bits, and as a result, TDM mode requires from 1 to 4 data output slots to transmit. Table 6 shows the supported output data types and the parameters of each data type.

Table 6. Supported PCM Data Output Types

OUTPUT DATA TYPE	SYMBOL	DATA WORD SIZE (BITS)	NUMBER OF TDM SLOTS	ENABLE/SLOT ASSIGNMENT
Speaker Amplifier Output Voltage Sense	VMON	16	2	PCM_VMON_ENI PCM_VMON_SLOT
Speaker Amplifier Output Current Sense	IMON	16	2	PCM_IMON_ENI PCM_IMON_SLOT
Speaker Amplifier DSP Monitor	DSPMON	32	4	PCM_DSPMONITOR_ENI PCM_DSP_MONITOR_SLOT
Applied DHT Attenuation	DHT_ATN	16	2	PCM_DHT_ATN_ENI PCM_DHT_ATN_SLOT
Supply1 Voltage (V _{VBAT} OR V _{PVDD} OR V _{VDDH})	VSUPPLY1	16	2	PCM_SUPPLY1_ENI PCM_SUPPLY1_SLOTI SUPPLY_SELECT
Supply2 Voltage (V _{VBAT} OR V _{PVDD} OR V _{VDDH})	VSUPPLY2	16	2	PCM SUPPLY2 ENI PCM SUPPLY2 SLOTI SUPPLY SELECT
BPE Level	BPELVL	3	1	PCM_BPE_ENI PCM_BPE_SLOT
ICC Data	ICCDATA	23	4	ICC OVER DOUT ENI PCM ICC SLOT
Device Status Flags	FLAG	14	2	PCM_STATUS_ENI PCM_STATUS_SLOT
Temperature	TEMP	9	2	PCM_THERM_ENI PCM_THERM_SLOT

An individual enable and slot assignment bit field is provided for each output data type. In I^2S and left-justified modes, use output slot 00/01 ($PCM_TX_Control_X = 0x0$) to assign data to channel 0 and output slot 01/02 ($PCM_TX_Control_X = 0x1$) to assign data to channel 1. In TDM mode, for data output types requiring more than 1 slot to transmit, the slot assignment selects the slot where the output data type transmit begins (so for example a 2-slot data type assigned to slot 6 would occupy slots 6 and 7).

In TDM mode, each data type can be assigned to any valid data output slot (or series of slots) with some restrictions. First, it is invalid for data types to be assigned such that the data word extends beyond the end of the data output frame. For example, data types that require 2 slots to transmit cannot be assigned to the last slot of the frame. Next, it is also invalid to assign a data output type to any slot that overlaps with the slot assignment of another data type (this also applies to channels in I²S and left-justified modes). Finally, it is invalid to assign a data type to any slots that do not exist in the frame structure of the current PCM interface configuration.

Any data output (DOUT) slots that exist in the current frame structure but have no output data type assigned to them are either Hi-Z or driven with a 0 code (as set by the PCM_TX_SLOT_HIZ bit field). Likewise, if a data output type is disabled, then the assigned data output slot(s) are also either Hi-Z or driven with a 0 code (as set by the PCM_TX_SLOT_HIZ bit field).

Data Output Channel-Interleaved I/V Sense Data

In I²S and left-justified use cases, the PCM interface limits the number of available data output channels to 2 making it impossible to fit amplifier output current and voltage sense data from stereo devices on a single shared data

output (DOUT) line. For these cases, the data output can be configured to allow the current and voltage sense data types from a single device to share a single data output channel. To enable channel-interleaved mode, set the PCM_TX_INTERLEAVE bit high. Then, assign the current and voltage sense data types to the same valid data channel (using PCM_VMON_SLOT and PCM_IMON_SLOT).

In this configuration, the current and voltage sense data types are frame interleaved on the assigned data output channel. The current and voltage sense data words are both 16-bits in length, and as a result, if the channel length is longer than 16-bits, the trailing padding bits are set to either Hi-Z or 0 code depending on the state of the PCM_TX_EXTRA_HIZ bit field

To identify the data type in channel-interleaved mode, the LSB of the 16-bit data word is dropped (truncated). The data word is then right-shifted by a single bit, and the now vacant MSB is replaced with either a 0 to indicate voltage sense data or a 1 to indicate current sense data. For phase alignment, the voltage sense data for a single sampling instant is always transmitted in the assigned channel on the first frame, followed by the current sense data on the second frame. The MSB value and the transmission order allow the host to identify and phase-align the output data across frames.

Since the I/V sense data is frame interleaved, the sample rate for the PCM interface must be greater than that of the I/V sense ADCs by an integer ratio of 2. <u>Figure 7</u> shows a basic case where the sample rate of the PCM interface is twice that of the I/V sense ADCs.

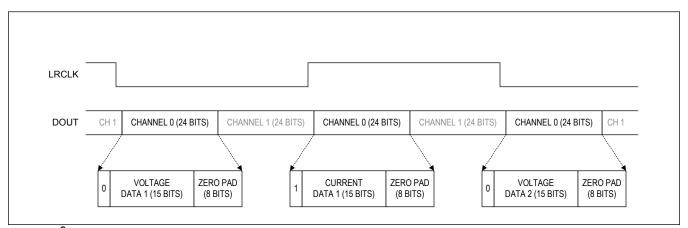


Figure 7. I²S Mode with Interleaved Voltage and Current Data, Channel Length = 24 Bits, Zero Padding

Data Output Status Bits

The following interrupt information is reported in the status slots:

- Bit 15: BPE level 0 begin
- Bit 14: BPE level change
- Bit 13: BPE active begin
- Bit 12: BPE active end
- Bit 11: Thermal warning 1 begin
- Bit 10: Thermal warning 1 end
- Bit 9: Thermal warning 2 begin
- Bit 8: Thermal warning 2 end
- Bit 7: Thermal foldback begin
- Bit 6: Thermal foldback end
- · Bit 5: DHT active end
- Bit 4: DHT active begin
- Bit 3: Speaker overcurrent
- Bit 2: Power-up done
- Bit 1: 0
- Bit 0: 0

Each of the above corresponds to a raw interrupt and is 1 bit wide. When a raw interrupt has a rising edge, the

corresponding status bit goes high during the next LRCLK frame. The status bit goes low during the next LRCLK frame even if the raw interrupt has remained high.

Interrupts

The device supports individually enabled status interrupts for sending feedback to the host about events that have occurred on-chip. When enabled, interrupts are transmitted on the IRQ output.

Interrupt Bit Field Composition

Each interrupt source has five individual bit field components. The function of each component is detailed below and the corresponding bit fields for each source can be identified by the appended suffix (shown in parentheses).

Raw Status (RAW) Each interrupt source has a read-only bit to indicate the real-time raw status of the interrupt source. State (STATE) Each interrupt source has a read-only state bit that is set whenever a rising edge occurs on the associated raw status bit. The state bit is set regardless of the setting of the source enable bit. Flag (FLAG) Each interrupt source has a read-only flag bit. If the source enable bit is set, then the flag bit is set and an interrupt can be generated whenever the source state bit is set. Enable (EN) Each interrupt source has a dynamic read/write enable bit. When the enable bit is set, the associated flag bit is set and an interrupt can be generated whenever the source state bit is set. Clear (CLR) Each interrupt source has a dynamic write-only clear bit. Writing a 1 to a clear bit resets the associated state and flag bits to 0. Writing a 0 to a clear bit has no effect. In I²C control mode, the IRQ output is de-asserted if all flag bits are 0.

Interrupt Output Configuration

The device allows the user to configure the drive mode, drive strength, and polarity of the IRQ output. The <u>IRQ_MODE</u> bit controls the drive mode. If <u>IRQ_MODE</u> is 0, the pin is configured as an open-drained output and requires an external pullup resistor. If <u>IRQ_MODE</u> is 1, then IRQ is configured as a push-pull CMOS output.

Additionally, when IRQ is configured as a push-pull CMOS output, the drive strength control (<u>IRQ_DRV</u>) bits set the drive strength of the IRQ output. Four different CMOS drive strengths are available.

The <u>IRQ POL</u> bit controls the polarity of the IRQ bus. Interrupt events (a flag bit is set high) assert the IRQ bus low if <u>IRQ POL</u> = 0 and high if <u>IRQ POL</u> = 1. The IRQ bus de-asserts if all flag bits are cleared (set low).

Interrupt Sources

Table 7. Interrupt Sources

INTERRUPT SOURCES	BIT FIELD	DESCRIPTION
Thermal Shutdown Begin Event	THERMSHDN_BGN_*	Indicates when the thermal-shutdown threshold temperature has been exceeded.
Thermal Shutdown End Event	THERMSHDN_END_*	Indicates that the die temperature was previously above the thermal-shutdown threshold and has now dropped below the threshold.
Thermal Warning 1 Begin Event	THERMWARN1_BGN_*	Indicates when the thermal-warning1 threshold temperature has been exceeded.
Thermal Warning 1 End Event	THERMWARN1_END_*	Indicates that the die temperature was previously above the thermal-warning1 threshold and has now dropped below the threshold.
Thermal Warning 2 Begin Event	THERMWARN2_BGN_*	Indicates when the thermal-warning2 threshold temperature has been exceeded.
Thermal Warning 2 End Event	THERMWARN2_END_*	Indicates that the die temperature was previously above the thermal-warning2 threshold and has now dropped below the threshold.

Table 7. Interrupt Sources (continued)

	•	
Thermal Foldback Begin Event	THERMFB_BGN_*	Indicates die temperature is above the thermal-warning1 threshold and the device is attenuating the output.
Thermal Foldback End Event	THERMFB_END_*	Indicates die temperature is below the thermal-warning1 threshold and the device has stopped attenuating the output.
BPE Level Change Event	BPE_LEVEL_*	Indicates that the BPE has transitioned between thresholds.
BPE Active Begin Event	BPE_ACTIVE_BGN_*	Indicates that the BPE is active.
BPE Active End Event	BPE_ACTIVE_END_*	Indicates that the BPE is no longer active.
BPE Level 0 Begin Event	<u>BPE_L0_*</u>	Indicates that the BPE has transitioned into L0.
OTP Load Fail Event	OTP_FAIL_*	Indicates when the OTP load routine that runs when exiting hardware shutdown has failed to complete successfully. If the OTP load routine fails, the device is held in software shutdown.
Speaker Over Current Event	SPK_OVC_*	Indicates that the speaker amplifier current limit has been exceeded.
Internal CLK Error	INT_CLK_ERR_*	Indicates a clock stop error in the internal clocks of the device.
External CLK (BCLK/LRCLK) Error	CLK_ERR_*	Indicates a frequency or framing error in the input BCLK or LRCLK.
External CLK (BCLK/LRCLK) Recover	CLK_RECOVER_*	Indicates that the input BCLK or LRCLK has recovered after an error event.
Speaker Amplifier Monitor Error	INT_SPKMON_ERR_*	Indicates an amplifier output stuck high or low error.
External Data (DIN) Error	DMON_ERR_*	Indicates a data stuck or data magnitude error at the PCM data input (DIN).
Power-Up Done Event	PWRUP_DONE_*	Indicates when the device has entered the active state, and the device is ready to play audio.
Power-Down Done Event	PWRDN_DONE_*	Indicates when the device has entered the software-shutdown state.
PVDD UVLO Shutdown Event	PVDD_UVLO_SHDN_*	Indicates that PVDD is below the minimum allowed voltage when the device is in active state.
VBAT UVLO Shutdown Event	VBAT_UVLO_SHDN_*	Indicates that VBAT is below the minimum allowed voltage when the device is in active state.
DHT Active Begin Event	DHT_ACTIVE_BGN_*	Indicates that the DHT circuit is active and is applying attenuation to the signal.
DHT Active End Event	DHT_ACTIVE_END_*	Indicates that the DHT circuit has stopped applying attenuation to the signal.

Note: The bit fields are shown without the component suffixes. For example, OTP_FAIL_* refers to OTP_FAIL_RAW, OTP_FAIL_STATE, OTP_FAIL_FLAG, OTP_FAIL_EN, and OTP_FAIL_CLR. All Interrupt sources have these 5 component bit fields.

Speaker Path

The source input data to the speaker amplifier path is routed from either the PCM interface or the tone generator. The data is then routed through digital filters, signal processing, and volume/gain control blocks before reaching the Class-DG speaker amplifier.

Speaker Path Block Diagram

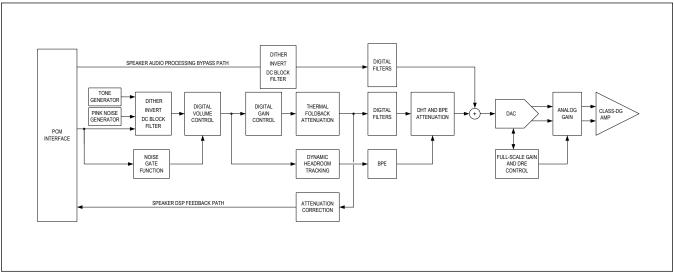


Figure 8. Speaker Signal Path Diagram

Speaker Playback Path

The source input data to the speaker amplifier path is routed from either the PCM interface or the tone generator. The data is then routed through digital filters, signal processing, and volume/gain control blocks before reaching the Class-DG speaker amplifier.

Speaker Path Noise Gate

The speaker path noise gate function is enabled when the device is in the active state and the noise gate enable (<u>NOISEGATE_EN</u>) is set to 1. The noise gate enable can be programmed dynamically. However, if the noise gate function is disabled (<u>NOISEGATE_EN</u> is set to 0) while the noise gate is active (speaker path actively muted), the noise gate function remains active until after it deactivates normally (unmutes the speaker path).

When the noise gate is enabled, the noise gate activates whenever the amplitude of the input audio data to the speaker path (from the PCM interface) is below the configured mute threshold (<u>NG_MUTE_THRESH</u>) for more than 1024 consecutive data samples. When the noise gate is active, the amplifier path is muted, the current and voltage sense ADC paths output zero code data, and the device idles in a reduced power state.

The noise gate deactivates immediately if the amplitude of a single sample from the input audio data exceeds the configured unmute threshold (<u>NG_UNMUTE_THRESH</u>). When the noise gate deactivates, the speaker path is unmuted and returns to normal operation before the input audio data (that triggered deactivation) reaches the speaker output. Once noise gate deactivation is completed, the current and voltage sense ADC paths resume operation and output data normally.

The noise gate mute and unmute threshold settings are selected in terms of the number of bits (starting from the LSB) that must be toggling (or active) for the input signal amplitude to exceed the thresholds. It is invalid to set the noise gate unmute threshold (<u>NG_UNMUTE_THRESH</u>) such that it is less than the configured mute threshold (<u>NG_MUTE_THRESH</u>). The location of the audio data LSB within the PCM input data channel is determined by the configured PCM data word size (<u>PCM_CHANSZ</u>). The supported combinations are shown in <u>Table 8</u>.

Table 8. Noise Gate Threshold LSB Location by Input Data Configuration

INPUT DATA WORD SIZE (<u>PCM_CHANSZ</u>)	NOISE GATE FUNCTION LSB LOCATION
16	16
24	24
32	

It is not valid to enable the speaker path noise gate function when the tone generator is enabled or when the speaker idle mode is enabled.

Speaker Path Dither

The input data to the speaker path can optionally have dither (±1LSB peak-to-peak) applied if <u>SPK_DITH_EN</u> is set to 1. No dither is applied when <u>SPK_DITH_EN</u> is set to 0.

Speaker Path Data Inversion

The input data to the speaker path can optionally be inverted by setting the SPK_INVERT bit is set to 1.

Speaker Path DC Blocking Filter

A DC blocking filter can be enabled on the speaker path by setting the SPK DCBLK EN bit to 1.

Speaker Path Digital Volume Control

The device provides a dynamically programmable speaker path digital volume control. The digital volume control provides an attenuation range of 0dB to -90dB in 0.5dB steps that is configured with the <u>SPK_VOL</u> bit field. A digital mute is also provided and is enabled when <u>SPK_VOL</u> is set to 0xFF.

Digital volume ramping during speaker path start-up, speaker path shutdown, and digital mute (<u>SPK_VOL</u> = 0xFF) is disabled by default. However, both the volume ramp-up and ramp-down can be individually enabled with the <u>SPK_VOL_RMPUP_BYPASS</u> and <u>SPK_VOL_RMPDN_BYPASS</u> bit fields respectively. When volume ramp-up or ramp-down is enabled, the device turn-on and turn-off times are longer.

Speaker Path Digital Gain Control

The device provides a programmable speaker path digital gain control. The digital gain control provides a range of 0dB to +6dB in 0.5dB steps that is configured with the <u>SPK_GAIN</u> bit field. Unlike the digital volume control, the digital gain setting cannot be dynamically changed.

Speaker Path DSP Data Feedback Path

The speaker path DSP data can be routed from just before the DAC input back to the PCM interface, and can be assigned to any valid data output channel. The speaker path DSP data feedback path is enabled with the SPK FB EN bit.

Speaker-Safe Mode

The device provides a safe mode bit (<u>SPK_SAFE_EN</u>), which when set to 1, applies a -18dB attenuation to the input signal. By default, speaker safe mode is enabled to protect any speaker connected to the device on power-up. While speaker safe mode is enabled, the digital volume control (<u>SPK_VOL</u>) and speaker digital gain control (<u>SPK_GAIN</u>) settings are ignored.

Speaker Audio Processing Bypass Path

In applications where the audio processing in the main speaker path is not desired, the device provides a bypass path. The bypass path is selected with the <u>PCM_BYPASS_EN</u> bit field. The PCM data input channel for the speaker audio processing bypass path is selected with the <u>PCM_BYPASS_SOURCE</u> bit field.

Bypass Path Data Inversion

The input data to the audio processing bypass path can optionally be inverted by setting the <u>BYP_INVERT</u> bit to 1.

Bypass Path Dither

The input data to the audio processing bypass path can optionally have dither (±1LSB peak-to-peak) applied if <u>SPK_DITH_EN</u> is set to 1. No dither is applied when <u>SPK_DITH_EN</u> is set to 0. The <u>SPK_DITH_EN</u> bit also controls the dither applied to the audio playback path.

Bypass Path DC Blocking Filter

A DC blocking filter can be enabled on the audio processing bypass path by setting the <u>SPK_DCBLK_EN</u> bit to 1. The <u>SPK_DCBLK_EN</u> also controls the DC blocking filter in the audio playback path.

Speaker Maximum Peak Output Voltage Scaling

The device operates over a large PVDD supply voltage range, and as a result, the full-scale speaker amplifier output amplitude level is configurable to allow it to be scaled. As a baseline, the full-scale output of the speaker path DAC is 3.50dBV (typical). The speaker path no-load maximum peak output voltage level (V_{MPO}) is then programmable relative to this baseline level. The peak output scaling range is from +6dB to +27dB and is set with the <u>SPK_GAIN_MAX</u> bit field.

The speaker output signal level (in dBV) for a given digital input signal level (in dBFS) is calculated as follows:

Output Signal Level (dBV) = Input Signal Level (dBFS) + 0.35 (dBV) + SPK_GAIN_MAX (dB) (0dBFS is referenced to 0dBV)

The peak output voltage scaling is applied to the signal path using a combination of digital gain and analog gain adjustments.

Dynamic Headroom Tracking (DHT)

The device features dynamic headroom tracking (DHT) that can preserve consistent signal distortion and listening levels in the presence of a varying supply level. The DHT block provides both a dynamic range compressor (DRC) and a limiter. The limiter can operate as either a signal distortion limiter (SDL) or a standard signal level limiter (SLL). Each of these three functions can be used independently (modes 1 through 3), and the SLL and DRC can be used simultaneously (mode 4).

The DHT block is enabled with the <u>DHT_EN</u> bit. Before enabling the DHT, the measurement ADC PVDD and VBAT channels should be configured and enabled as required based on the amplifier mode of operation. The DHT block uses the measured supply levels, and the current signal level to calculate the attenuation (if any) that is applied to the signal path. Also, the DHT block should not be disabled by setting the <u>DHT_EN</u> bit to 0 when the DHT is active i.e., attenuation is being applied.

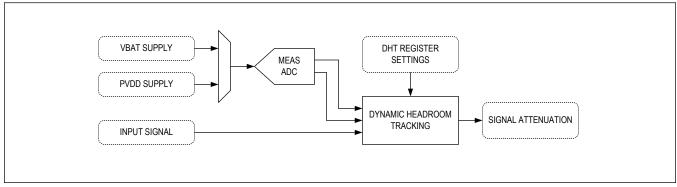


Figure 9. Simplified Dynamic Headroom Tracking System Block Diagram

DHT Supply Tracking and Headroom

The DHT block uses three parameters to track the target peak output level (V_{TPO}) relative to the maximum peak output voltage (V_{MPO}) as the active speaker amplifier supply level varies.

The first is the speaker amplifier full-scale gain setting (<u>SPK_GAIN_MAX</u> bit field). This control selects the maximum (no-load) peak output voltage level (V_{MPO}) that is output by the Class-DG amplifier with a full-scale input signal (0dBFS).

MAX98397

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

Most DHT thresholds and parameters are calculated relative to the full-scale V_{MPO}.

The second parameter is the measured speaker amplifier supply voltage level (V_{SUP}). The measurement ADC provides the DHT block with the current supply voltage levels (V_{PVDD} and V_{VBAT}). The DHT block decides which supply voltage to use for calculations based on the currently active speaker amplifier supply.

The third parameter is the speaker amplifier supply headroom (SUP_{HR}). The supply headroom is a positive or negative percentage offset relative to the measured V_{SUP} conversion result. It is configured using the <u>DHT_HR</u> bit field, and can be set from +20% to -20% of V_{SUP} in 2.5% step sizes.

The DHT target peak output voltage level (V_{TPO}) is equal to the measured supply voltage (V_{SUP}) scaled to include the selected supply headroom percentage, and is actively calculated with the following equation:

$$V_{TPO} = V_{SUP} \times (100\% - SUP_{HR})$$

The target peak output attenuation (or ratio) from V_{TPO} to V_{MPO} is calculated as follows:

$$A_{TPO} = 20 \times \log (V_{TPO}/V_{MPO})$$

If A_{TPO} exceeds 0dB (V_{SUP} with headroom > V_{MPO}), then the DHT block assumes that there is sufficient supply voltage to reproduce the audio signals as configured without attenuation. In this case, A_{TPO} = 0dB is used for all further calculations. This is important as the DHT functions only ever apply attenuation, and never apply positive gain. Once the calculated V_{TPO} drops below V_{MPO} , the calculated target peak output attenuation (A_{TPO}) is less than 0dB, and the DHT functions are applied appropriately as the input signal level changes.

For example, if V_{MPO} = 13.63V, V_{SUP} = 8.04V, and SUP_{HR} = -20% then solving for V_{TPO} yields a target peak output level of ~9.65V. Next, solving for the target peak output attenuation (A_{TPO}) yields approximately -3dB.

Figure 10 shows the default transfer function (with no DHT attenuation applied), and where the current target peak output level (V_{TPO}) is based on the current V_{SUP} and the supply headroom settings. The tracked V_{TPO} and the resulting peak output attenuation (A_{TPO}) are then used in the attenuation calculations for the DHT functions. Note that this and all subsequent figures are not drawn to a precise scale and that the x-axis is the input signal level (dBFS) on a linear scale, while the y-axis is the peak output voltage level on a log scale.

28V Digital Input, Class-DG Amplifier with IV_{SENSE} , Ultra-Low I_Q , and Brownout Prevention

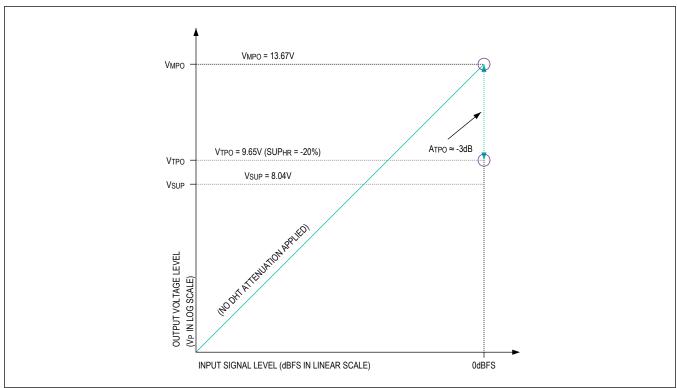


Figure 10. V_{TPO} and A_{TPO} Calculation Example

DHT Mode 1—Signal Distortion Limiter

The DHT signal distortion limiter (SDL) maintains a consistent level of signal distortion at the amplifier output as the supply voltage (V_{SUP}) changes. To use DHT mode 1 (just the signal distortion limiter active), set the <u>DHT_LIM_MODE</u> bit low (default) to place the limiter function in supply tracking mode (SDL), and set the dynamic range compressor rotation point (<u>DHT_VROT_PNT</u>) to 0dBFS (effectively disabling the DRC).

The signal distortion limiter function is a compressor with a ratio of infinity to 1 that actively sets its threshold (V_{SDL} in voltage) equal to the calculated target peak output voltage level (V_{TPO}). The output referred SDL threshold (SDL_{THR}) and the input-referred SDL knee or rotation point (SDL_{RP}) are equal in mode 1, and can be calculated relative to full-scale (in dBFS) as a ratio of V_{TPO} to V_{MPO} :

$$SDL_{RP} = SDL_{THR} = 20 \text{ x log } (A_{TPO}) = 20 \text{ x log } (V_{TPO}/V_{MPO})$$

The transfer function for input signal levels below the SDL rotation point (SDL $_{RP}$) is unchanged. When the input signal level exceeds SDL $_{RP}$, the signal distortion limiter function is applied to the signal path. As the input signal level increases, the distortion limiter attenuation continues to increase as well and can be calculated for a given input signal level (A $_{INPUT}$ in dBFS) as follows:

SDL ATTENUATION = SDLRP - AINPUT

By actively recalculating SDL_{RP} (or SDL_{THR}) as the target peak output level (V_{TPO}) changes, the DHT SDL maintains a consistent limit and level of amplifier output distortion relative to the available supply voltage (V_{SUP}).

When the target peak output voltage (V_{TPO}) exceeds the amplifier maximum peak output voltage (V_{MPO}), there is sufficient headroom and no SDL attenuation is applied. However, as soon as V_{TPO} falls below V_{MPO} , it is possible for the input signal amplitude to exceed the calculated SDL_{RP}. The following figures show the transfer function when $V_{SUP} \ge V_{MPO}$ with the minimum (-20%), no (0%), and maximum (+20%) supply headroom (SUP_{HR}) settings. Note that in the case with positive headroom (+20%), the SDL_{RP} falls below the input signal full-scale level even though $V_{SUP} = V_{MPO}$.

28V Digital Input, Class-DG Amplifier with ${\sf IV}_{\sf SENSE},$ Ultra-Low ${\sf I}_{\sf Q},$ and Brownout Prevention

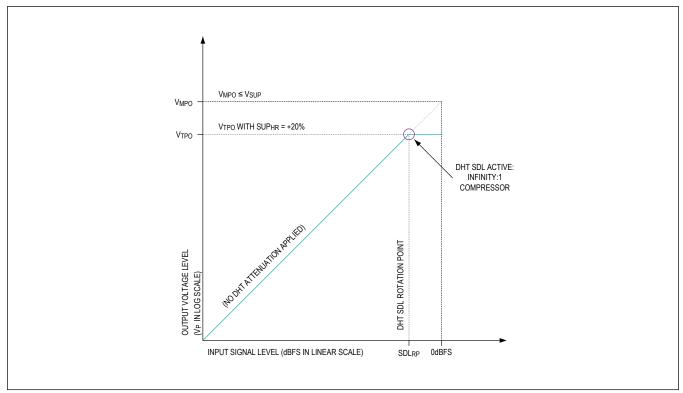


Figure 11. Signal Distortion Limiter with $V_{MPO} \le V_{SUP}$ and +20% Headroom (SUP_{HR})

28V Digital Input, Class-DG Amplifier with $\mathsf{IV}_{\mathsf{SENSE}}, \mathsf{Ultra\text{-}Low} \ \mathsf{I}_\mathsf{Q}, \ \mathsf{and} \ \mathsf{Brownout} \ \mathsf{Prevention}$

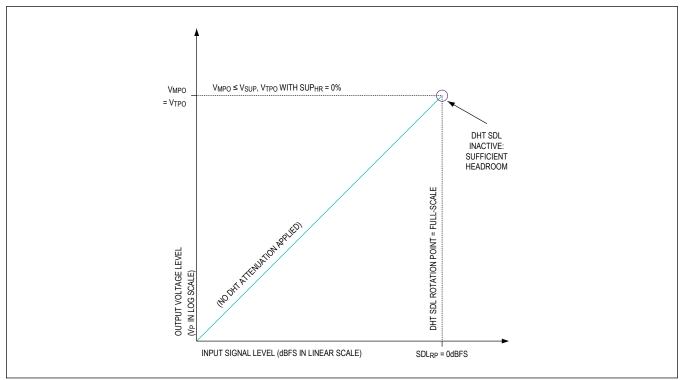


Figure 12. Signal Distortion Limiter with V_{MPO} ≤ V_{SUP} and 0% Headroom (SUP_{HR})

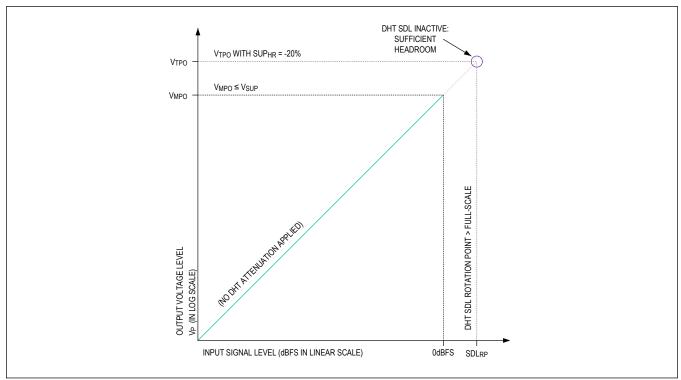


Figure 13. Signal Distortion Limiter with V_{MPO} ≤ V_{SUP} and -20% Headroom (SUP_{HR})

As the supply voltage (V_{SUP}) drops further below the maximum peak output voltage (V_{MPO}), the DHT target peak out voltage (V_{TPO}) proportionally scales down. In cases with zero or positive amplifier supply headroom settings ($+20\% \ge SUP_{HR} \ge 0\%$), the input signal level can exceed the SDL rotation point (SDL_{RP}) before the peak output exceeds V_{SUP} . In this case, amplifier output clipping can be prevented.

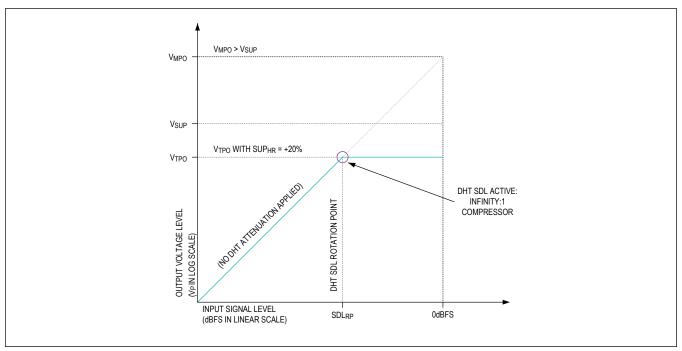


Figure 14. Signal Distortion Limiter with $V_{MPO} > V_{SUP}$ and +20% Headroom (SUP_{HR})

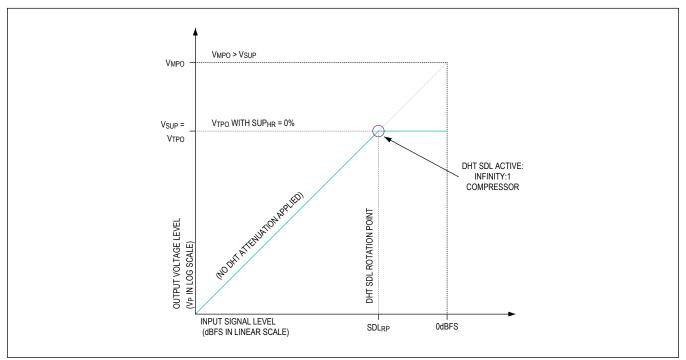


Figure 15. Signal Distortion Limiter with $V_{MPO} > V_{SUP}$ and 0% Headroom (SUP_{HR})

In cases with a negative supply headroom setting (0% > $SUP_{HR} \ge -20\%$), the input signal does not exceed the SDL_{RP}

until after the peak output reaches V_{SUP} . As a result, clipping occurs at the amplifier output. However, once the input signal level exceeds the SDL_{RP} , the audio signal level is digitally limited by the SDL preventing the amplifier output clipping from worsening further.

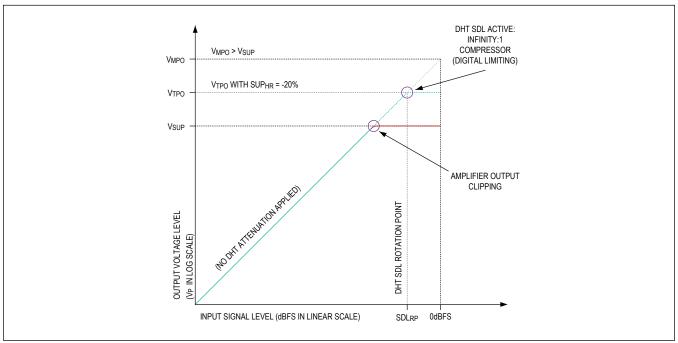


Figure 16. Signal Distortion Limiter with VMPO > VSUP and -20% Headroom (SUPHR)

DHT Mode 2—Signal Level Limiter

In DHT mode 2, the limiter is configured as a fixed threshold signal level limiter (SLL). Set the <u>DHT_LIM_MODE</u> bit high to place the limiter function in SLL mode, and set the dynamic range compressor rotation point to 0dBFS (effectively disabling the DRC).

Like the signal distortion limiter, the signal level limiter function is a compressor with a ratio of infinity to 1. However, unlike the SDL, the SLL output referred threshold (SLL_{THR}) is configured to a set level. The SLL_{THR} is selected with the $\underline{\textit{DHT_LIM_THRESH}}$ bit field from a range of 0dBFS to -15dBFS. The SLL threshold can also be expressed as an input referred knee or rotation point (SLL_{RP}) which is equal to SLL_{THR} in mode 2. The SLL amplifier peak output voltage limit (V_{SLL}) is calculated from the selected SLL threshold (SLL_{THR}) and maximum peak output voltage (V_{MPO}) with the following equation:

SLL PEAK OUTPUT VOLTAGE LIMIT = V_{SLL} = V_{MPO} x 10 ^(SLL_{THR} / 20)

The transfer function for signal levels below the SLL threshold (SLL_{THR}) is unchanged. When the signal level exceeds the SLL_{THR} , the signal level limiter function is applied to the signal path. As the input signal level increases, the limiter attenuation continues to increase as well and can be calculated for a given input signal level (A_{INPUT} in dBFS) relative to SLL_{RP} (= SLL_{THR}) as follows:

SLL ATTENUATION = SLL_{RP} - A_{INPUT}

When V_{TPO} is greater than V_{SLL} , the amplifier peak output level is limited to V_{SLL} whenever the signal amplitude exceeds the SLL threshold (SLL_{THR}). As a result of the fixed SLL threshold and rotation point, the transfer function is identical for any V_{SUP} level and corresponding V_{TPO} that is greater than V_{SLL} .

This is illustrated in Figure 17 for decreasing V_{SUP} and V_{TPO} levels. As V_{SUP} decreases, V_{TPO} is recalculated and decreases as well. Three different, progressively lower V_{TPO} levels are shown (V_{TPO1} , V_{TPO2} , and V_{TPO3}). Due to the fixed SLL threshold, V_{SLL} is the same in all three cases. Since all three V_{TPO} values are greater than V_{SLL} , the transfer function for each case is identical and is limited at V_{SLL} .

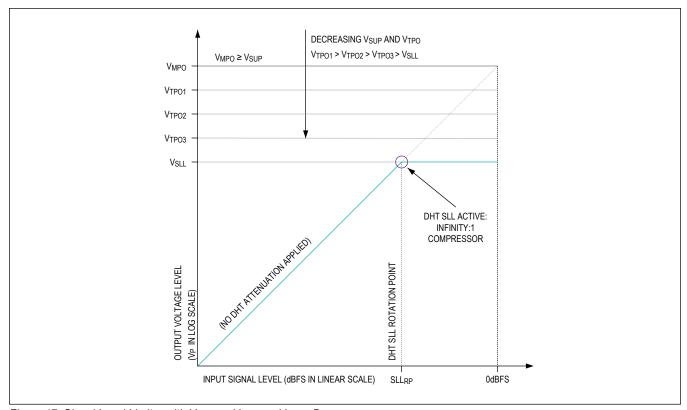


Figure 17. Signal Level Limiter with V_{TPO} > V_{SLL} as V_{SUP} Decreases

When the V_{TPO} is less than V_{SLL} , the amplifier output can clip before the input signal amplitude exceeds the SLL rotation point (SLL_{RP} = SLL_{THR}). As the input signal level continues to increase, once it exceeds SLL_{RP}, the signal level is digitally limited preventing the amplifier output clipping from worsening further. Because both the SLL threshold and rotation point are fixed relative to full-scale, as V_{SUP} continues to decrease the clipping at the amplifier output grows progressively worse before the input signal exceeds SLL_{RP} (= SLL_{THR}).

Figure 18 has the same SLL settings as Figure 17 (same SLL_{THR}). For simplicity, $V_{TPO} = V_{SUP}$ ($SUP_{HR} = 0\%$), and V_{TPO} has decreased further and is now less than V_{SLL} . As a result, the amplifier output clips before the SLL digitally limits the signal level.

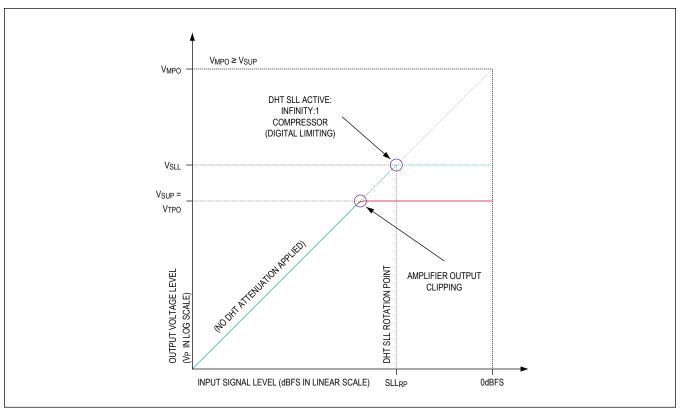


Figure 18. Signal Level Limiter with V_{TPO}< V_{SLL} Showing Amplifier Output Clipping

Note: Do not use DHT_Active_Begin interrupt when SLL is active in DHT Mode 2 and DHT Mode 4 to indicate the start of DHT attenuation on the device.

DHT Mode 3—Dynamic Range Compressor

The DHT dynamic range compressor (DRC) is configured by setting the input referred rotation point (DRC_{RP} in dBFS). The DRC_{RP} can be selected from a range of 0dBFS to -15dBFS with the $\frac{DHT_VROT_PNT}{PNT}$ bit field. To calculate the DRC output referred voltage threshold (V_{DRC}), use the following equation:

$$V_{DRC} = V_{MPO} \times 10^{\circ} (DRC_{RP}/20)$$

For the mode 3 operation, set the DRC rotation point (DRC_{RP}) to any level lower than 0dBFS. Next, to disable limiter functions, place it into signal level limiter mode ($\underline{DHT_LIM_MODE}$ = 1), and set the fixed SLL threshold (SLL_{THR}) to 0dBFS (using the $\underline{DHT_LIM_THRESH}$ bit field).

Once configured, the dynamic range compressor rotation point (DRC_{RP}) is fixed at the selected level (or ratio) relative to the input full-scale. As V_{SUP} and V_{TPO} change, the DRC compression ratio for input signals exceeding DRC_{RP} changes as well. The transfer function, however, for input signals below DRC_{RP} remains unchanged. If the amplifier is operating in class-G mode, it is recommended that the DRC rotation point (DRC_{RP}) be set such that V_{DRC} exceeds the maximum possible VBAT voltage level. This ensures DRC compression is only applied when PVDD is the active amplifier supply, and that the DHT cannot rapidly switch between two different ratios if the active amplifier supply toggles quickly.

DHT tracks the target peak output voltage (V_{TPO}) and attenuation (A_{TPO}). As they change, the adaptive DRC compression ratio smoothly scales the listening level of the amplifier (for any input signals that exceed DRC_{RP}). The DRC compression ratio is actively calculated with the following formula:

DRC COMPRESSION RATIO = DRC_{RP}/(A_{TPO} - DRC_{RP})

The DRC attenuation for a given input signal level (AINPUT in dBFS) is calculated as follows:

DRC ATTENUATION = ATPO - AINPUT x (ATPO / DRCRP)

<u>Figure 19</u> shows the DRC transfer function with SUP_{HR} \geq 0% as V_{SUP} (and thus V_{TPO}) decreases. As the V_{TPO} level decreases (from V_{TPO1} to V_{TPO2} to V_{TPO3}), the DRC compression ratio increases.

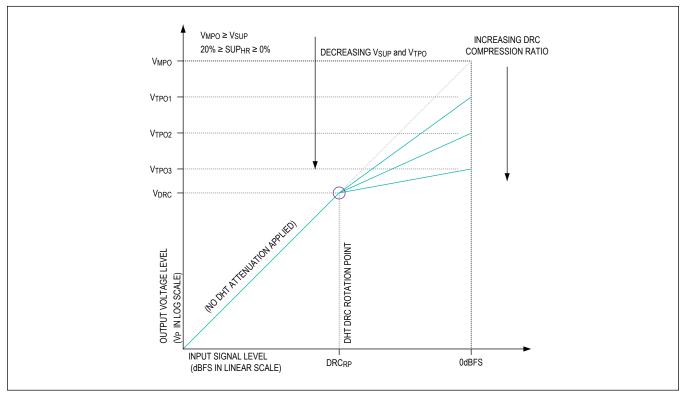


Figure 19. Dynamic Range Compression with Decreasing V_{SUP} and SUP_{HR} ≥ 0%

<u>Figure 20</u> shows the DRC transfer function with $SUP_{HR} < 0\%$. Due to the negative supply headroom, V_{TPO} is greater than V_{SUP} and the amplifier output clips before the input signal reaches full-scale.

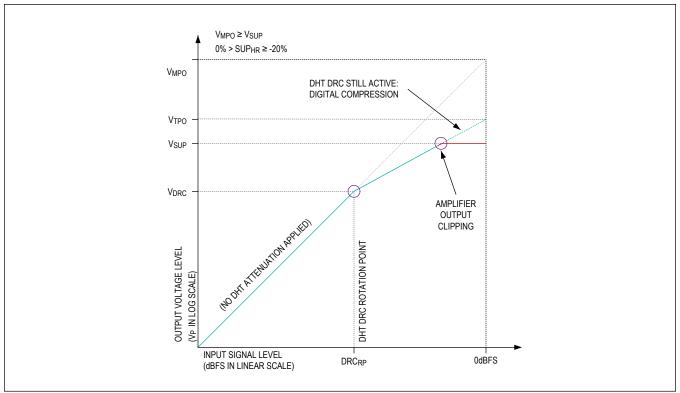


Figure 20. Dynamic Range Compressor with SUPHR < 0% and Output Clipping

DHT Mode 4—Dynamic Range Compressor with Signal Level Limiter

In DHT mode 4, the dynamic range compressor (DRC) and signal level limiter (SLL) are both enabled. To allow mode 4, the DRC rotation point (DRC_{RP}) must be less than 0dBFS. In addition, the DHT limiter function must be configured for SLL mode ($\underline{DHT_LIM_MODE}$ = 1) with an SLL threshold (SLL_{THR}) less than 0dBFS. Finally, to create a DHT response curve with both DRC and SLL inflection points, the SLL threshold (V_{SLL}) must be greater than the DRC voltage threshold (V_{DRC}). This ensures that the resulting SLL_{RP} is always greater than the DRC_{RP} (otherwise, the SLL limits the signal level before the DRC rotation point is ever reached).

<u>Figure 21</u> shows three mode 4 transfer functions for three progressively lower V_{SUP} levels. The supply headroom is configured for $SUP_{HR} > 0\%$ (positive supply headroom), and the calculated V_{TPO} value is falling (such that $V_{TPO1} > V_{TPO2} > V_{TPO3}$). The DRC rotation point and SLL threshold are constant in all three cases, and SLL_{THR} is selected such that as V_{TPO} falls the SLL knee (SLL_{RP}) is greater than the DRC_{RP} .

In the first two cases (for V_{TPO1} and V_{TPO2}), the calculated SLL output voltage limit (V_{SLL}) is less than V_{TPO} . As the signal level increases it is first compressed (by the DRC function), and then limited once the output level reaches V_{SLL} . In the third case, V_{SLL} is greater than V_{TPO3} and the signal level (while still compressed by the DRC) reaches full-scale before exceeding V_{SLL} , and the SLL limiter function is never applied.

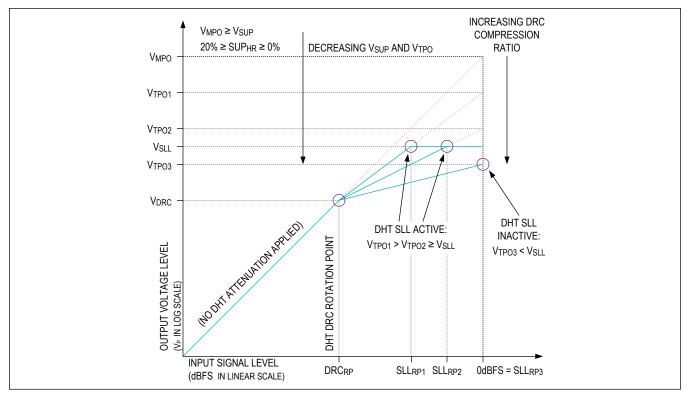


Figure 21. DHT DRC and SLL with Decreasing V_{SUP}(V_{TPO}), and SUP_{HR} ≥ 0%

Figure 22 shows a mode 4 transfer function where the supply headroom is negative (SUP $_{HR}$ < 0%). As before, the SLL threshold (SLL $_{THR}$) is programmed so that the resulting SLL $_{RP}$ is greater than the DRC $_{RP}$. This also ensures that the resulting V $_{SLL}$ is greater than V $_{DRC}$ and less than V $_{TPO}$. As the audio signal level increases, it is first compressed (by the DRC function) and then limited once the digital output signal level reaches V $_{SLL}$. However, due to the negative headroom, the amplifier output clips before the SLL function digitally limits the signal level.

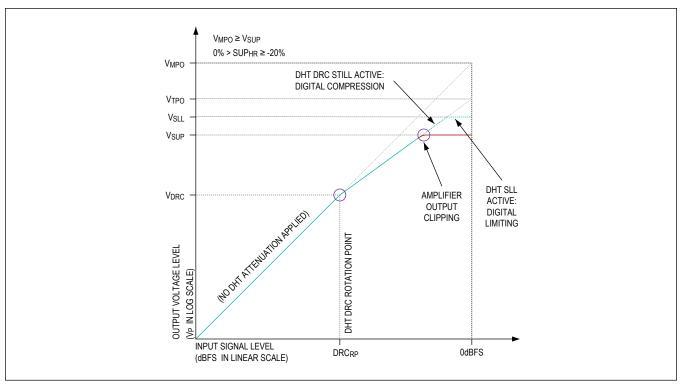


Figure 22. DHT DRC and SLL with Decreasing V_{SUP}(V_{TPO}), and SUP_{HR} < 0%

DHT Attenuation

When the DHT block first applies attenuation, an interrupt is generated (<u>DHT_ACTIVE_BGN_*</u>). When the DHT block fully releases all applied attenuation (i.e., DHT is inactive) an interrupt is generated (<u>DHT_ACTIVE_END_*</u>). Interrupts are not generated when DHT is actively adjusting the level of attenuation.

The maximum attenuation (A_{MAX}) applied to the audio signal by the DHT functions is selected with the <u>DHT MAX ATN</u> bit field. The maximum attenuation can be set from -1dB to -15dB with a 1dB step size. The configured DHT functions stop further attenuation of the audio signal once the calculated attenuation (relative to the un-attenuated input signal level) reaches the selected maximum attenuation (A_{MAX}). If the calculated attenuation (based on input signal level and measured V_{SUP}) exceeds the selected maximum attenuation (A_{MAX}), the applied attenuation is set equal to (limited at) A_{MAX} . This can occur anytime that the target peak output (V_{TPO}) to maximum peak output (V_{MPO}) ratio or peak output attenuation (denoted A_{TPO}) is less than (or has a larger absolute value than) A_{MAX} .

All previous examples show cases where the peak output attenuation (A_{TPO}) did not exceed the selected maximum attenuation (A_{MAX}). The figures below show signal distortion limiter use cases where V_{SUP} has decreased until A_{TPO} < A_{MAX} (the DHT DRC function DRC_{RP} is set to 0dbFS as in use case 1).

In Figure 23, the SUP $_{HR}$ is set to -20%. Since $A_{TPO} < A_{MAX}$, the attenuation applied by the distortion limiter reaches the programmed maximum attenuation level before the input signal reaches full-scale. For input signals past the point where calculated attenuation is equal to A_{MAX} , the attenuation stops increasing and is now fixed at A_{MAX} . As a result, past this point the audio signal (in the digital domain) begins to increase. This results in the distortion increasing at the amplifier output (which was already clipping at the limited level of distortion).

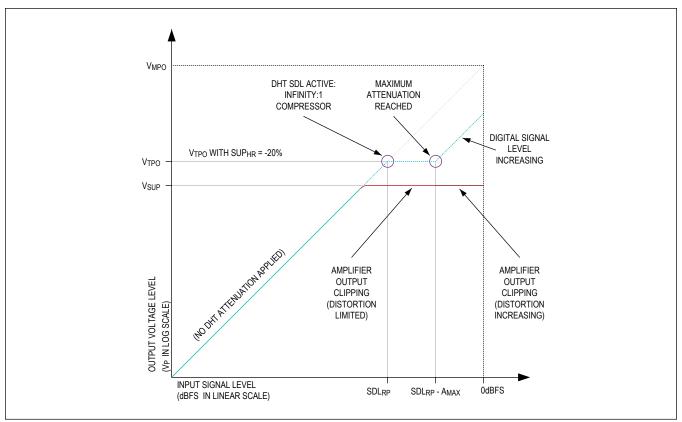


Figure 23. Distortion Limiter Case with -20% Headroom and A_{MAX} Exceeded

In Figure 24, the supply headroom is set to +20%. As before, the attenuation applied by the SDL reaches the selected maximum attenuation (A_{MAX}) before the input signal reaches full-scale. Past this point, the audio signal (in the digital domain) begins increasing, and the signal level (and any distortion) at the amplifier output increases as well. In this case, the amplifier output was not clipping until after A_{MAX} was exceeded.

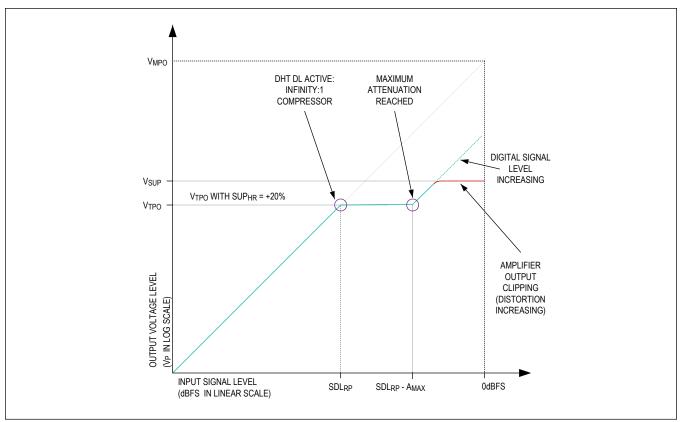


Figure 24. Distortion Limiter Case with +20% Headroom and AMAX Exceeded

DHT Attenuation Reporting

In TDM mode, the current level of DHT attenuation is reported on the PCM data output (DOUT) when the DHT attenuation transmit enable bit is set high (<u>PCM_DHT_ATN_EN</u> = 1). The DHT attenuation level output is transmitted as a 14-bit unsigned binary attenuation level.

DOUT CURRENT DHT ATTENUATION (dB) = 20 x log(14-bit DOUT Value /16383)

If enabled, the DHT attenuation target (in dB) is also shared between devices on the Inter Chip Communication (ICC) bus. In this case, the DHT attenuation level output requires two ICC output slots (8 bits each) and is transmitted as a 10-bit unsigned binary attenuation level (DHT_ATN) followed by 6 bits of zero padding.

The current DHT attenuation (in dB) is calculated from the 10-bit value (DHT ATN) with the following equation:

ICC CURRENT DHT ATTENUATION (dB) = - (DHT_ATN[9:0] x 0.015625dB)

The current DHT attenuation level cannot exceed the selected DHT maximum attenuation (A_{MAX}). Additionally, when the DHT is inactive, the reported attenuation is 0x0.

DHT Ballistics

When the signal level exceeds the rotation point or threshold for a configured DHT function (SDL, SLL, and/or DRC) or continues to increase beyond this point, the appropriate level of attenuation is applied to the signal level at the programmed attack rate. The DHT attack rate is selected with the DHT_ATK_RATE bit field. The actual attack rates for small attenuations and faster attack rates are slightly higher than specified in the table due to a fixed 0.5ms/dB response time required by the peak detector in the path.

The change in input signal level is detected by a peak detect circuit which has a fixed 3.5ms release time. When the signal level decreases or drops below the rotation point or threshold for a configured DHT function (SDL, SLL, and/or DRC), the appropriate level of applied attenuation is released. The DHT release rate is selected with the <u>DHT RLS RATE</u> bit field.

However, due to the 3.5ms/dB peak detector, the 2ms/dB release rate is effectively 3.5ms/dB. All other release rates have a fixed delta of 3.5ms compared to the programmed release rate.

The attack and release behavior is a bit different when triggered by a change in the active amplifier supply level. When the supply level decreases and triggers a DHT function attack, the attenuation is applied quickly at the configured attack rate. Likewise, as the supply level increases, the attenuation is released at the configured release rate. However, if DHT supply hysteresis is enabled (<u>DHT_SUPPLY_HYST_EN</u> = 1), then as the supply increases the applied DHT function does not release attenuation until the increase in the supply level exceeds the programmed DHT supply hysteresis level (<u>DHT_SUPPLY_HYST</u>). Once the supply increase exceeds the hysteresis, the appropriate level of applied attenuation is released at the configured release rate.

Speaker Amplifier

The device features a Class-DG speaker amplifier output stage. The speaker amplifier playback path is enabled and disabled using the <u>SPK_EN</u> bit. The Class-DG multilevel amplifier generates a rail-to-rail output, pulse-width modulated (PWM) signal. By varying the PWM duty cycle, the amplifier modulates the output with the audio input signal. Because the switching frequency of the amplifier is 320kHz (typical) when the output signal is filtered by the speaker, only the audio component remains.

The default Class-D amplifier switching frequency is 320kHz, and results in the best efficiency. However, the output switching frequency is programmable and can be increased to 620kHz by setting the TRI_FSW2X_MODE bit field to 1. The increased switching frequency setting trades an improvement in THD+N performance for a reduction in amplifier efficiency.

Rail-to-rail operation ensures that power dissipation at the output is dominated by the on-resistance (R_{ON}) of the power output MOSFETs, brief saturation current draw as the output switches as well as the current draw necessary to charge the output stage gates. In MAX98397, the high-side output stage gate drive supply is provided by bootstrap pins VBOOT_P and VBOOT_N. For proper operation of the bootstrap circuit, a small ceramic capacitor must be connected between the bootstrap pin (VBOOTP or VBOOTN) and the associated Class-D output pin (OUTP or OUTN).

In addition, the amplifier's output MOSFETs are segmented, and to save power they are automatically scaled based on the selected operating mode, input signal level, and configured gain structure.

Speaker Amplifier Operating Modes

The speaker amplifier can operate both in Class-DG and standard Class-D modes. In Class-DG mode, the amplifier output supply rail is switched between V_{PVDD} and V_{VBAT} based on the signal level. If Class-DG operation is disabled the amplifier operates as a fixed supply Class-D amplifier and can be configured to use either V_{PVDD} or V_{VBAT} as the output supply rail. The speaker amplifier operating mode is selected with the SPK MODE bit field.

Class-DG Mode Enabled

Class-DG is the default speaker amplifier mode of operation (<u>SPK_MODE</u> = 0x0). In this mode, the amplifier switches the supply rail between PVDD and VBAT as needed to efficiently supply the required output power.

Additionally, if V_{VBAT} drops below a programmed threshold level <u>VBATLOW_OK_LVL</u> bit field the amplifier operates from PVDD supply rail regardless of signal level.

The Class-DG signal level threshold (VDG_THR) at which the amplifier switches between the supply rails is programmable. The method used to program the signal level threshold is selected with the <u>SPK_DG_SEL</u> bit field. When <u>SPK_DG_SEL</u> is set to 0x0, the threshold (VDG_THR) is set to a fixed peak voltage level with the <u>SPK_DG_SEL</u> bit field. When <u>SPK_DG_SEL</u> is set to 0x1 (default), the threshold (VDG_THR) is variable relative to the current VBAT voltage (measurement ADC result). The peak voltage headroom relative to V_{VBAT} is configured with the <u>SPK_DG_HEADROOM</u> bit field. Finally, if <u>SPK_DG_SEL</u> is set to 0x2, the threshold (VDG_THR) is set based on whichever setting (SPK_DG_THRES and <u>SPK_DG_HEADROOM</u>) results in the lowest threshold for the current V_{VBAT} voltage level. As a result, as V_{VBAT} decreases VDG_THR may transition from a fixed threshold to a lower V_{VBAT} headroom-based variable threshold.

The Class-DG mode hold time is configured with the <u>SPK_DG_HOLD_TIME</u> bit field. To save power, when the signal level drops below the threshold for longer than the hold time, VBAT is selected as the active amplifier supply. The amplifier switches to the VBAT supply only at signal zero cross so the measured hold time is the register-configured hold time plus the time taken for a zero cross event to occur. When VBAT is the active amplifier output supply, the LV_EN

MAX98397

28V Digital Input, Class-DG Amplifier with IV_{SENSE} , Ultra-Low I_Q , and Brownout Prevention

output asserts high. When the signal level rises above the threshold, the amplifier supply quickly switches to PVDD to provide a higher output voltage swing and to avoid clipping. When PVDD is the active amplifier output supply, the LV_EN output asserts low.

Delay for DG Mode

When the amplifier is operating in the automatic Class-DG mode, to avoid the potential for clipping the output signal as the PVDD supply rises, there is a programmable delay in the signal path controlled by <u>SPK_DG_DELAY</u>. This allows the PVDD supply time to increase the output voltage before it is required to output larger signals.

Class-DG Mode Disabled

When Class-DG mode is disabled the speaker amplifier operates in standard Class-D mode. In this case, the active amplifier output supply is configured to either PVDD ($\underline{SPK_MODE} = 0x1$) or VBAT ($\underline{SPK_MODE} = 0x2$).

If the active amplifier output supply is configured to VBAT (<u>SPK_MODE</u> = 0x2), the amplifier operates from VBAT regardless of signal level. In this mode, the LV_EN pin is asserted high.

When the active amplifier supply is set to PVDD, the amplifier always operates from PVDD regardless of the signal and supply levels. Furthermore, to save power PVDD can be actively regulated between any levels within its standard operating range (3V to 28V). In this mode, LV_EN pin is always asserted low.

IDLE Mode

In customer systems where an external LC filter is used for EMI reduction, the quiescent power consumption and power consumption in DG Mode for low signal levels can be reduced by setting the <u>IDLE MODE_EN</u> bit-field to 1. The Idle mode setting is not intended for operation in PVDD mode (with the VBAT pin supplied externally) and should not be enabled.

When the idle mode is enabled, the idle mode activates whenever the amplitude of the input audio data to the speaker path (from the PCM interface) is below the configured mute threshold (<u>NG MUTE THRESH</u>) for more than 1024 consecutive data samples. When the idle mode is active the current and voltage sense ADC paths output zero code data. The idle mode deactivates immediately if the amplitude of a single sample from the input audio data exceeds the configured unmute threshold (<u>NG UNMUTE THRESH</u>). When the idle mode deactivates the current and voltage sense ADC paths resume operation and output data normally.

The idle mode mute and unmute threshold settings are selected in terms of the number of bits (starting from the LSB) that must be toggling (or active) for the input signal amplitude to exceed the thresholds. It is invalid to set the noise gate unmute threshold (<u>NG_UNMUTE_THRESH</u>) such that it is less than the configured mute threshold (<u>NG_MUTE_THRESH</u>). The location of the audio data LSB within the PCM input data channel is determined by the configured PCM data word size (<u>PCM_CHANSZ</u>). The supported combinations are shown in <u>Table 8</u>.

It is not valid to enable idle mode and noise gate functions simultaneously.

Speaker Amplifier Ultra-Low EMI Filterless Operation

Traditional Class-D amplifiers require the use of external LC filters, or shielding, to meet electromagnetic-interference (EMI) regulation standards. However, the device features emissions-limiting circuitry that limits the output switching harmonics that can directly contribute to EMI and radiated emissions.

The programmable speaker amplifier edge rate control bits are used to adjust the switching edge rate to help tune EMI performance. As the edge rate increases, the efficiency improves slightly, while as the edge rate is decreased, the efficiency drops slightly. The speaker amplifier edge rate is configured with the <u>SPK_SL_RATE_GMODE</u>, <u>SPK_SL_RATE_LS</u>, and <u>SPK_SL_RATE_HS</u> bit fields.

The speaker amplifier output also supports spread spectrum modulation (SSM). SSM is enabled by default, and it optimizes the suppression and control of the output switching harmonics that can contribute to EMI and radiated emissions. The modulation index in spread-spectrum mode is controlled by the TRI_SSM_MOD bit field, and the maximum modulation index (MMI) varies accordingly. Higher percentage settings of the modulation index result in the switching frequency of the amplifier being modulated by a wider range, spreading out-of-band energy across a wider bandwidth. Above 10MHz, the wideband spectrum looks like noise for EMI purposes.

Speaker Amplifier Overcurrent Protection

The device features amplifier current limit protection that protects the amplifier output from both high current and short circuit events. If the <u>OVC_AUTORESTART_EN</u> bit is set to 1 and the speaker amplifier output current exceeds the current limit threshold (8.3A min.), the device generates an interrupt and disables the amplifier output. After ~20ms, the amplifier output is re-enabled. If the overcurrent condition still exists, the device continues to disable and re-enable the amplifier output automatically until the fault condition is removed.

If the <u>OVC_AUTORESTART_EN</u> bit is set to 0, when a speaker amplifier overcurrent event occurs the device still generates an interrupt and disables the amplifier output. However, in this case the device is placed into software shutdown and the software enable (<u>EN</u>) bit is set to 0. As a result, the host must manually re-enable the device after an overcurrent event.

Speaker Current and Voltage Sense ADC Path

The device provides two separate 16-bit ADCs to monitor the speaker amplifier output current and voltage (the I/V sense ADC path). The current and voltage ADC paths are independently enabled with the IVADC_I_EN and IVADC_I_EN and IVADC_I_EN and IVADC_I_EN and IVADC_I_EN bits respectively. Voltage and Current ADC data is output through the PCM interface data output (DOUT) which is enabled by the PCM_TX_EN bit field.

For accurate voltage measurements, the OUTPSNS and OUTNSNS pins should be Kelvin connected as close as possible to the load connected between OUTP and OUTN. If a filter is installed between the speaker amplifier output pins and the load, then the sense lines should be connected close to the load and after the filter. The speaker amplifier current is measured internally and requires no external connections.

The voltage and current digital data output are routed to the host through the PCM interface. Both the current and voltage sense ADC output data can optionally have dither applied (±1 LSB peak-to-peak) by setting the IVADC_DITH_EN bit field to 1. No dither is applied when IVADC_DITH_EN is set to 0.

The I/V sense ADC path provides separate optional DC blocking filters (first-order highpass) in the current and voltage sense paths. The current and voltage path filters are enabled by setting the IVADC I DCBLK EN and IVADC V DCBLK EN bit fields to 1 respectively.

To ensure phase alignment, the current and voltage sense ADCs should be enabled either with a single write to the $\underline{IVADC\ I\ EN}$ and $\underline{IVADC\ V\ EN}$ bits (\underline{EN} = 1) or by setting both bits high before exiting software shutdown.

Brownout-Prevention Engine

The brownout-prevention engine (BPE) allows the device to reduce its contribution to the overall system power consumption by attenuating the amplifier output when the supply drops below a set of programmable thresholds. The BPE is enabled and disabled using the <u>BPE_EN</u> bit. The BPE can be enabled at any time by setting the <u>BPE_EN</u> bit high. However, the BPE must not be disabled when it is active (in critical supply levels 0 through 3). The BPE can be disabled safely at any time that it is inactive. The input to the BPE controller is selected using the <u>BPE_SRC_SEL</u> bit. By default, the input to the BPE controller is the measurement ADC PVDD channel. If the selected measurement ADC channel is not already active, enabling the BPE will automatically enable it. The sample rate and filter settings for the measurement ADC determine the speed at which the BPE updates. Note that the signal limiter block acts on the audio data before the gain reduction block in the speaker playback data path.

28V Digital Input, Class-DG Amplifier with IV_{SENSE} , Ultra-Low I_Q , and Brownout Prevention

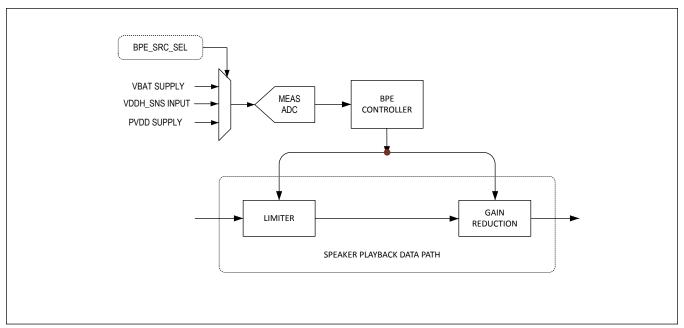


Figure 25. BPE Block Diagram

BPE State Controller and Level Thresholds

There are a total of four BPE critical supply levels each with individually programmable thresholds. The thresholds for each level are configured with the BPE_L0_VTHRESH to BPE_L3_VTHRESH bit fields respectively. The BPE state controller monitors the measurement ADC channel results and automatically makes state changes.

Table 9. Brownout-Prevention Engine Levels

THRESHOLD NAME CONDITION			
BPE Inactive	V _{SUPPLY} > Critical Supply Level 3		
Critical Supply Level 3	Critical Supply 3 ≥ V _{SUPPLY} > Critical Supply Level 2 + Hysteresis		
Critical Supply Level 2	Critical Supply Level 2 ≥ V _{SUPPLY} > Critical Supply Level 1 + Hysteresis		
Critical Supply Level 1	Critical Supply Level 1 ≥ V _{SUPPLY} > Critical Supply Level 0 + Hysteresis		
Critical Supply Level 0	V _{SUPPLY} ≤ Critical Supply Level 0		

The brownout engine supports hysteresis on the levels. This behaves as follows:

- When in level N, transition to level N + 1 when V_{SUPPLY} stays above (level N threshold) + (hysteresis).
- When in level N, transition to level N 1 when V_{SUPPLY} falls below the level N threshold.

The amount of hysteresis is defined by the <u>BPE_VTHRESH_HYST</u> register. and the hysteresis is only applied to the thresholds when the supply voltage is increasing. The amount of hysteresis can be defined as larger than the distance between two levels.

Thresholds must be configured so that the level N threshold is greater than the sum of the level N - 1 threshold and the hysteresis. For example, if the level 2 threshold is set to 3.15V and hysteresis is set to 25mV, then the level 3 threshold must be set to 3.1875V or higher.

The current level that the BPE is in can be read-back using the <u>BPE_STATE</u> register. The <u>BPE_LOWEST</u> register contains the lowest BPE level that the controller has visited since the last time the <u>BPE_LOWEST</u> register was read.

BPE Level Configuration Options

For a given BPE level, the following options are configurable to reduce the overall device current draw:

Gain Attenuation Function

Limiter Function

Each of these configuration options are individually configurable for each BPE level.

BPE Gain Attenuation Function

The speaker gain attenuation block reduces the overall current drawn by the device at low supply voltages by applying smooth digital gain changes to the signal path. For each BPE level, the maximum attenuation that can be applied can be independently configured. The maximum attenuation that can be applied for each level is programmable from 0 to -31dB in 1dB steps and is configured using the BPE Lx MAXATTN bits.

When the V_{SUPPLY} voltage level falls below the programmed level, the brownout controller waits for a time equal to the programmed dwell time for the level before applying attenuation at the programmed attack rate. The brownout controller then enters the hold time phase when maximum attenuation is reached or when the V_{SUPPLY} voltage increases and causes the brownout controller to enter the next level. After the programmed hold time for a BPE level expires, the controller enters the release phase where the controller releases the attenuation at the programmed release rate. Additionally, each BPE level has independent programmable settings for dwell time (<u>BPE Lx DWELL</u>), hold time (<u>BPE Lx BAIN ATK</u>), and release rate (<u>BPE Lx GAIN ATK</u>). While the attack-and-release rates are independently configurable for the gain attenuation and limiter block, the attack-and-release step size settings are common.

BPE Limiter Function

The BPE limiter function allows the device to reduce the overall current draw at low supply levels by quickly attenuating (<15us) input signals that exceed a programmed threshold. When the BPE limiter is enabled (<u>BPE_LIM_EN</u> = 1), the device ignores the signal distortion limiter and signal level limiter settings in the DHT. In this state, the limiter knee threshold is determined solely by the BPE limiter setting of the current BPE level. Each BPE level has an individually configured limiter threshold (set by <u>BPE_Ln_LIM</u>) that is programmable from 0dBFS and -15dBFS in 1dB steps.

Input signals that exceed the limiter knee threshold are attenuated, while input signals below the threshold are not. Each BPE level has an individually configured attack-and-release step size (<u>BPE_Lx_STEP</u>), attack rates (<u>BPE_Lx_LIM_ATK</u>) and release rates (<u>BPE_Lx_LIM_RLS</u>). While the attack-and-release rates are independently configurable for the gain attenuation and limiter block, the attack-and-release step size settings are common.

The <u>BPE_LOWEST_LIMIT</u> register contains the lowest limiter setting applied to the brownout controller. The register is updated upon reading to show the current limiter setting applied by the BPE.

Brownout Interrupts

The BPE can generate interrupts triggered by the following conditions:

- BPE controller enters level 0 (<u>BPE L0 *</u>)
- BPE controller changes from one level to another (<u>BPE_LEVEL_*</u>)
- BPE controller is active (<u>BPE ACTIVE BGN *</u>)
- BPE controller is no longer active (BPE ACTIVE END *)

See the *Interrupts* section for more information.

Measurement ADC

The device features a configurable 9-bit measurement ADC. The measurement ADC has four channels, one for die temperature measurement (measurement ADC thermal channel), one for PVDD supply voltage measurement (measurement ADC PVDD channel), one channel for VBAT supply voltage measurement (measurement ADC VBAT channel), and one channel for external supply sense voltage measurement (measurement ADC VDDH_SNS channel). Enabled channels are measured sequentially and continuously.

The measurement ADC sample rate is programmable in regular mode (<u>MEAS_ADC_OPT_MODE</u> = 0) and it can be set independently for each channel. In addition, the device provides two measurement ADC optimal sample rate modes (<u>MEAS_ADC_OPT_MODE</u> > 0) that provides a fixed higher sample rate for the BPE source channel and lower sample rates for all other measurement ADC channels. Each channel separately provides an optional programmable lowpass IIR filter.

28V Digital Input, Class-DG Amplifier with IV_{SENSE} , Ultra-Low I_Q , and Brownout Prevention

Measurement ADC Channel Optimal Mode

Measurement ADC Channel Optimal Modes provide the fastest change to the amplifier output in response to a BPE event. The VBAT and PVDD measurement ADC channels on the device must be enabled (<u>MEAS_ADC_PVDD_EN</u>, <u>MEAS_ADC_VBAT_EN</u>) when using MEAS_ADC_OPT_MODE > 0. If VDDH_SNS input is used in the system, either for supply monitoring or as a BPE Source channel, the VDDH_SNS measurement ADC channel must be enabled (<u>MEAS_ADC_VDDH_EN</u>).

<u>Table 10</u> shows the measurement ADC sample rates for the different measurement ADC channels in the two measurement ADC optimal modes.

Table 10. Measurement ADC Channels Sample Rate in Optimal Modes

MEAS_ADC_OPT_MODE	BPE SOURCE	BPE SOURCE SAMPLE RATE	THERMAL CHANNEL SAMPLE RATE	SECONDARY SUPPLY CHANNEL SAMPLE RATE	VDDH_SNS ADC CHANNEL STATE	VDDH_SNS SAMPLE RATE
	VBAT	600kHz	37.5kHz	PVDD = 300kHz	Disabled	_
	PVDD	600kHz	37.5kHz	VBAT = 300kHz	Disabled	_
	VDDH_SNS	525kHz	37.5kHz	VBAT = 300kHz PVDD = 75kHz	Enabled	525kHz
0x1	VBAT	525kHz	37.5kHz	VBAT = 525kHz PVDD = 300kHz	Enabled	75kHz
	PVDD	525kHz	37.5kHz	VBAT = 300kHz PVDD = 525kHz	Enabled	75kHz
	VBAT	900kHz	37.5kHz	PVDD = 75kHz	Disabled	_
	PVDD	900kHz	37.5kHz	VBAT = 75kHz	Disabled	_
0x2	VDDH_SNS	825kHz	37.5kHz	VBAT = 75kHz PVDD = 75kHz	Enabled	825kHz
	VBAT	825kHz	37.5kHz	VBAT = 825kHz PVDD = 75kHz	Enabled	75kHz
	PVDD	825kHz	37.5kHz	VBAT = 75kHz PVDD = 825kHz	Enabled	75kHz

Measurement ADC Thermal Channel

When the device is clocked, in the active state (EN = 1) the measurement ADC thermal channel automatically activates. When active, it continuously measures and reports the device die temperature over the range from -29° C to $+150^{\circ}$ C.

The output of the thermal ADC channel can be read back through the <u>MEAS_ADC_THERM_DATA</u> bit field and is the input to both the thermal protection and thermal foldback blocks. By default (<u>MEAS_ADC_THERM_RD_MODE</u> = 0), the thermal readback value is automatically updated after each conversion is completed. Setting <u>MEAS_ADC_THERM_RD_MODE</u> to 1 places thermal readback into manual mode. In manual mode, the thermal readback result is updated manually when a 1 is written to the <u>MEAS_ADC_THERM_UPD</u> bit field. The ADC thermal channel data read back in manual mode and the data streamed through the PCM interface is 9 bits. In the automatic mode, since the 9-bit data readback is from two registers, the LSB register isn't guaranteed to be synchronous with the MSB register and can result in higher noise in the automatic mode.

The highest measured temperature measurement result is read back through the <u>HIGHEST_THERM_DATA_MSB</u> and <u>HIGHEST_THERM_DATA_LSB</u> bit fields. These bit fields both automatically clear and are reset to the value of the current measurement result immediately after LSB readback is completed.

The thermal ADC channel also provides an optional lowpass IIR filter with a programmable bandwidth that scales relative to the measurement ADC sample rate. The filter is enabled with the <u>MEAS_ADC_TEMP_FILT_EN</u> bit field and the bandwidth is set with the <u>MEAS_ADC_TEMP_FILT_COEFF</u> bit field.

Measurement ADC PVDD Channel

When the device is clocked and in the active state (<u>EN</u> = 1), the measurement ADC PVDD channel can be enabled. The PVDD channel is manually enabled by setting the <u>MEAS_ADC_PVDD_EN</u> bit to 1 and must be manually enabled for the DHT to operate. When the channel is enabled, it continuously measures and reports the PVDD supply voltage level over the range of 2.5V to 28V.

The output of the measurement ADC PVDD channel can be read back through the <u>MEAS_ADC_PVDD_DATA</u> bit field, and is routed to the DHT. By default (<u>MEAS_ADC_PVDD_RD_MODE</u> = 0), the PVDD readback value is automatically updated after each conversion is completed. Setting <u>MEAS_ADC_PVDD_RD_MODE</u> to 1 places PVDD readback into manual mode. In manual mode, the readback result is updated when a 1 is written to the <u>MEAS_ADC_PVDD_RD_UPD</u> bit field. The ADC_PVDD channel data read back in manual mode and the data streamed via the PCM interface is 9 bits. In the automatic mode, since the 9-bit data readback is from two registers, the LSB register isn't guaranteed to be synchronous with the MSB register and can result in higher noise in automatic mode.

The lowest measured PVDD measurement result is read back through the <u>LOWEST_PVDD_DATA_MSB</u> and <u>LOWEST_PVDD_DATA_LSB</u> bit fields. These bit fields both automatically clear and are reset to the value of the current measurement result immediately after LSB readback is completed.

The PVDD channel also provides an optional lowpass IIR filter with a programmable bandwidth that scales relative to the measurement ADC sample rate. The filter is enabled with the <u>MEAS_ADC_PVDD_FILT_EN</u> bit and the bandwidth is set with the <u>MEAS_ADC_PVDD_FILT_COEFF</u> bit field.

Measurement ADC VBAT Channel

When the device is clocked, in the active state (EN = 1), the measurement ADC VBAT channel can be enabled. The VBAT channel is manually enabled by setting the <u>MEAS ADC VBAT EN</u> bit to 1 and must be manually enabled for the DHT to operate. When the channel is enabled, it continuously measures and reports the VBAT supply voltage level over the range of 2.5V to 5.5V.

The output of the measurement ADC VBAT channel can be read back through the <u>MEAS_ADC_VBAT_DATA</u> bit field. By default (<u>MEAS_ADC_VBAT_RD_MODE</u> = 0), the VBAT readback value is automatically updated after each conversion is completed. Setting <u>MEAS_ADC_VBAT_RD_MODE</u> to 1 places VBAT readback into manual mode. In manual mode, the readback result is updated when a 1 is written to the <u>MEAS_ADC_VBAT_RD_UPD</u> bit field. The ADC VBAT channel data read back in manual mode and the data streamed through the PCM interface is 9 bits. In the automatic mode, since the 9-bit data readback is from two registers, the LSB register isn't guaranteed to be synchronous with the MSB register and can result in higher noise in automatic mode.

The lowest measured VBAT measurement result is read back through the <u>LOWEST_VBAT_DATA_MSB</u> and <u>LOWEST_VBAT_DATA_LSB</u> bit fields. These bit fields both automatically clear and are reset to the value of the current measurement result immediately after LSB readback is completed.

The VBAT channel also provides an optional lowpass IIR filter with a programmable bandwidth that scales relative to the measurement ADC sample rate. The filter is enabled with the <u>MEAS_ADC_VBAT_FILT_EN</u> bit and the bandwidth is set with the <u>MEAS_ADC_VBAT_FILT_COEFF</u> bit field.

Measurement ADC VDDH Channel

When the device is clocked, and in the active state (<u>EN</u> = 1), the measurement ADC VDDH channel can be enabled. The VDDH channel is manually enabled by setting the <u>MEAS_ADC_VDDH_EN</u> bit to 1. When the channel is enabled, it continuously measures and reports the VDDH supply voltage level over the range of 2.5V to 28V.

The output of the measurement ADC VDDH channel can be read back through the <u>MEAS_ADC_VDDH_DATA</u> bit field, and is routed to the BPE. By default (<u>MEAS_ADC_VDDH_RD_MODE</u> = 0), the VDDH readback value is automatically updated after each conversion is completed. Setting <u>MEAS_ADC_VDDH_RD_MODE</u> to 1 places VDDH readback into manual mode. In manual mode, the readback result is updated when a 1 is written to the <u>MEAS_ADC_VDDH_RD_UPD</u> bit field. The ADC_VDDH channel data read back in manual mode and the data streamed via the PCM interface is 9 bits. In the automatic mode, since the 9-bit data readback is from two registers, the LSB register isn't guaranteed to be synchronous with the MSB register and can result in higher noise in automatic mode.

The lowest measured VDDH measurement result is read back through the <u>LOWEST_VDDH_DATA_MSB</u> and LOWEST_PVDD_DATA_LSB bit fields. These bit fields both automatically clear and are reset to the value of the current measurement result immediately after the LSB readback is completed.

The VDDH channel also provides an optional lowpass IIR filter with a programmable bandwidth that scales relative to the measurement ADC sample rate. The filter is enabled with the <u>MEAS_ADC_VDDH_FILT_EN</u> bit and the bandwidth is set with the <u>MEAS_ADC_VDDH_FILT_COEFF</u> bit field.

Clock and Data Monitors

The device provides input data and external clock monitors that detect host and system-level faults. The data monitor detects persistent stuck and high amplitude input signals, while the clock monitor detects external clock failures and invalid clock configurations. Upon fault detection, these monitors automatically place the device into software shutdown to stop glitches and unwanted signals at the amplifier output and speaker load.

Input Data Monitor

The device provides an optional input data monitor that is enabled by setting <u>DMON_MAG_EN</u> to 1 for the data magnitude monitor or <u>DMON_STUCK_EN</u> to 1 (for the data stuck monitor). Once the data monitor is enabled, it actively monitors the selected input data (from DIN) to the speaker amplifier path anytime the device exits software shutdown (<u>EN</u> = 1) and the amplifier is enabled (<u>SPK_EN</u> = 1). When the tone generator is enabled, the data monitor is automatically disabled.

When active, the block monitors the selected input data for the enabled data error types (data magnitude, data stuck, or both). The <u>DMON_DURATION</u> bit field selects the duration that a data stuck or magnitude error must persist for before a data error is detected. Once a data error is detected, the data monitor automatically places the device into software shutdown (sets <u>EN</u> to 0) and generates a data monitor error interrupt (<u>DMON_ERR_*</u>).

A data stuck error is detected if the input signal repeats a fixed value with a magnitude (positive or negative) that is beyond the data stuck threshold (<u>DMON_STUCK_THRES</u>) for longer than the data error duration (set by <u>DMON_DURATION</u>) if the input signal repeats a fixed value for any duration with a magnitude that is within the data stuck threshold limits (such as a zero or near zero code), no data stuck error is detected.

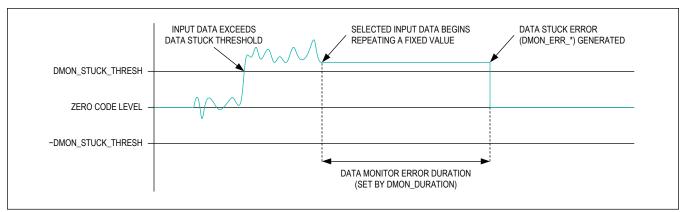


Figure 26. Data Monitor Error Generation due to Input Data Stuck Error Detection

A data magnitude error is detected if the input signal magnitude (positive or negative) is beyond the data magnitude threshold (set by <u>DMON MAG THRES</u>) for longer than the data error duration (set by <u>DMON DURATION</u>).

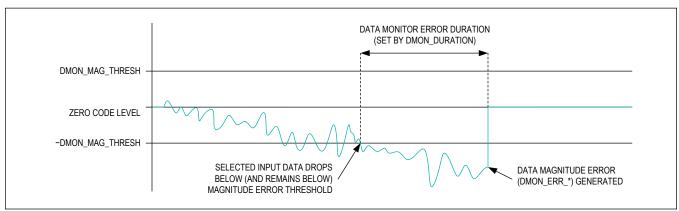


Figure 27. Monitor Error Generation due to Input Data Magnitude Error Detection

Clock Monitor

The device provides a clock monitor that is enabled by setting $\underline{CMON_EN}$ to 1. Once enabled, it actively monitors the input BCLK and LRCLK anytime the device exits software shutdown (\underline{EN} = 1). When the tone generator is enabled, the clock monitor is automatically disabled. When active, the clock monitor detects clock activity, clock frequency, and frame timing (clock ratio). If faults are detected, the clock monitor automatically places the device into software shutdown and generates a clock error interrupt ($\underline{CLK_ERR_*}$).

The clock monitor operates in automatic mode when <u>CMON AUTORESTART EN</u> = 1 and manual mode when <u>CMON AUTORESTART EN</u> = 0. In automatic mode, when a clock error places the device into software shutdown the global enable bit (EN) is not changed (remains 1), and the device automatically recovers from all clock errors. In automatic mode, both clock error (<u>CLK_ERR_*</u>) and clock recovery (<u>CLK_RECOVER_*</u>) interrupts are generated in pairs (a clock recovery interrupt is not possible until after a clock error has occurred).

In manual mode, when a clock error places the device into software shutdown, the global enable bit (EN) is set to 0. Clock recovery (CLK RECOVER *) interrupts are never generated in manual mode, and the device remains in software shutdown until the host sets EN back to 1. Once the device is re-enabled (EN set to 1), the clock monitor is active and detects any new (or persisting) clock errors. If a clock error is detected, the device returns to software shutdown (EN = 0), and a new clock error interrupt (CLK ERR *) is generated.

Clock errors are fault conditions, and audible glitches may occur on clock monitor-based transitions into and out of software shutdown. When the clock monitor is enabled, no false clock error or clock recovery interrupts are generated

when the host software transitions the device normally into and out of software shutdown.

The clock monitor is enabled by default, and it is highly recommended to keep the block enabled to allow the speaker monitor to function correctly in absence of BCLK and LRCLK.

Clock Activity and Frequency Detection

When the clock monitor is enabled, the bit clock (BCLK) and frame clock (LRCLK) frequencies are monitored. The expected LRCLK frequency is equal to the PCM sample rate (<u>PCM_SR</u>). The expected BCLK frequency is based on the BCLK to LRCLK ratio (<u>PCM_BSEL</u>) relative to the PCM sample rate (<u>PCM_SR</u>).

The current frequency of each clock is measured relative to (and once per interval of) the programmed frame period (as set by <u>PCM_SR</u>). A clock frequency error is detected when the measured clock frequencies differ from programmed clock frequencies (faster or slower) by more than the frequency error threshold (45% typical). If either clock stops high or low, the frequency measurement result allows the detection of the clock stop event.

The <u>CMON_ERRTOL</u> bit field sets the clock frequency error tolerance. The tolerance is the required number of consecutive frame clock periods (<u>PCM_SR</u>) with an incorrect clock frequency before a clock error is generated. If the error persists for the selected number of frame periods, a clock error interrupt (<u>CLK_ERR_*</u>) is generated, and the device is placed into software shutdown.

In automatic mode, the <u>CMON_ERRTOL</u> bit field also sets the number of consecutive frame clock periods with no clock frequency errors (LRCLK or BCLK) that are required for automatic restart to occur. Once the selected number of consecutive error-free frames are detected, a clock recovery interrupt (<u>CLK_RECOVER_*</u>) is generated and the device automatically exits software shutdown.

In manual mode, no clock recovery interrupts are generated. The clock monitor remains disabled, and the device remains in software shutdown until the host software sets *EN* back to 1.

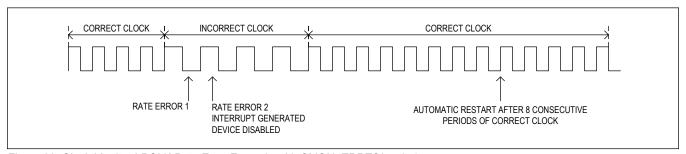


Figure 28. Clock Monitor LRCLK Rate Error Example with CMON_ERRTOL = 0x1

Clock Frame Error Detection

When the clock monitor is enabled, the bit clock (BCLK) to frame clock (LRCLK) ratio is monitored. The clock monitor counts the number of BCLK periods per frame (LRCLK period) and then compares the count to the configured clock ratio (<u>PCM_BSEL</u>). In addition, in I²S and left-justified (LJ) modes the clock monitor verifies the LRCLK duty cycle by checking that the number of BCLK periods per channel is equal. In TDM mode, data transport is synchronized to the active frame clock (LRCLK) edge, so no duty cycle restrictions are enforced.

A frame error is detected in each frame where the monitored clock ratio (and duty cycle in I²S and LJ modes) differs from the configured settings. The <u>CMON_BSELTOL</u> bit field sets the number of consecutive frames with frame errors that are required before a clock error interrupt is generated (CLK_ERR_*) and the device is placed into software shutdown.

In automatic mode, the <u>CMON_BSELTOL</u> bit field also sets the number of consecutive frames with no frame errors that are required for automatic restart to occur. Once the selected number of consecutive error-free frames are detected, a clock recover interrupt (CLK_RECOVER_*) is generated and the device automatically exits software shutdown.

In manual mode, no clock recovery interrupts are generated. The clock monitor remains disabled, and the device remains in software shutdown until the host software sets *EN* back to 1.

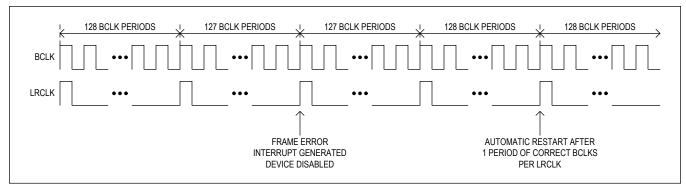


Figure 29. Clock Monitor Framing Error Example in TDM Mode with PCM_BSEL = 0x6 and CMON_BSELTOL = 0x0

Speaker Monitor

The speaker monitor is a circuit that is designed to protect the speaker against amplifier signals that could damage it. The speaker monitor is enabled by default and can be disabled by setting the <u>SPKMON_EN</u> bit to zero. The circuit monitors the amplifier's PWM signal and shuts down the amplifier output when the DC signal goes above a programmed speaker monitor threshold (set by <u>SPKMON_THRESH</u>). Additionally, the device also generates an <u>INT_SPKMON_ERR</u> interrupt. For the speaker monitor to operate, PCM clocks should be available.

Thermal Protection

When the device is active, the measurement ADC thermal channel is automatically enabled, and it monitors the die temperature to ensure that it does not exceed the configured thermal thresholds. Interrupt registers are provided so that the device can notify the host when the die temperature crosses either the thermal warning or thermal-shutdown threshold, or when thermal foldback starts and stops.

Thermal Warning and Thermal Shutdown Configuration

The device features two thermal-warning thresholds. The thermal-warning thresholds are configured by <u>THERMWARN1_THRESH[6:0]</u> and <u>THERMWARN2_THRESH[6:0]</u> bit fields and the thermal-shutdown threshold is configured by the <u>THERMSHDN_THRESH[5:0]</u> bit field. The thermal-warning2 threshold should always be set to a temperature higher than or equal to the thermal-warning1 temperature. Additionally, the thermal-warning2 threshold temperature should never be configured higher than the thermal shutdown threshold temperature minus hysteresis. When the die temperature is decreasing, hysteresis is applied to thermal-shutdown, thermal-warning1, and thermal-warning2 thresholds. The temperature hysteresis is configured with the <u>THERM_HYST</u> bit field.

Thermal Shutdown Recovery Configuration

The device thermal-shutdown recovery behavior is determined by the state of the <u>THERM_AUTORESTART_EN</u> bit. When the <u>THERM_AUTORESTART_EN</u> bit is set to 0, the thermal-shutdown recovery is in manual mode. In manual mode, when the die temperature exceeds the thermal-shutdown threshold an interrupt is generated and the amplifier output is automatically disabled. Once the die temperature drops below the thermal shutdown minus the hysteresis and thermal-warning2 threshold minus the hysteresis, the appropriate interrupts are generated to notify the host. In addition, once the die temperature drops below the thermal-warning2 threshold minus the hysteresis, the device is placed into software shutdown (<u>EN</u> is set to 0) and remains in that state until the host manually re-enables the device. When the <u>THERM_AUTORESTART_EN</u> bit is set to 1, the thermal-shutdown recovery is in automatic mode. In automatic mode, when the die temperature exceeds the thermal-shutdown threshold an interrupt is generated and the amplifier is automatically disabled. Once the die temperature drops below the thermal-shutdown threshold minus the hysteresis, an interrupt is generated but the amplifier remains disabled. When the temperature drops below the thermal-warning2 threshold minus the hysteresis, another interrupt is generated and (unlike manual mode) the amplifier is then automatically re-enabled.

Thermal Foldback

The device features thermal foldback to allow for a smoother audio response to high-temperature events. Thermal

foldback is enabled by setting the <u>THERMFB_EN</u> bit to 1. The device provides two thermal-warning thresholds that are configured by <u>THERMWARN1_THRESH[6:0]</u> and <u>THERMWARN2_THRESH[6:0]</u> bit fields. They should be set such that the thermal-warning2 threshold temperature is higher than or equal to the thermal-warning1 threshold temperature. Additionally, the thermal-warning2 threshold temperature should never be configured higher than the thermal-shutdown threshold temperature minus hysteresis.

Once enabled, when the die temperature exceeds the configured thermal-warning1 threshold, the thermal foldback begins, interrupts are generated (<u>THERMFB_BGN_*</u> and <u>THERMWARN1_BGN_*</u>) and attenuation is applied to the speaker amplifier path. The slope of the thermal foldback attenuation is programmed with the <u>THERMFB_SLOPE1</u> bit field.

If the die temperature continues to increase and exceeds the configured thermal-warning2 threshold, an interrupt (<u>THERMWARN2_BGN_*</u>) is generated and attenuation is continued to be applied to the speaker amplifier path. The slope of the attenuation applied to the speaker amplifier path is now programmed with the <u>THERMFB_SLOPE2</u> bit field. As the die temperature increases, the level of attenuation also increases proportionally up to a maximum level of -12dB (unless the thermal-shutdown threshold is exceeded first). When thermal foldback is active, the attack time for a gain change can be a maximum of 2 samples. Additionally, there is a sample delay in the signal path attenuation due to the group delay of the amplifier.

When the die temperature starts to decrease and drops below the thermal-warning2 threshold minus the programmed hysteresis level and remains there for longer than the programmed hold time (set with the <u>THERMFB_HOLD</u> bit field), the attenuation starts to release and an interrupt (<u>THERMWARN2_END_*</u>) is generated. If the die temperature continues to reduce and drops below the thermal-warning1 threshold temperature minus the programmed hysteresis level, thermal foldback ends and interrupts (<u>THERMFB_END_*</u> and <u>THERMWARN1_END_*</u>) are generated. The attenuation release rate (for decreasing temperature) is programmable and is configured with the <u>THERMFB_RLS</u> bit field.

Tone Generator

The device includes a tone generator which when enabled (using the <u>TONE_EN</u> bit field) replaces the PCM interface as the input source to the speaker playback path. When the tone generator is enabled, both it and the speaker playback path operates without the need for any external clocks.

The tone generator output is configured to generate sine wave or DC tones (using the TONE CONFIG bit field).

The tone generator can create sine waves with either a 1kHz fixed frequency or a variable sample rate-dependent frequency. When a sample rate-based sinewave output is selected, the tone generator output frequency is set by the playback sample rate setting (<u>PCM_SR</u>) divided by the selected ratio (as set by <u>TONE_CONFIG</u>). For the playback sample rate of 44.1kHz and its multiples, the tone generator output frequency can vary by up to 9%. The tone generator supports all available sample rate settings (<u>PCM_SR</u>). The amplitude of the output sine wave relative to full-scale is selected with the <u>TONE_AMPLITUDE</u> bit field.

The tone generator can output either a fixed or a programmable DC output level (as set by <u>TONE_CONFIG</u>). Fixed DC output levels of zero code, positive half-scale, and negative half-scale are provided for quick configuration. If the programmable DC output level is selected (<u>TONE_CONFIG</u>), the DC level is configured as a signed two's complement value with the <u>TONE_DC</u> bit field.

Pink Noise Generator

The device includes a pink noise generator which when enabled (using the <u>PINK_NOISE_EN</u> bit field) replaces the PCM interface as the input source to the speaker playback path. The pink noise generator and the tone generator cannot be enabled at the same time. When the pink noise generator is enabled, both it and the speaker playback path operate without the need for any external clocks. The output level of the generator is fixed, so the amplifier gain and speaker volume must be used to adjust the level.

Interchip Communication

The device features an interchip communication (ICC) interface that uses a shared data bus to facilitate synchronized speaker amplifier path attenuation adjustments across groups of devices. Depending on the configuration, the ICC interface can synchronize the brownout prevention engine (BPE), DHT, and thermal foldback. Each device receives the data of the other grouped devices and reacts accordingly.

ICC Operation and Data Format

The bidirectional ICC bus is used to synchronize the responses of grouped devices. To create the ICC bus, the ICC interface pins of each device are externally connected (whether or not the devices are in the same group). The ICC bus operates with the same clock sources and data format configuration as the PCM interface data input (DIN), and can support a maximum of 16 channels. For a given valid PCM interface configuration, the number of available ICC data channels per frame is calculated as follows (based on the <u>PCM_CHANSZ, PCM_BSEL</u>, and <u>PCM_FORMAT</u> settings):

Number of Available Data Input Channels = BCLK to LRCLK Ratio / Channel Length

The ICC interface is disabled when both the ICC data transmit output (ICC TX EN) and the ICC data link (ICC LINK EN) is disabled. To enable the ICC interface, both ICC TX EN and ICC LINK EN must be set to 1. It is illegal to set these controls to different values, and both must always be set to the same state (either enabled or disabled). Once the ICC link and data transmit are enabled, the ICC data output channel is assigned with the ICC TX DEST bit field. The ICC pin is Hi-Z during all other data channels and can be configured (with the ICC RX CHN EN bits) to accept data from the output data channels of grouped devices.

The transmitted ICC data is always the same size as the configured PCM data input word size (as set by <u>PCM_CHANSZ</u>). When a 16-bit data word is selected, the ICC data word is not long enough to synchronize BPE, DHT, and thermal foldback. In this case, the <u>ICC_DATA_SEL</u> bit is used to choose whether the DHT function or thermal foldback function is synchronized in addition to the BPE state. When a 24-bit or 32-bit data word size is selected, ICC can synchronize BPE, DHT, and thermal foldback across a given group. In these cases, the <u>ICC_DATA_SEL</u> bit has no effect. Active ICC data channels always contain ICC data words followed by the zero-padding bit up to the ICC data channel length (which is equal to the PCM input data channel length). If BPE, DHT, or thermal foldback is disabled for any given group, then the transmitted ICC data for the disabled function(s) is always zero code.

Multiamplifier Grouping

The ICC interface allows multiple devices to be grouped so that BPE, DHT, and thermal foldback behavior can be synchronized. The receive channel enables (ICC RX CHn EN) are used to define groups. A given device monitors all selected channels (when ICC RX CHn EN = 1, and n denotes the channel number) on the ICC data bus. The configured set of receive channels must also include the assigned transmit channel (as set by ICC TX DEST) for any given device. Each device in a given group must have identical settings for all ICC receive channel enables (ICC RX CHn EN). Furthermore, all devices in the same group must have identical DHT, thermal protection, and thermal foldback settings to achieve a synchronized response across the group. The behavior of a group as a whole is undefined if any given device in a group has different settings.

The ICC bus can support a maximum of 16 data channels. The minimum size of a group is two devices, and as a result, the maximum number of concurrent groups on a single ICC bus is eight. A group can contain as many as 16 devices, but then only a single group is possible on a single ICC bus.

ICC Multigroup Example

Consider a system design that includes four devices that require DHT synchronization, and that two distinct groups of two devices each (with different DHT settings) must share a single ICC bus. The PCM interface (and thus the ICC bus) is configured in TDM mode 1 with four 16-bit data channels available. One possible configuration (among many) is to assign devices 1 and 3 to the first group (denoted group A) and to assign devices 2 and 4 to a second group (denoted group B).

To configure group A, both devices 1 and 3 are set to monitor channels 0 and 2 by programming <u>ICC_RX_CH0_EN</u> = 1 and <u>ICC_RX_CH2_EN</u> = 1 on both devices (all other ICC receive bit fields are 0). Device 1 transmits on channel 0 (ICC_TX_DEST = 0x0) and device 3 transmits on channel 2 (ICC_TX_DEST = 0x2).

To configure group B, both devices 2 and 4 are set to monitor channels 1 and 3 by programming <u>ICC_RX_CH1_EN</u> = 1 and <u>ICC_RX_CH3_EN</u> = 1 on both devices (all other ICC receive bit fields are 0). Device 2 transmits on channel 1 (<u>ICC_TX_DEST</u> = 0x1) and device 4 transmits on channel 3 (<u>ICC_TX_DEST</u> = 0x3).

Since the ICC channel length and data word size is limited to 16 bits, the <u>ICC_DATA_SEL</u> bit field in all 4 devices must be set to 0 to select DHT target attenuation synchronization. Finally, on all 4 devices set <u>ICC_LINK_EN</u> = 1 and <u>ICC_TX_EN</u> = 1 to enable the ICC interfaces.

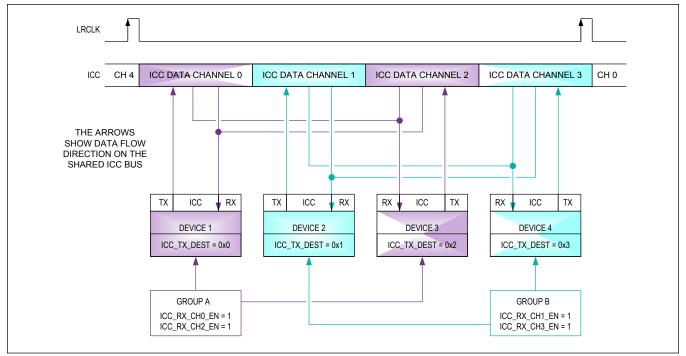


Figure 30. ICC Multigroup Example with Two Groups and Four Total Devices

ICC Over PCM Output (DOUT)

In non-HDI PCB layouts, an ICC pin may not be available for routing due to the location of the pin on an internal bump. In such systems, ICC functionality can be enabled by using the DOUT pin and the shared PCM bus. ICC over DOUT is enabled when ICC_OVER_DOUT_EN and ICC_LINK_EN are both set to 1. When it is enabled, the DOUT pin carries all supported PCM data output types as well as ICC data.

The device uses information in the PCM_ICC_SLOT bit field to select the starting location of the ICC to transmit data and uses ICC_RX_CHn_EN to identify the channels to monitor data from other devices in its group. In TDM format mode with 24-bit or 32-bit PCM data widths, each PCM_ICC_SLOT setting selects 3 PCM 8-bit slots to transmit all 23 bits of ICC data.

In TDM format mode with 16-bit PCM data width, all 23 bits of ICC data can be interleaved by setting ICC_INTERLEAVE_MODE to 1. In this case, BPE and DHT ICC data is sent in the first frame, and BPE and Thermal ICC data is sent in the next frame. The BPE and DHT ICC data frame is indicated by setting MSB to 0 in the ICC transmit data slot, whereas BPE and thermal ICC data frame is indicated by setting MSB to 1 in the ICC transmit data slot. If ICC_DATA_SEL is set to select either BPE+DHT or BPE+Therm data to be sent on ICC, it is not required to use interleave mode.

In I²S/LJ format mode with 24-bit or 32-bit PCM data widths and IV_{SENSE} disabled and ICC transmit data from each device on the bus will occupy each channel. With 16-bit PCM data width, ICC over DOUT with all 23 bits of ICC data, works in ICC interleave mode only (ICC INTERLEAVE MODE to be set to 1). In interleave mode, BPE and DHT ICC data frame are indicated by setting MSB to 0 in the ICC transmit data slot, whereas BPE and thermal ICC data frame is indicated by setting MSB to 1 in the ICC transmit data slot. If ICC DATA SEL is set to select either BPE+DHT or BPE+Therm data to be sent on ICC, it is not required to use interleave mode.

In I²S/LJ format mode with IV_{SENSE} enabled, ICC over DOUT works with 32-bit PCM data width only and requires ICC_INTERLEAVE_MODE to be set to 1. Since ICC data shares the slot with IV data, PCM_ICC_SLOT must be set to the same setting as PCM_VMON_SLOT. In interleave mode, BPE and DHT ICC data frame are indicated by setting MSB to 0 in the ICC transmit data slot, whereas BPE and thermal ICC data frame is indicated by setting MSB to 1 in the ICC transmit data slot.

I²C Serial Interface

Peripheral Address

The peripheral address is defined as the seven most significant bits (MSBs) followed by the read/write bit. The seven most significant bits are programmable through the ADDR1 and ADDR2 connection as shown in <u>Table 11</u>. The device does not communicate if ADDR1 and ADDR2 are floating. Setting the read/write bit to 1 configures the device for read mode. Setting the read/write bit to 0 configures the device for write mode. The address is the first byte of information sent to the IC after the START condition.

Table 11. I²C Peripheral Address

ADDR1 CONNECTION	ADDR2 CONNECTION	I ² C PERIPHERAL ADDRESS (BINARY)	I ² C WRITE ADDRESS (BINARY)	I ² C READ ADDRESS (BINARY)
Connected to DVDD	Connected to AGND	0111000x	01110000	01110001
Connected to DGND	Connected to AGND	0111001x	01110010	01110011
Connected to SDA	Connected to AGND	0111010x	01110100	01110101
Connected to SCL	Connected to AGND	0111011x	01110110	01110111
Connected to DVDD	Connected to DVDD	0111100x	01111000	01111001
Connected to DGND	Connected to DVDD	0111101x	01111010	01111011
Connected to SDA	Connected to DVDD	0111110x	01111100	01111101
Connected to SCL	Connected to DVDD	0111111x	01111110	01111111

The IC features an I 2 C/SMBus-compatible, 2-wire serial interface consisting of a serial data line (SDA) and a serial clock line (SCL). SDA and SCL facilitate communication between the IC and the controller at clock rates up to 1MHz. Figure 31 shows the 2-wire interface timing diagram. The controller generates SCL and initiates a data transfer on the bus. The controller device writes data to the IC by transmitting the proper peripheral address followed by two register address bytes (the most significant byte first) and then the data word. Each transmit sequence is framed by a START (S) or REPEATED START (Sr) condition and a STOP (P) condition. Each word transmitted to the IC is 8 bits long and is followed by an acknowledge clock pulse. A controller reading data from the IC transmits the proper peripheral address followed by a series of nine SCL pulses. The IC transmits data on SDA in sync with the controller-generated SCL pulses. The controller acknowledges receipt of each byte of data. Each read sequence is framed by a START (S) or REPEATED START (Sr) condition, a not acknowledge, and a STOP (P) condition. SDA operates as both an input and an open-drain output. A pullup resistor, typically greater than 500 Ω , is required on SCL if there are multiple controllers on the bus, or if the single controller has an open-drain SCL output. Series resistors in line with SDA and SCL are optional. Series resistors protect the digital inputs of the IC from high voltage spikes on the bus lines, and minimize crosstalk and undershoot of the bus signals.

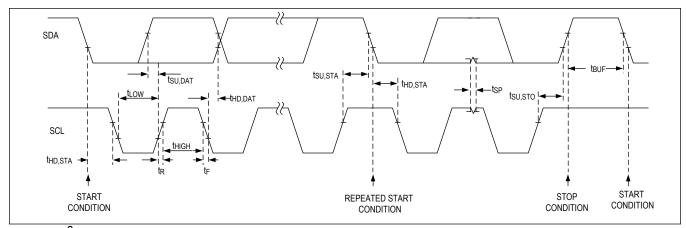


Figure 31. I²C Interface Timing Diagram

Bit Transfer

One data bit is transferred during each SCL cycle. The data on SDA must remain stable during the high period of the SCL pulse. Changes in SDA, while SCL is high, are control signals (see the *START and STOP Conditions* section).

START and STOP Conditions

SDA and SCL idle high when the bus is not in use. A controller initiates communication by issuing a START condition. A START condition is a high-to-low transition on SDA with SCL high. A STOP condition is a low-to-high transition on SDA while SCL is high. A START condition from the controller signals the beginning of a transmission to the IC. The controller terminates transmission, and frees the bus, by issuing a STOP condition. The bus remains active if a REPEATED START condition is generated instead of a STOP condition.

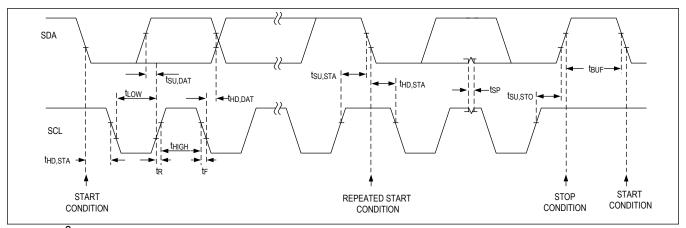


Figure 32. I²C START, STOP, and REPEATED START Conditions

Early STOP Conditions

The IC recognizes a STOP condition at any point during data transmission except if the STOP condition occurs in the same high pulse as a START condition. For proper operation, do not send a STOP condition during the same SCL high pulse as the START condition.

Acknowledge

The acknowledge bit (ACK) is a clocked 9th bit that the IC uses to handshake receipt each byte of data when in write mode. The IC pulls down SDA during the entire controller-generated 9th clock pulse if the previous byte is successfully received. Monitoring ACK allows for the detection of unsuccessful data transfers. An unsuccessful data transfer occurs if a receiving device is busy or if a system fault has occurred. In the event of an unsuccessful data transfer, the bus controller retries communication. The controller pulls down SDA during the 9th clock cycle to acknowledge receipt of data when the IC is in read mode. An acknowledge is sent by the controller after each read byte to allow data transfer to continue. A not-acknowledge is sent when the controller reads the final byte of data from the IC, followed by a STOP condition.

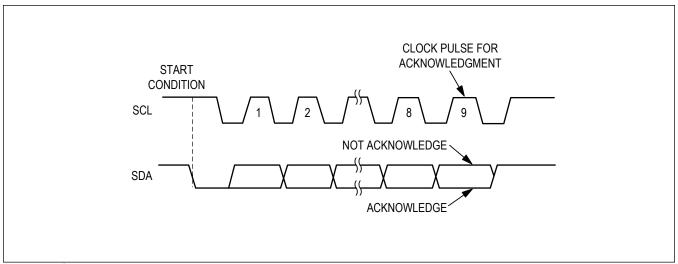


Figure 33. I²C Acknowledge

Write Data Format

A write to the IC includes the transmission of a START condition, the peripheral address with the R/W bit set to 0, two bytes of data to configure the internal register address pointer, one or more bytes of data, and a STOP condition.

The peripheral address with the R/\overline{W} bit set to 0 indicates that the controller intends to write data to the IC. The IC acknowledges receipt of the address byte during the controller-generated 9th SCL pulse.

The second and third bytes transmitted from the controller configure the ICs internal register address pointer. The pointer tells the IC where to write the next byte of data. An acknowledge pulse is sent by the IC upon receipt of the address pointer data.

The third byte sent to the IC contains the data that is written to the chosen register. An acknowledge pulse from the IC signals receipt of the data byte. The address pointer auto increments to the next register address after each received data byte. This auto-increment feature allows a controller to write to sequential registers within one continuous frame. The controller signals the end of transmission by issuing a STOP condition.

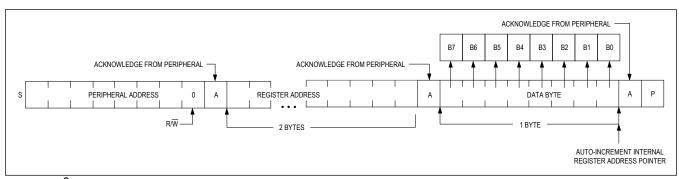


Figure 34. I²C Writing One Byte of Data to the Peripheral

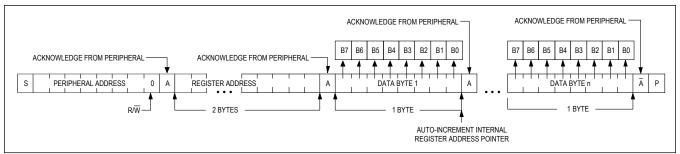


Figure 35. I²C Writing n-Bytes of Data to the Peripheral

Read Data Format

The I^2C register address pointer must be preset to a specific target register address before a read command is issued. The controller presets the peripheral register address pointer by first sending the device's peripheral address with the R/W bit set to 0 (write command) followed by two commands containing the target register address for the address pointer.

A REPEATED START condition is then sent followed by the read command (peripheral address with the R/W bit set to 1). This begins a read command with the internal register address pointer set to the target register address. The first byte transmitted from the device contains the contents of the register that the address pointer is set to. Transmitted data is valid on the rising edge of SCL. The controller acknowledges (ACK) receipt of each read byte during the acknowledge clock pulse. The address pointer then auto-increments after each acknowledged read data byte. This auto-increment feature allows multiple registers to be read sequentially within one continuous frame.

The controller must issue an acknowledge (ACK) for all correctly received bytes except the last byte. To terminate the read operation, the final byte must be followed by a not acknowledge (NACK) from the controller and then a STOP condition. A not-acknowledge (NACK) followed by a STOP condition can be issued after any number of read data bytes.

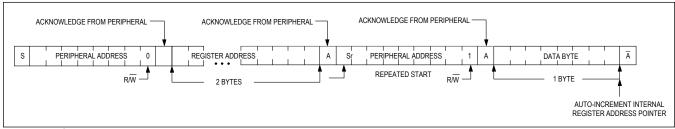


Figure 36. I²C Controller Reading One Byte of Data from the Peripheral

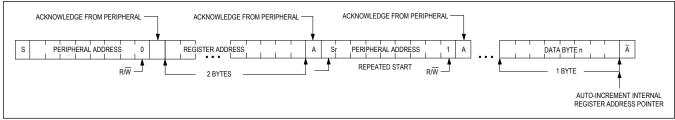


Figure 37. I²C Controller Reading n-Bytes of Data from the Peripheral

I²C Register Map

Control Bit Field Types and Write Access Restrictions

The device control bit fields fall into one of three basic types: read, write, or read and write. There are no read restrictions, and any read-enabled bit field can be read back anytime the I²C control interface is active. There are however write restrictions, and every write-enabled bit field falls into one of two write access subtypes.

The first write access subtype is dynamic. Dynamic bit fields effectively have no write access restrictions and can be safely changed (written) in any device state where the I²C control interface is active. The second bit field access subtype is restricted. Restricted bit fields should only be changed (written) when the related functional block (as shown in <u>Table 12</u>) is powered down.

If the write access is restricted to the global enable (restrictions EN and ENL), then the restricted bit field should only be changed (written) when the device is in software shutdown. As a form of system protection, write access to some critical global enable restricted bit fields (ENL) is locked out by the hardware when the device is not in the software-shutdown state. Attempting to change (write to) these locked restricted bit fields when the device is not in the software-shutdown state has no effect (read-access is still allowed).

The bit field type and write access subtype are provided for every bit field in the detailed register description tables. For all bit fields with the restricted subtype, the dependency is also denoted in the "RES" column.

<u>Table 12</u> provides a detailed description of all device register types, access subtypes, and restriction dependencies that are used by this device. The write access restrictions describe the specific device condition(s) that should be met (and the corresponding bit field settings) before the system attempts to change (write to) bit fields with that restriction type.

Table 12. Control Bit Types and Write Access Restrictions

BIT FIELD	WRITE	WRITE ACCESS RESTRICTIO	NS	"RES"
TYPE	ACCESS	DESCRIPTION	CONDITION	SYMBOL
Read	Read Only	_	_	_
	Dynamic	_	_	_
		Device in Software Shutdown	EN = 0	EN
		Write Access Locked Out by Hardware Unless the Device is in Software Shutdown	EN = 0	ENL
		Speaker Amplifier Output and Feedback Disabled	SPK_EN = 0 and SPK_FB_EN = 0	SPK
		Voltage and Current Sense ADCs Disabled	IVADC_V_EN = 0 and IVADC_I_EN = 0	IVS
Write		Thermal Foldback Disabled	THERMFB_EN = 0	TFB
or Read/Write	Restricted	Noise Gate Disabled	NOISEGATE_EN = 0	NG
		Dynamic Headroom Tracking Disabled	DHT_EN = 0	DHT
		Brownout Protection Engine Disabled	BPE_EN = 0	BPE
		PCM Interface Data Input and Output Disabled	PCM_RX_EN = 0 and PCM_TX_EN = 0	PCM
		PCM Data Output Disabled	PCM_TX_EN = 0	TXEN
		IRQ Bus Output Disabled	IRQ_EN = 0	IRQ
		Interchip Communication (ICC) Interface Disabled	ICC_LINK_EN = 0 and ICC_TX_EN = 0	ICC

Register Map

Register Map

ADDRESS	NAME	MSB							LSB
Reset									
0x2000	Software Reset[7:0]	_	_	_	_	_	_	_	RST
Interrupts				l		l		l	
0x2001	Interrupt Raw 1[7:0]	THERM SHDN_B GN_RA W	THERM SHDN_E ND_RA W	THERM WARN1_ BGN_RA W	THERM WARN1_ END_RA W	THERMF B_BGN_ RAW	THERMF B_END_ RAW	OTP_FAI L_RAW	SPK_OV C_RAW
0x2002	Interrupt Raw 2[7:0]	THERM WARN2_ BGN_RA W	THERM WARN2_ END_RA W	INT_SPK MON_E RR_RA W	INT_CLK _ERR_R AW	-	CLK_RE COVER_ RAW	CLK_ER R_RAW	DMON_ ERR_RA W
0x2003	Interrupt Raw 3[7:0]	AVDD_U VLO_RA W	DVDD_U VLO_RA W	PWRUP _DONE_ RAW	PWRDN _DONE_ RAW	PVDD_U VLO_SH DN_RA W	VBAT_U VLO_SH DN_RA W	DHT_AC TIVE_B GN_RA W	DHT_AC TIVE_EN D_RAW
0x2004	Interrupt Raw 4[7:0]	_	_	_	_	BPE_L0 _RAW	BPE_LE VEL_RA W	BPE_AC TIVE_B GN_RA W	BPE_AC TIVE_EN D_RAW
0x2006	Interrupt State 1[7:0]	THERM SHDN_B GN_STA TE	THERM SHDN_E ND_STA TE	THERM WARN1_ BGN_ST ATE	THERM WARN1_ END_ST ATE	THERMF B_BGN_ STATE	THERMF B_END_ STATE	OTP_FAI L_STAT E	SPK_OV C_STAT E
0x2007	Interrupt State 2[7:0]	THERM WARN2_ BGN_ST ATE	THERM WARN2_ END_ST ATE	INT_SPK MON_E RR_STA TE	INT_CLK _ERR_S TATE	_	CLK_RE COVER_ STATE	CLK_ER R_STAT E	DMON_ ERR_ST ATE
0x2008	Interrupt State 3[7:0]	AVDD_U VLO_ST ATE	DVDD_U VLO_ST ATE	PWRUP _DONE_ STATE	PWRDN _DONE_ STATE	PVDD_U VLO_SH DN_STA TE	VBAT_U VLO_SH DN_STA TE	DHT_AC TIVE_B GN_STA TE	DHT_AC TIVE_EN D_STAT E
0x2009	Interrupt State 4[7:0]	_	_	-	_	BPE_L0 _STATE	BPE_LE VEL_ST ATE	BPE_AC TIVE_B GN_STA TE	BPE_AC TIVE_EN D_STAT E
0x200B	Interrupt Flag 1[7:0]	THERM SHDN_B GN_FLA G	THERM SHDN_E ND_FLA G	THERM WARN1_ BGN_FL AG	THERM WARN1_ END_FL AG	THERMF B_BGN_ FLAG	THERMF B_END_ FLAG	OTP_FAI L_FLAG	SPK_OV C_FLAG
0x200C	Interrupt Flag 2[7:0]	THERM WARN2_ BGN_FL AG	THERM WARN2_ END_FL AG	INT_SPK MON_E RR_FLA G	INT_CLK _ERR_F LAG	_	CLK_RE COVER_ FLAG	CLK_ER R_FLAG	DMON_ ERR_FL AG
0x200D	Interrupt Flag 3[7:0]	AVDD_U VLO_FL AG	DVDD_U VLO_FL AG	PWRUP _DONE_ FLAG	PWRDN _DONE_ FLAG	PVDD_U VLO_SH DN_FLA G	VBAT_U VLO_SH DN_FLA G	DHT_AC TIVE_B GN_FLA G	DHT_AC TIVE_EN D_FLAG

ADDRESS	NAME	MSB							LSB
0x200E	Interrupt Flag 4[7:0]	-	_	-	_	BPE_L0 _FLAG	BPE_LE VEL_FL AG	BPE_AC TIVE_B GN_FLA G	BPE_AC TIVE_EN D_FLAG
0x2010	Interrupt Enable 1[7:0]	THERM SHDN_B GN_EN	THERM SHDN_E ND_EN	THERM WARN1_ BGN_EN	THERM WARN1_ END_EN	THERMF B_BGN_ EN	THERMF B_END_ EN	OTP_FAI L_EN	SPK_OV C_EN
0x2011	Interrupt Enable 2[7:0]	THERM WARN2_ BGN_EN	THERM WARN2_ END_EN	INT_SPK MON_E RR_EN	INT_CLK _ERR_E N	-	CLK_RE COVER_ EN	CLK_ER R_EN	DMON_ ERR_EN
0x2012	Interrupt Enable 3[7:0]	AVDD_U VLO_EN	DVDD_U VLO_EN	PWRUP _DONE_ EN	PWRDN _DONE_ EN	PVDD_U VLO_SH DN_EN	VBAT_U VLO_SH DN_EN	DHT_AC TIVE_B GN_EN	DHT_AC TIVE_EN D_EN
0x2013	Interrupt Enable 4[7:0]	_	_	-	_	BPE_L0 _EN	BPE_LE VEL_EN	BPE_AC TIVE_B GN_EN	BPE_AC TIVE_EN D_EN
0x2015	Interrupt Flag Clear 1[7:0]	THERM SHDN_B GN_CLR	THERM SHDN_E ND_CLR	THERM WARN1_ BGN_CL R	THERM WARN1_ END_CL R	THERMF B_BGN_ CLR	THERMF B_END_ CLR	OTP_FAI L_CLR	SPK_OV C_CLR
0x2016	Interrupt Flag Clear 2[7:0]	THERM WARN2_ BGN_CL R	THERM WARN2_ END_CL R	INT_SPK MON_E RR_CLR	INT_CLK _ERR_C _LR	_	CLK_RE COVER_ CLR	CLK_ER R_CLR	DMON_ ERR_CL R
0x2017	Interrupt Flag Clear 3[7:0]	AVDD_U VLO_CL R	DVDD_U VLO_CL R	PWRUP _DONE_ CLR	PWRDN _DONE_ CLR	PVDD_U VLO_SH DN_CLR	VBAT_U VLO_SH DN_CLR	DHT_AC TIVE_B GN_CLR	DHT_AC TIVE_EN D_CLR
0x2018	Interrupt Flag Clear 4[7:0]	-	-	-	-	BPE_L0 _CLR	BPE_LE VEL_CL R	BPE_AC TIVE_B GN_CLR	BPE_AC TIVE_EN D_CLR
0x201F	IRQ Control[7:0]	_	_	_	_	_	IRQ_MO DE	IRQ_PO L	IRQ_EN
Thermal Pr	otection								
0x2020	Thermal Warning Threshhold[7:0]	_			THERMW	/ARN1_THF	RESH[6:0]		
0x2021	Warning Threshold 2[7:0]	_			THERMW	/ARN2_THF	RESH[6:0]		
0x2022	Thermal Shutdown Threshold[7:0]	-			THERMS	SHDN_THR	ESH[6:0]		
0x2023	Thermal Hysteresis[7:0]	_	_	_	_	_	_	THERM_I	HYST[1:0]
0x2024	Thermal Foldback Settings[7:0]		B_HOLD[1:]	THERMFE	B_RLS[1:0]		3_SLOPE2 :0]	THERMFE [1	
0x2027	Thermal Foldback Enable[7:0]	THE						THERMF B_EN	
Noise Gate	and Idle Mode	1	1	1	1	1	1	1	
0x2030	Noise Gate/Idle Mode Control[7:0]	NG_UNMUTE_THRESH[3:0] NG_MUTE_THRESH[3:0])]		
0x2033	Noise Gate/Idle Mode Enables[7:0]	_	_	_	_	-	_	IDLE_M ODE_EN	NOISEG ATE_EN

ADDRESS	NAME	MSB							LSB
Clock and I	Data Monitor Control			•					
0x2038	Clock Monitor Control[7:0]	-	СМО	N_BSELTO	L[2:0]	СМС	N_ERRTO	L[2:0]	CMON_ AUTORE START_ EN
0x2039	Data Monitor Control[7:0]	-	-		AG_THRE 1:0]		TUCK_TH [1:0]		URATION[0]
0x203A	Speaker Monitor Threshold[7:0]	-	_	_	_	:	SPKMON_T	HRESH[3:0]
0x203F	Enable Controls[7:0]	-	_	_	_	SPKMO N_EN	DMON_ MAG_E N	DMON_ STUCK_ EN	CMON_ EN
PCM Regis	ters		•	•			•	•	•
0x2040	Pin Config[7:0]	LV_EN_I	DRV[1:0]	ICC_D	RV[1:0]	IRQ_D	RV[1:0]	DOUT_I	DRV[1:0]
0x2041	PCM Mode Config[7:0]	PCM_CH	ANSZ[1:0]	PCN	M_FORMAT	[2:0]	PCM_TX _INTERL EAVE	PCM_C HANSEL	PCM_TX _EXTRA _HIZ
0x2042	PCM Clock Setup[7:0]	_	_	_	PCM_BC LKEDGE				
0x2043	PCM Sample Rate Setup 1[7:0]		IVADC_	_SR[3:0]			PCM_	SR[3:0]	
0x2044	PCM TX Control 1[7:0]	ı	_		I	PCM_VMO	N_SLOT[5:0]	
0x2045	PCM TX Control 2[7:0]	_	_	PCM_IMON_SLOT[5:0]					
0x2046	PCM TX Control 3[7:0]	ı	-	PCM_SUPPLY1_SLOT[5:0]					
0x2047	PCM TX Control 4[7:0]	_	_		P	CM_SUPPL	Y2_SLOT[5	:0]	
0x2048	PCM TX Control 5[7:0]	_	_			CM_DHT_A			
0x2049	PCM TX Control 6[7:0]	-	_			CM_STATL			
0x204A	PCM TX Control 7[7:0]	_	_		PCM	_DSP_MON		T[5:0]	
0x204B	PCM TX Control 8[7:0]	_	_				_SLOT[5:0]		
0x204C	PCM TX Control 9[7:0]	-	_		F	CM_THER		0]	
0x204D	PCM TX Control 10[7:0]	-	_			PCM_ICC_	_SLOT[5:0]		
0x204E	PCM Tx HiZ Control 1[7:0]			P	CM_TX_SLO	DT_HIZ[63:	56]		
0x204F	PCM Tx HiZ Control 2[7:0]			P	CM_TX_SLO	OT_HIZ[55:4	18]		
0x2050	PCM Tx HiZ Control 3[7:0]			P	CM_TX_SLC	OT_HIZ[47:4	10]		
0x2051	PCM Tx HiZ Control 4[7:0]			P	CM_TX_SLC	OT_HIZ[39:3	32]		
0x2052	PCM Tx HiZ Control 5[7:0]	PCM_TX_SLOT_HIZ[31:24]							
0x2053	PCM Tx HiZ Control 6[7:0]	PCM_TX_SLOT_HIZ[23:16]							
0x2054	PCM Tx HiZ Control 7[7:0]	PCM_TX_SLOT_HIZ[15:8]							
0x2055	PCM Tx HiZ Control 8[7:0]	PCM_TX_SLOT_HIZ[7:0]							

ADDRESS	NAME	MSB							LSB
0x2057	PCM RX Source 1[7:0]	_	_	_	_	_	_		MIX_CFG[0]
0x2058	PCM RX Source 2[7:0]	PCM_	DMMIX_CI	H1_SOURC	E[3:0]	PCM_DMMIX_CH0_SOURCE[3:0]			
0x2059	PCM Bypass Source[7:0]	_	_	_	_	PCI	PCM_BYPASS_SOURCE[3:0]		
0x205C	PCM TX Source Enables[7:0]	PCM_BP E_EN	PCM_ST ATUS_E N	PCM_D HT_ATN _EN	PCM_SU PPLY2_ EN	PCM_SU PPLY1_ EN	PCM_DS PMONIT OR_EN	PCM_IM ON_EN	PCM_V MON_E N
0x205D	PCM TX Source Enables 2[7:0]	_	_	_	_	_	_	_	PCM_TH ERM_EN
0x205E	PCM Rx Enables[7:0]	_	-	_	-	_	_	PCM_BY P_EN	PCM_RX _EN
0x205F	PCM Tx Enables[7:0]	_	_	_	_	_	_	_	PCM_TX _EN
0x2060	PCM Tx Supply Select[7:0]	_	_	_	_	_	_		SELECT[1)]
Interchip Co	ommunication								
0x2070	ICC Rx Enables A[7:0]	ICC_RX _CH7_E N	ICC_RX _CH6_E N	ICC_RX _CH5_E N	ICC_RX _CH4_E N	ICC_RX _CH3_E N	ICC_RX _CH2_E N	ICC_RX _CH1_E N	ICC_RX _CH0_E N
0x2071	ICC Rx Enables B[7:0]	ICC_RX _CH15_ EN	ICC_RX _CH14_ EN	ICC_RX _CH13_ EN	ICC_RX _CH12_ EN	ICC_RX _CH11_ EN	ICC_RX _CH10_ EN	ICC_RX _CH9_E N	ICC_RX _CH8_E N
0x2072	ICC Tx Control[7:0]	_	ICC_INT ERLEAV E_MOD E	ICC_DA TA_SEL	_	ICC_TX_DEST[3:0]			
0x207F	ICC Enables[7:0]	_	_	_	_	_	ICC_OV ER_DOU T_EN	ICC_LIN K_EN	ICC_TX_ EN
Tone Gener	rator Control								
0x2083	Tone Generator and DC Config[7:0]	_	_		MPLITUDE[:0]		TONE_CO	ONFIG[3:0]	
0x2084	Tone Generator DC Level 1[7:0]				TONE_D	C[23:16]			
0x2085	Tone Generator DC Level 2[7:0]				TONE_I	DC[15:8]			
0x2086	Tone Generator DC Level 3[7:0]				TONE_	DC[7:0]			
0x208F	Tone Generator Enable[7:0]	_	_	_	_	- PINK_N OISE_E N			
Speaker Pa	th Control								
0x2090	AMP volume control[7:0]	SPK_VOL[7:0]							
0x2091	AMP Path Gain[7:0]	-	_	_		SPK_GAIN_MAX[4:0]			
0x2092	AMP DSP Config[7:0]	_	SPK_WB AND_FIL T_EN	SPK_SA FE_EN	SPK_VO L_RMPD N_BYPA SS	SPK_VO L_RMPU P_BYPA SS	SPK_IN VERT	SPK_DIT H_EN	SPK_DC BLK_EN

ADDRESS	NAME	MSB							LSB	
0x2093	SSM Configuration[7:0]	_	_	-	_	TRI_SS M_EN	_	TRI_SSM_	_MOD[1:0]	
0x2094	SPK Class DG Threshold[7:0]	-	_	_		SPK_	SPK_DG_THRES[4:0]			
0x2095	SPK Class DG Headroom[7:0]	_	_	SPK_DG	_SEL[1:0]	SF	PK_DG_HE	ADROOM[3	:0]	
0x2096	SPK Class DG Hold Time[7:0]	_	SPK_D	G_PEAK_H	YST[2:0]	SI	PK_DG_HO	LD_TIME[3	:0]	
0x2097	SPK Class DG Delay[7:0]	_	_			SPK_DG_I	DELAY[5:0]			
0x2098	SPK Class DG Mode[7:0]	_	_	_	_	_	_	SPK_M	DDE[1:0]	
0x2099	SPK Class DG VBAT Level[7:0]	_	_	_	_	_	VBATI	_OW_OK_L	VL[2:0]	
0x209A	SPK Edge Control[7:0]	_	_	_	_	-	TRI_FS W2X_M ODE	_	П	
0x209B	SPK Path Wideband Only Enable[7:0]	_	_	_	_	_	_	_	SPK_WI DEBAND _ONLY_ EN	
0x209C	SPK Edge Control 1[7:0]	SPK_EN _TURNO FF_SLE W	-	-	_	SPK_SL_RATE_GMODE[3:0]			3:0]	
0x209D	SPK Edge Control 2[7:0]	,	SPK_SL_R	ATE_LS[3:0]	,	SPK_SL_RA	ATE_HS[3:0]	
0x209E	Amp Clip Gain[7:0]	-	_	_	_		SPK_G	AIN[3:0]		
0x209F	Bypass Path Config[7:0]	_	_	_	_	_	_	BYP_WB AND_FIL T_EN	BYP_IN VERT	
0x20AF	AMP enables[7:0]	_	_	_	_	_	_	SPK_FB _EN	SPK_EN	
Meas ADC			•					•		
0x20B0	Meas ADC Sample Rate[7:0]	MEAS_AI	DC_VDDH [1:0]		DC_TEMP [1:0]		DC_PVDD [1:0]	MEAS_AD		
0x20B1	Meas ADC PVDD Config[7:0]	_	_	_	MEAS_A DC_PVD D_FILT_ EN	MEAS_	ADC_PVDE	D_FILT_COE	EFF[3:0]	
0x20B2	Meas ADC VBAT Config[7:0]	-	_	-	MEAS_A DC_VBA T_FILT_ EN	MEAS_	ADC_VBAT	_FILT_COE	EFF[3:0]	
0x20B3	Meas ADC Thermal Config[7:0]	-	-	-	MEAS_A DC_TEM P_FILT_ EN	MEAS_	ADC_TEMF	P_FILT_COE	EFF[3:0]	
0x20B4	Meas ADC VDDH Config[7:0]	-	_	-	MEAS_A DC_VDD H_FILT_ EN	MEAS_	ADC_VDDH	H_FILT_CO	EFF[3:0]	

ADDRESS	NAME	MSB							LSB
0x20B5	Meas ADC Readback Control 1[7:0]	-	-	-	-	MEAS_A DC_VDD H_RD_M ODE	MEAS_A DC_THE RM_RD_ MODE	MEAS_A DC_VBA T_RD_M ODE	MEAS_A DC_PVD D_RD_M ODE
0x20B6	Meas ADC Readback Control 2[7:0]	_	_	-	_	MEAS_A DC_VDD H_RD_U PD	MEAS_A DC_THE RM_RD_ UPD	MEAS_A DC_VBA T_RD_U PD	MEAS_A DC_PVD D_RD_U PD
0x20B7	Meas ADC PVDD Readback MSB[7:0]			ME	AS_ADC_P	VDD_DATA	[8:1]		
0x20B8	Meas ADC PVDD Readback LSB[7:0]	_	_	_	-	_	_	_	MEAS_A DC_PVD D_DATA [0]
0x20B9	Meas ADC VBAT Readback MSB[7:0]	MEAS_ADC_VBAT_DATA[8:1]							
0x20BA	Meas ADC VBAT Readback LSB[7:0]	_	_	_	-	_	_	_	MEAS_A DC_VBA T_DATA[0]
0x20BB	Meas ADC Temp Readback MSB[7:0]	MEAS_ADC_THERM_DATA[8:1]							
0x20BC	Meas ADC Temp Readback LSB[7:0]	_	_	_	_	_	_	_	MEAS_A DC_THE RM_DAT A[0]
0x20BD	Meas ADC VDDH Readback MSB[7:0]			ME	AS_ADC_V	DDH_DATA	[8:1]		
0x20BE	Meas ADC VDDH Readback LSB[7:0]	_	_	_	-	-	_	_	MEAS_A DC_VDD H_DATA [0]
0x20BF	Meas ADC Lowest PVDD Readback MSB[7:0]			LC	WEST_PV	DD_DATA[8	:1]		
0x20C0	Meas ADC Lowest PVDD Readback LSB[7:0]	_	_	_	_	_	_	_	LOWES T_PVDD _DATA[0]
0x20C1	Meas ADC Lowest VBAT Readback MSB[7:0]			LC	OWEST_VB	AT_DATA[8	:1]		
0x20C2	Meas ADC Lowest VBAT Readback LSB[7:0]	_	_	_	_	_	_	_	LOWES T_VBAT _DATA[0]
0x20C3	Meas ADC Lowest VDDH Readback MSB[7:0]	LOWEST_VDDH_DATA[8:1]							
0x20C4	Meas ADC Lowest VDDH Readback LSB[7:0]	_	_	_	_	_	_	_	LOWES T_VDDH _DATA[0]

ADDRESS	NAME	MSB							LSB
0x20C5	Meas ADC Highest Thermal Readback MSB[7:0]			HIGHE	ST_THERN	M_DATA_M	SB[7:0]		
0x20C6	Meas ADC Highest Thermal Readback LSB[7:0]	-	_	_	_	_	_	_	HIGHES T_THER M_DATA _LSB
0x20C7	Meas ADC Optimal Mode[7:0]	-	-	-	_	MEAS_AD VE_SI	C_OPT_A EL[1:0]	MEAS_AI MOD	DC_OPT_ E[1:0]
0x20C8	Meas ADC Config[7:0]	_	_	-	_	_	MEAS_A DC_VDD H_EN	MEAS_A DC_VBA T_EN	MEAS_A DC_PVD D_EN
Dynamic He	eadroom Tracking								
0x20D0	DHT Configuration 1[7:0]	_	_	_	_		DHT_VRO	T_PNT[3:0]	
0x20D1	Limiter Configuration 1[7:0]	_	_	_		[OHT_HR[4:0)]	
0x20D2	Limiter Configuration 2[7:0]	_	_		DHT_	LIM_THRES	SH[4:0]		DHT_LI M_MOD E
0x20D3	DHT Configuration 2[7:0]	_	_	_		DHT	_MAX_ATN	I[4:0]	
0x20D4	DHT Configuration 3[7:0]	-	-	-	_		DHT_ATK	_RATE[3:0]	
0x20D5	DHT Configuration 4[7:0]	_	_	_	_		DHT_RLS	_RATE[3:0]	
0x20D6	DHT Supply Hysteresis Configuration[7:0]	_	_	_	_	DHT_S	UPPLY_HY	'ST[2:0]	DHT_SU PPLY_H YST_EN
0x20DF	DHT Enable[7:0]	_	_	_	_	-	_	_	DHT_EN
I_V Sense F	Path Control								
0x20E0	L_V Sense Path Config[7:0]	_	_	_	_	IVADC_ WBAND _FILT_E N	IVADC_ DITH_E N	IVADC_I _DCBLK _EN	IVADC_ V_DCBL K_EN
0x20E4	I_V Sense Path Enables[7:0]	-	-	-	_	_	IVADC_I M_EN	IVADC_I _EN	IVADC_ V_EN
Brownout F	Protection Engine	•	•	•				•	
0x20E5	BPE State[7:0]	_	_	_	_	_	BF	PE_STATE[2	2:0]
0x20E6	BPE L3 Threshold MSB[7:0]				BPE_L3_V1	THRESH[8:1]		
0x20E7	BPE L3 Threshold LSB[7:0]	-	-	-	-	_	_	-	BPE_L3 _VTHRE SH[0]
0x20E8	BPE L2 Threshold MSB[7:0]	BPE_L2_VTHRESH[8:1]							
0x20E9	BPE L2 Threshold LSB[7:0]	_	_	_	_	_	_	_	BPE_L2 _VTHRE SH[0]

ADDRESS	NAME	MSB							LSB
0x20EA	BPE L1 Threshold MSB[7:0]			į.	BPE_L1_VT	HRESH[8:1]	1	
0x20EB	BPE L1 Threshold LSB[7:0]	-	_	-	_	_	_	-	BPE_L1 _VTHRE SH[0]
0x20EC	BPE L0 Threshold MSB[7:0]			E	BPE_L0_VT	HRESH[8:1]		
0x20ED	BPE L0 Threshold LSB[7:0]	-	_	-	_	_	_	-	BPE_L0 _VTHRE SH[0]
0x20EE	BPE L3 Dwell and Hold Time[7:0]	_	_	BPE_	_L3_DWELI	L[2:0]	BPE	_L3_HOLD	[2:0]
0x20EF	BPE L2 Dwell and Hold Time[7:0]	_	_	BPE_	_L2_DWELI	L[2:0]	BPE	_L2_HOLD	[2:0]
0x20F0	BPE L1 Dwell and Hold Time[7:0]	_	_	BPE _.	_L1_DWELI	L[2:0]	BPE	_L1_HOLD	[2:0]
0x20F1	BPE L0 Hold Time[7:0]	_	_	_	_	_	BPE	_L0_HOLD	[2:0]
0x20F2	BPE L3 Attack and Release Step[7:0]	_	_	_	_		BPE_L3_	STEP[3:0]	
0x20F3	BPE L2 Attack and Release Step[7:0]	_	_	_	_		BPE_L2_STEP[3:0]		
0x20F4	BPE L1 Attack and Release Step[7:0]	_	_	_	_		BPE_L1_	STEP[3:0]	
0x20F5	BPE L0 Attack and Release Step[7:0]	_	_	_	_		BPE_L0_	STEP[3:0]	
0x20F6	BPE L3 Max Gain Attn[7:0]	_	_	_		BPE_l	_3_MAXATT	ΓN[4:0]	
0x20F7	BPE L2 Max Gain Attn[7:0]	_	_	_		BPE_l	_2_MAXATT	ΓN[4:0]	
0x20F8	BPE L1 Max Gain Attn[7:0]	_	_	_		BPE_l	_1_MAXATT	ΓN[4:0]	
0x20F9	BPE L0 Max Gain Attn[7:0]	_	_	_		BPE_l	_0_MAXATT	ΓN[4:0]	
0x20FA	BPE L3 Gain Attack and Rls Rates[7:0]	_	_	BPE_L	_3_GAIN_R	LS[2:0]	BPE_L	_3_GAIN_A	TK[2:0]
0x20FB	BPE L2 Gain Attack and Rls Rates[7:0]	-	_	BPE_L	_2_GAIN_R	LS[2:0]	BPE_L	_2_GAIN_A	TK[2:0]
0x20FC	BPE L1 Gain Attack and Rls Rates[7:0]	_	_	BPE_L	_1_GAIN_R	LS[2:0]	BPE_L	_1_GAIN_A	TK[2:0]
0x20FD	BPE L0 Gain Attack and Rls Rates[7:0]	_	_	BPE_L	.0_GAIN_RLS[2:0] BPE_L0_GAIN_ATK[2:0]			TK[2:0]	
0x20FE	BPE L3 Limiter Config[7:0]	_	_	_	- BPE_L3_LIM[3:0]				
0x20FF	BPE L2 Limiter Config[7:0]	-	_	_	- BPE_L2_LIM[3:0]				
0x2100	BPE L1 Limiter Config[7:0]	-	_	-	- BPE_L1_LIM[3:0]				
0x2101	BPE L0 Limiter Config[7:0]	-	_	_	- BPE_L0_LIM[3:0]				

ADDRESS	NAME	MSB							LSB	
0x2102	BPE L3 Limiter Attack and Release Rates[7:0]	_	_	BPE_	L3_LIM_RL	S[2:0]	BPE_	BPE_L3_LIM_ATK[2:0]		
0x2103	BPE L2 Limiter Attack and Release Rates[7:0]	_	_	BPE_	L2_LIM_RL	S[2:0]	BPE_	L2_LIM_AT	K[2:0]	
0x2104	BPE L1 Limiter Attack and Release Rates[7:0]	-	-	BPE_	L1_LIM_RL	S[2:0]	BPE_	L1_LIM_AT	K[2:0]	
0x2105	BPE L0 Limiter Attack and Release Rates[7:0]	_	_	BPE_	L0_LIM_RL	S[2:0]	BPE_	L0_LIM_AT	K[2:0]	
0x2106	BPE Threshold Hysteresis[7:0]			BF	PE_VTHRES	SH_HYST[7	:0]			
0x2107	BPE Infinite Hold Clear[7:0]	_	-	_	_	_	_	_	BPE_HL D_RLS	
0x2108	BPE Supply Source[7:0]	_	_	_	_	_	_	BPE_SRC	SEL[1:0]	
0x2109	BPE Lowest State[7:0]	_	_	_	_	-	BPE	_LOWEST	[2:0]	
0x210A	BPE Lowest Gain[7:0]			В	PE_LOWES	ST_GAIN[7:	0]			
0x210B	BPE Lowest Limiter[7:0]			В	PE_LOWES	ST_LIMIT[7:	0]			
0x210D	BPE Enable[7:0]	_	_	_	-	_	_	BPE_LI M_EN	BPE_EN	
System Cor	nfiguration									
0x210E	Auto-Restart Behavior[7:0]	_	_	_	-	OVC_AU TOREST ART_EN	THERM_ AUTORE START_ EN	VBAT_A UTORES TART_E N	PVDD_A UTORES TART_E N	
0x210F	Global Enable[7:0]	EN								
Device and	Revision ID						-			
0x22FF	Revision ID[7:0]	REV_ID[7:0]								

Register Details

Software Reset (0x2000)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	RST
Reset	_	-	-	-	-	-	_	0b0
Access Type	_	_	_	_	_	_	_	Write Only

BITFIELD	BITS	DESCRIPTION	DECODE
RST	0	This bit field is used to trigger a software reset event. Writing a 1 resets the device and returns the control registers to their power-on reset states. Writing a 0 has no effect, and readback always returns 0.	0: No action. 1: Triggers a software reset event.

Interrupt Raw 1 (0x2001)

BIT	7	6	5	4	3	2	1	0
Field	THERMSH DN_BGN_R AW	THERMSH DN_END_R AW	THERMWA RN1_BGN_ RAW	THERMWA RN1_END_ RAW	THERMFB_ BGN_RAW	THERMFB_ END_RAW	OTP_FAIL_ RAW	SPK_OVC_ RAW
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
THERMSHD N_BGN_RA W	7	Raw value of thermal shutdown begin indicator.	Die temperature below thermal shutdown limit. Die temperature above thermal shutdown limit.
THERMSHD N_END_RA W	6	Raw value of thermal shutdown end indicator.	Die temperature above thermal shutdown limit. Die temperature has dropped below thermal shutdown limit.
THERMWAR N1_BGN_RA W	5	Raw value of thermal-warning1 begin indicator.	Die temperature below thermal-warning1 limit. Die temperature above thermal- warning1 limit.
THERMWAR N1_END_RA W	4	Raw value of thermal-warning1 end indicator.	Die temperature above thermal-warning1 limit. Die temperature has dropped below thermalwarning1 limit.
THERMFB_B GN_RAW	3	Raw value of thermal foldback begin.	The thermal foldback is not active. Thermal foldback is active.
THERMFB_E ND_RAW	2	Raw value of thermal foldback end.	The thermal foldback is active. Thermal foldback has ended.
OTP_FAIL_R AW	1	Raw status of OTP load fail.	No OTP load failure. The OTP load routine did not complete succesfully.
SPK_OVC_R AW	0	Raw value of speaker overcurrent limit.	Speaker overcurrent limit inactive. Speaker overcurrent limit active.

Interrupt Raw 2 (0x2002)

BIT	7	6	5	4	3	2	1	0
Field	THERMWA RN2_BGN_ RAW	THERMWA RN2_END_ RAW	INT_SPKM ON_ERR_R AW	INT_CLK_E RR_RAW	_	CLK_RECO VER_RAW	CLK_ERR_ RAW	DMON_ER R_RAW
Reset	0b0	0b0	0b0	0x0	_	0x0	0x0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	_	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
THERMWAR N2_BGN_RA W	7	Raw value of thermal-warning2 begin indicator.	Die temperature below thermal-warning2 limit. Die temperature above thermal-warning2 limit.
THERMWAR N2_END_RA W	6	Raw value of thermal-warning2 end indicator.	Die temperature above thermal-warning2 limit. Die temperature has dropped below thermal-warning2 limit.
INT_SPKMO N_ERR_RA W	5	Raw value of the internal speaker monitor status indicator.	O: Internal speaker monitor not reporting data error. I: Internal speaker monitor reporting data error.

BITFIELD	BITS	DESCRIPTION	DECODE
INT_CLK_ER R_RAW	4	Raw value of internal clock error indicator.	O: Internal clock monitor not reporting clock error. I: Internal clock monitor reporting clock error.
CLK_RECOV ER_RAW	2	Raw value of the external clock monitor error recovery indicator.	Clock monitor not reporting clock error recovery. Clock monitor reporting clock error recovery.
CLK_ERR_R AW	1	Raw value of the external clock monitor error indicator.	No external clock error detected. Clock monitor reporting clock error.
DMON_ERR _RAW	0	Raw value of external data monitor error indicator.	No external data error detected. Data monitor reporting data error.

Interrupt Raw 3 (0x2003)

BIT	7	6	5	4	3	2	1	0
Field	AVDD_UVL O_RAW	DVDD_UVL O_RAW	PWRUP_D ONE_RAW	PWRDN_D ONE_RAW	PVDD_UVL O_SHDN_R AW	VBAT_UVL O_SHDN_R AW	DHT_ACTI VE_BGN_R AW	DHT_ACTI VE_END_R AW
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE		
AVDD_UVLO _RAW	7	Raw value of AVDD UVLO error indicator.	0: No AVDD UVLO error. 1: AVDD below UVLO threshold in the active state.		
DVDD_UVL O_RAW	6	Raw value of DVDD UVLO error indicator.	0: No DVDD UVLO error. 1: DVDD below UVLO threshold in the active state.		
PWRUP_DO NE_RAW	5	Raw value of power-up done.	O: Device is not reporting a power-up event. Device is reporting a power-up into the active state with the speaker amplifier enabled.		
PWRDN_DO NE_RAW	4	Raw value of power-down done.	O: Device is not reporting a power-down into software shutdown event. Device is reporting a power-down into software shutdown event.		
PVDD_UVLO _SHDN_RA W	3	Raw value of PVDD UVLO error indicator.	0: No PVDD UVLO error. 1: PVDD below UVLO threshold in the active state.		
VBAT_UVLO _SHDN_RA W	2	Raw value of VBAT UVLO error Indicator.	0: No VBAT UVLO error. 1: VBAT below UVLO threshold in the active state.		
DHT_ACTIV E_BGN_RA W	1	Raw value of DHT active begin.	0: DHT is not active. 1: DHT is active.		
DHT_ACTIV E_END_RA W	0	Raw value of DHT active end.	O: DHT is currently active or has not yet applied attenuation. 1: DHT activity has ended.		

28V Digital Input, Class-DG Amplifier with $\mathsf{IV}_{\mathsf{SENSE}}, \mathsf{Ultra\text{-}Low} \; \mathsf{I}_{\mathsf{Q}}, \; \mathsf{and} \; \mathsf{Brownout} \; \mathsf{Prevention}$

Interrupt Raw 4 (0x2004)

BIT	7	6	5	4	3	2	1	0
Field	_	_	-	_	BPE_L0_R AW	BPE_LEVE L_RAW	BPE_ACTIV E_BGN_RA W	BPE_ACTIV E_END_RA W
Reset	_	_	_	_	0x0	0x0	0x0	0x0
Access Type	_	_	_	_	Read Only	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_RA W	3	Indicates that BPE has transitioned into level 0.	0: BPE controller is not in level 0. 1: BPE controller has transitioned into level 0.
BPE_LEVEL _RAW	2	Indicates that BPE has transitioned between levels.	0: BPE is static. 1: BPE level is changing.
BPE_ACTIV E_BGN_RA W	1	Indicates that the BPE is active.	Brownout-protection engine is inactive. Brownout-protection engine is active.
BPE_ACTIV E_END_RA W	0	Indicates that the BPE is no longer active.	Brownout-protection engine is active. Brownout-protection engine is inactive.

Interrupt State 1 (0x2006)

BIT	7	6	5	4	3	2	1	0
Field	THERMSH DN_BGN_S TATE	THERMSH DN_END_S TATE	THERMWA RN1_BGN_ STATE	THERMWA RN1_END_ STATE	THERMFB_ BGN_STAT E	THERMFB_ END_STAT E	OTP_FAIL_ STATE	SPK_OVC_ STATE
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only

	•	T	
BITFIELD	BITS	DESCRIPTION	DECODE
THERMSHD N_BGN_STA TE	7	Unmaskable interrupt state, cleared by THERMSHDN_BGN_CLR.	0: No rising edge of THERMSHDN_BGN_RAW since last THERMSHDN_BGN_CLR. 1: Rising edge of THERMSHDN_BGN_RAW since last THERMSHDN_BGN_CLR.
THERMSHD N_END_STA TE	6	Unmaskable interrupt state, cleared by THERMSHDN_END_CLR.	0: No rising edge of THERMSHDN_END_RAW since last THERMSHDN_END_CLR. 1: Rising edge of THERMSHDN_END_RAW since last THERMSHDN_END_CLR.
THERMWAR N1_BGN_ST ATE	5	Unmaskable interrupt state, cleared by THERMWARN1_BGN_CLR.	0: No rising edge of THERMWARN1_BGN_RAW since last THERMWARN1_BGN_CLR. 1: Rising edge of THERMWARN1_BGN_RAW since last THERMWARN1_BGN_CLR.
THERMWAR N1_END_ST ATE	4	Unmaskable interrupt state, cleared by THERMWARN1_END_CLR.	0: No rising edge of THERMWARN1_END_RAW since last THERMWARN1_END_CLR. 1: Rising edge of THERMWARN1_END_RAW since last THERMWARN1_END_CLR.
THERMFB_B GN_STATE	3	Unmaskable interrupt state, cleared by THERMFB_BGN_CLR.	0: No rising edge of THERMFB_BGN_RAW since last THERMFB_BGN_CLR. 1: Rising edge of THERMFB_BGN_RAW since last THERMFB_BGN_CLR.

BITFIELD	BITS	DESCRIPTION	DECODE
THERMFB_E ND_STATE	2	Unmaskable interrupt state, cleared by THERMFB_END_CLR.	0: No rising edge of THERMFB_END_RAW since last THERMFB_END_CLR. 1: Rising edge of THERMFB_END_RAW since last THERMFB_END_CLR.
OTP_FAIL_S TATE	1	Unmaskable interrupt state, cleared by OTP_FAIL_CLR.	0: No rising edge of OTP_FAIL_RAW since last OTP_FAIL_CLR. 1: Rising edge of OTP_FAIL_RAW since last OTP_FAIL_CLR.
SPK_OVC_S TATE	0	Unmaskable interrupt state, cleared by SPK_OVC_CLR.	0: No rising edge of SPK_OVC_RAW since last SPK_OVC_CLR. 1: Rising edge of SPK_OVC_RAW since last SPK_OVC_CLR.

Interrupt State 2 (0x2007)

BIT	7	6	5	4	3	2	1	0
Field	THERMWA RN2_BGN_ STATE	THERMWA RN2_END_ STATE	INT_SPKM ON_ERR_S TATE	INT_CLK_E RR_STATE	-	CLK_RECO VER_STAT E	CLK_ERR_ STATE	DMON_ER R_STATE
Reset	0b0	0b0	0b0	0x0	-	0x0	0x0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	-	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
THERMWAR N2_BGN_ST ATE	7	Unmaskable interrupt state, cleared by THERMWARN2_BGN_CLR.	0: No rising edge of THERMWARN2_BGN_RAW since last THERMWARN2_BGN_CLR. 1: Rising edge of THERMWARN2_BGN_RAW since last THERMWARN2_BGN_CLR.
THERMWAR N2_END_ST ATE	6	Unmaskable interrupt state, cleared by THERMWARN2_END_CLR.	0: No rising edge of THERMWARN2_END_RAW since last THERMWARN2_END_CLR. 1: Rising edge of THERMWARN2_END_RAW since last THERMWARN2_END_CLR.
INT_SPKMO N_ERR_STA TE	5	Unmaskable interrupt state, cleared by INT_SPKMON_ERR_CLR.	0: No rising edge of INT_SPKMON_ERR_RAW since last INT_SPKMON_ERR_CLR. 1: Rising edge of INT_SPKMON_ERR_RAW since last INT_SPKMON_ERR_CLR.
INT_CLK_ER R_STATE	4	Unmaskable interrupt state, cleared by INT_CLK_ERR_CLR.	0: No rising edge of INT_CLK_ERR_RAW since last INT_CLK_ERR_CLR. 1: Rising edge of INT_CLK_ERR_RAW since last INT_CLK_ERR_CLR.
CLK_RECOV ER_STATE	2	Unmaskable interrupt state, cleared by CLK_RECOVER_CLR.	0: No rising edge of CLK_RECOVER_RAW since last CLK_RECOVER_CLR. 1: Rising edge of CLK_RECOVER_RAW since last CLK_RECOVER_CLR.
CLK_ERR_S TATE	1	Unmaskable interrupt state, cleared by CLK_ERR_CLR.	0: No rising edge of CLK_ERR_RAW since last CLK_ERR_CLR. 1: Rising edge of CLK_ERR_RAW since last CLK_ERR_CLR.
DMON_ERR _STATE	0	Unmaskable interrupt state, cleared by DMON_ERR_CLR.	0: No rising edge of DMON_ERR_RAW since last DMON_ERR_CLR. 1: Rising edge of DMON_ERR_RAW since last DMON_ERR_CLR.

Interrupt State 3 (0x2008)

BIT	7	6	5	4	3	2	1	0
Field	AVDD_UVL O_STATE	DVDD_UVL O_STATE	PWRUP_D ONE_STAT E	PWRDN_D ONE_STAT E	PVDD_UVL O_SHDN_S TATE	VBAT_UVL O_SHDN_S TATE	DHT_ACTI VE_BGN_S TATE	DHT_ACTI VE_END_S TATE
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
AVDD_UVLO _STATE	7	Unmaskable interrupt state, cleared by AVDD_UVLO_CLR.	0: No rising edge of AVDD_UVLO_RAW since last AVDD_UVLO_CLR. 1: Rising edge of AVDD_UVLO_RAW since last AVDD_UVLO_CLR.
DVDD_UVL O_STATE	6	Unmaskable interrupt state, cleared by DVDD_UVLO_CLR.	0: No rising edge of DVDD_UVLO_RAW since last DVDD_UVLO_CLR. 1: Rising edge of DVDD_UVLO_RAW since last DVDD_UVLO_CLR.
PWRUP_DO NE_STATE	5	Unmaskable interrupt state, cleared by PWRUP_DONE_CLR.	0: No rising edge of PWRUP_DONE_RAW since last PWRUP_DONE_CLR. 1: Rising edge of PWRUP_DONE_RAW since last PWRUP_DONE_CLR.
PWRDN_DO NE_STATE	4	Unmaskable interrupt state, cleared by PWRDN_DONE_CLR.	0: No rising edge of PWRDN_DONE_RAW since last PWRDN_DONE_CLR. 1: Rising edge of PWRDN_DONE_RAW since last PWRDN_DONE_CLR.
PVDD_UVLO _SHDN_STA TE	3	Unmaskable interrupt state, cleared by PVDD_UVLO_SHDN_CLR.	0: No rising edge of PVDD_UVLO_SHDN_RAW since last PVDD_UVLO_SHDN_CLR. 1: Rising edge of PVDD_UVLO_SHDN_RAW since last PVDD_UVLO_SHDN_CLR.
VBAT_UVLO _SHDN_STA TE	2	Unmaskable interrupt state, cleared by VBAT_UVLO_SHDN_CLR.	0: No rising edge of VBAT_UVLO_SHDN_RAW since last VBAT_UVLO_SHDN_CLR. 1: Rising edge of VBAT_UVLO_SHDN_RAW since last VBAT_UVLO_SHDN_CLR.
DHT_ACTIV E_BGN_STA TE	1	Unmaskable interrupt state, cleared by DHT_ACTIVE_BGN_CLR.	0: No rising edge of DHT_ACTIVE_BGN_RAW since last DHT_ACTIVE_BGN_CLR. 1: Rising edge of DHT_ACTIVE_BGN_RAW since last DHT_ACTIVE_BGN_CLR.
DHT_ACTIV E_END_STA TE	0	Unmaskable interrupt state, cleared by DHT_ACTIVE_END_CLR.	0: No rising edge of DHT_ACTIVE_END_RAW since last DHT_ACTIVE_END_CLR. 1: Rising edge of DHT_ACTIVE_END_RAW since last DHT_ACTIVE_END_CLR.

Interrupt State 4 (0x2009)

BIT	7	6	5	4	3	2	1	0
Field	_	_	-	_	BPE_L0_ST ATE	BPE_LEVE L_STATE	BPE_ACTIV E_BGN_ST ATE	BPE_ACTIV E_END_ST ATE
Reset	_	_	_	_	0x0	0x0	0x0	0x0
Access Type	_	_	_	_	Read Only	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_ST ATE	3	Unmaskable interrupt state, cleared by BPE_L0_CLR.	0: No rising edge of BPE_L0_RAW since last BPE_L0_CLR. 1: Rising edge of BPE_L0_RAW since last BPE_L0_CLR.
BPE_LEVEL _STATE	2	Unmaskable interrupt state, cleared by BPE_LEVEL_CLR.	0: No rising edge of BPE_LEVEL_RAW since last BPE_LEVEL_CLR. 1: Rising edge of BPE_LEVEL_RAW since last BPE_LEVEL_CLR.
BPE_ACTIV E_BGN_STA TE	1	Unmaskable interrupt state, cleared by BPE_ACTIVE_END_CLR.	0: No rising edge of BPE_ACTIVE_BGN_RAW since last BPE_ACTIVE_BGN_CLR. 1: Rising edge of BPE_ACTIVE_BGN_RAW since last BPE_ACTIVE_BGN_CLR.
BPE_ACTIV E_END_STA TE	0	Unmaskable interrupt state, cleared by BPE_ACTIVE_END_CLR.	0: No rising edge of BPE_ACTIVE_END_RAW since last BPE_ACTIVE_END_CLR. 1: Rising edge of BPE_ACTIVE_END_RAW since last BPE_ACTIVE_END_CLR.

Interrupt Flag 1 (0x200B)

BIT	7	6	5	4	3	2	1	0
Field	THERMSH DN_BGN_F LAG	THERMSH DN_END_F LAG	THERMWA RN1_BGN_ FLAG	THERMWA RN1_END_ FLAG	THERMFB_ BGN_FLAG	THERMFB_ END_FLAG	OTP_FAIL_ FLAG	SPK_OVC_ FLAG
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
THERMSHD N_BGN_FLA G	7	Thermal Shutdown Begin Event Maskable Interrupt Flag. Masked by THERMSHDN_END_EN and cleared by THERMSHDN_END_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of THERMSHDN_BGN_RAW since last THERMSHDN_BGN_CLR or THERMSHDN_BGN_EN is low. 1: THERMSHDN_BGN_EN is high and rising edge of THERMSHDN_BGN_RAW since last THERMSHDN_BGN_CLR.
THERMSHD N_END_FLA G	6	Thermal Shutdown End Event Maskable Interrupt Flag. Masked by THERMSHDN_END_EN and cleared by THERMSHDN_END_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of THERMSHDN_END_RAW since last THERMSHDN_END_CLR or THERMSHDN_END_EN is low. 1: THERMSHDN_END_EN is high and rising edge of THERMSHDN_END_RAW since last THERMSHDN_END_CLR.
THERMWAR N1_BGN_FL AG	5	Thermal-warning1 Begin Event Maskable Interrupt Flag. Masked by THERMWARN1_BGN_EN and cleared by THERMWARN1_BGN_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of THERMWARN1_BGN_RAW since last THERMWARN1_BGN_CLR or THERMWARN1_BGN_EN is low. 1: THERMWARN1_BGN_EN is high and rising edge of THERMWARN1_BGN_RAW since last THERMWARN1_BGN_CLR.
THERMWAR N1_END_FL AG	4	Thermal-warning1 End Event Maskable Interrupt Flag. Masked by THERMWARN1_END_EN and cleared by THERMWARN1_END_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of THERMWARN1_END_RAW since last THERMWARN1_END_CLR or THERMWARN1_END_EN is low. 1: THERMWARN1_END_EN is high and rising edge of THERMWARN1_END_RAW since last THERMWARN1_END_CLR.

BITFIELD	BITS	DESCRIPTION	DECODE
THERMFB_B GN_FLAG	3	Thermal Foldback Begin Event Maskable Interrupt Flag. Masked by THERMFB_BGN_EN and cleared by THERMFB_BGN_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of THERMFB_BGN_RAW since last THERMFB_BGN_CLR or THERMFB_BGN_EN is low. 1: THERMFB_BGN_EN is high and rising edge of THERMFB_BGN_RAW since last THERMFB_BGN_CLR.
THERMFB_E ND_FLAG	2	Thermal Foldback End Event Maskable Interrupt Flag. Masked by THERMFB_END_EN and cleared by THERMFB_END_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of THERMFB_END_RAW since last THERMFB_END_CLR or THERMFB_END_EN is low. 1: THERMFB_END_EN is high and rising edge of THERMFB_END_RAW since last THERMFB_END_CLR.
OTP_FAIL_F LAG	1	OTP Load Routine Fail Event Maskable Interrupt Flag. Masked by OTP_FAIL_EN and cleared by OTP_FAIL_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	O: No rising edge of OTP_FAIL_RAW since last OTP_FAIL_CLR or OTP_FAIL_EN is low. 1: OTP_FAIL_EN is high and rising edge of OTP_FAIL_RAW since last OTP_FAIL_CLR.
SPK_OVC_F LAG	0	Speaker Overcurrent Event Maskable Interrupt Flag. Masked by SPK_OVC_EN and cleared by SPK_OVC_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of SPK_OVC_RAW since last SPK_OVC_CLR or SPK_OVC_EN is low. 1: SPK_OVC_EN is high and rising edge of SPK_OVC_RAW since last SPK_OVC_CLR.

Interrupt Flag 2 (0x200C)

BIT	7	6	5	4	3	2	1	0
Field	THERMWA RN2_BGN_ FLAG	THERMWA RN2_END_ FLAG	INT_SPKM ON_ERR_F LAG	INT_CLK_E RR_FLAG	_	CLK_RECO VER_FLAG	CLK_ERR_ FLAG	DMON_ER R_FLAG
Reset	0b0	0b0	0b0	0x0	_	0x0	0x0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	_	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
THERMWAR N2_BGN_FL AG	7	Thermal-warning2 Begin Event Maskable Interrupt Flag. Masked by THERMWARN2_BGN_EN and cleared by THERMWARN2_BGN_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of THERMWARN2_BGN_RAW since last THERMWARN2_BGN_CLR or THERMWARN2_BGN_EN is low. 1: THERMWARN2_BGN_EN is high and rising edge of THERMWARN2_BGN_RAW since last THERMWARN2_BGN_CLR.
THERMWAR N2_END_FL AG	6	Thermal-warning2 End Event Maskable Interrupt Flag. Masked by THERMWARN2_END_EN and cleared by THERMWARN2_END_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of THERMWARN2_END_RAW since last THERMWARN2_END_CLR or THERMWARN2_END_EN is low. 1: THERMWARN2_END_EN is high and rising edge of THERMWARN2_END_RAW since last THERMWARN2_END_CLR.
INT_SPKMO N_ERR_FLA G	5	Internal Speaker Data Monitor Error Event Maskable Interrupt Flag. Masked by INT_SPKMON_ERR_EN and cleared by INT_SPKMON_ERR_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of INT_SPKMON_ERR_RAW since last INT_SPKMON_ERR_CLR or INT_SPKMON_ERR_EN is low. 1: INT_SPKMON_ERR_EN high and rising edge of INT_SPKMON_ERR_RAW since last INT_SPKMON_ERR_CLR.

BITFIELD	BITS	DESCRIPTION	DECODE
INT_CLK_ER R_FLAG	4	Internal Clock Monitor Error Event Maskable Interrupt Flag. Masked by INT_CLK_ERR_EN and cleared by INT_CLK_ERR_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of INT_CLK_ERR_RAW since last INT_CLK_ERR_CLR or INT_CLK_ERR_EN is low. 1: INT_CLK_ERR_EN high and rising edge of INT_CLK_ERR_RAW since last INT_CLK_ERR_CLR.
CLK_RECOV ER_FLAG	2	PCM Input Clock Error Recovery Event Maskable Interrupt Flag. Masked by CLK_RECOVER_EN and cleared by CLK_RECOVER_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of CLK_RECOVER_RAW since last CLK_RECOVER_CLR or CLK_RECOVER_EN is low. 1: BCLK_RECOVER_EN high and rising edge of BCLK_RECOVER_RAW since last BCLK_RECOVER_CLR.
CLK_ERR_F LAG	1	PCM Input Clock Error Event Maskable Interrupt Flag. Masked by CLK_ERR_EN and cleared by CLK_ERR_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of CLK_ERR_RAW since last CLK_ERR_CLR or CLK_ERR_EN is low. 1: CLK_ERR_EN high and rising edge of CLK_ERR_RAW since last CLK_ERR_CLR.
DMON_ERR _FLAG	0	PCM Data Input Error Event Maskable Interrupt Flag. Masked by DMON_ERR_EN and cleared by DMON_ERR_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of DMON_ERR_RAW since last DMON_ERR_CLR or DMON_ERR_EN is low. 1: DMON_ERR_EN high and rising edge of DMON_ERR_RAW since last DMON_ERR_CLR.

Interrupt Flag 3 (0x200D)

BIT	7	6	5	4	3	2	1	0
Field	AVDD_UVL O_FLAG	DVDD_UVL O_FLAG	PWRUP_D ONE_FLAG	PWRDN_D ONE_FLAG	PVDD_UVL O_SHDN_F LAG	VBAT_UVL O_SHDN_F LAG	DHT_ACTI VE_BGN_F LAG	DHT_ACTI VE_END_F LAG
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE
AVDD_UVLO _FLAG	7	AVDD Supply UVLO Event Maskable Interrupt Flag. Masked by AVDD_UVLO_EN and cleared by AVDD_UVLO_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of AVDD_UVLO_RAW since last AVDD_UVLO_CLR or AVDD_UVLO_EN is low. 1: AVDD_UVLO_EN is high and rising edge of AVDD_UVLO_RAW since last AVDD_UVLO_CLR.
DVDD_UVL O_FLAG	6	DVDD Supply UVLO Event Maskable Interrupt Flag. Masked by DVDD_UVLO_EN and cleared by DVDD_UVLO_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of DVDD_UVLO_RAW since last DVDD_UVLO_CLR or DVDD_UVLO_EN is low. 1: DVDD_UVLO_EN is high and rising edge of DVDD_UVLO_RAW since last DVDD_UVLO_CLR.
PWRUP_DO NE_FLAG	5	Device Power-Up Done Event Maskable Interrupt Flag. Masked by PWRUP_DONE_EN and cleared by PWRUP_DONE_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	O: No rising edge of PWRUP_DONE_RAW since last PWRUP_DONE_CLR or PWRUP_DONE_EN is low. 1: PWRUP_DONE_EN is high and rising edge of PWRUP_DONE_RAW since last PWRUP_DONE_CLR.

BITFIELD	BITS	DESCRIPTION	DECODE
PWRDN_DO NE_FLAG	4	Device Power-Down Done Event Maskable Interrupt Flag. Masked by PWRDN_DONE_EN and cleared by PWRDN_DONE_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of PWRDN_DONE_RAW since last PWRDN_DONE_CLR or PWRDN_DONE_EN is low. 1: PWRDN_DONE_EN is high and rising edge of PWRDN_DONE_RAW since last PWRDN_DONE_CLR.
PVDD_UVLO _SHDN_FLA G	3	PVDD Supply UVLO Event Maskable Interrupt Flag. Masked by PVDD_UVLO_SHDN_EN and cleared by PVDD_UVLO_SHDN_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of PVDD_UVLO_SHDN_RAW since last PVDD_UVLO_SHDN_CLR or PVDD_UVLO_SHDN_EN is low. 1: PVDD_UVLO_SHDN_EN is high and rising edge of PVDD_UVLO_SHDN_RAW since last PVDD_UVLO_SHDN_CLR.
VBAT_UVLO _SHDN_FLA G	2	VBAT supply UVLO Event Maskable Interrupt Flag. Masked by VBAT_UVLO_SHDN_EN and cleared by VBAT_UVLO_SHDN_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of VBAT_UVLO_SHDN_RAW since last VBAT_UVLO_SHDN_CLR or VBAT_UVLO_SHDN_EN is low. 1: VBAT_UVLO_SHDN_EN is high and rising edge of VBAT_UVLO_SHDN_RAW since last VBAT_UVLO_SHDN_CLR.
DHT_ACTIV E_BGN_FLA G	1	DHT Active Begin Event Maskable Interrupt Flag. Masked by DHT_ACTIVE_BGN_EN and cleared by DHT_ACTIVE_BGN_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of DHT_ACTIVE_BGN_RAW since last DHT_ACTIVE_BGN_CLR or DHT_ACTIVE_BGN_EN is low. 1: DHT_ACTIVE_BGN_EN is high and rising edge of DHT_ACTIVE_BGN_RAW since last DHT_ACTIVE_BGN_CLR.
DHT_ACTIV E_END_FLA G	0	DHT Active End Event Maskable Interrupt Flag. Masked by DHT_ACTIVE_END_EN and cleared by DHT_ACTIVE_END_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of DHT_ACTIVE_END_RAW since last DHT_ACTIVE_END_CLR or DHT_ACTIVE_END_EN is low. 1: DHT_ACTIVE_END_EN is high and rising edge of DHT_ACTIVE_END_RAW since last DHT_ACTIVE_END_CLR.

Interrupt Flag 4 (0x200E)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	BPE_L0_FL AG	BPE_LEVE L_FLAG	BPE_ACTIV E_BGN_FL AG	BPE_ACTIV E_END_FL AG
Reset	_	_	_	_	0x0	0x0	0x0	0x0
Access Type	_	_	_	_	Read Only	Read Only	Read Only	Read Only

BITFIELD	BITS	DESCRIPTION	DECODE	
BPE_L0_FLA G	3	Brownout-Protection Engine Level 0 Entry Event Maskable Interrupt Flag. Masked by BPE_L0_EN and cleared by BPE_L0_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.		
BPE_LEVEL _FLAG	2	Brownout-Protection Engine Level Change Maskable Interrupt Flag. Masked by BPE_LEVEL_EN and cleared by BPE_LEVEL_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of BPE_LEVEL_RAW since last BPE_LEVEL_CLR or BPE_LEVEL_EN is low. 1: BPE_LEVEL_EN high and rising edge of BPE_LEVEL_RAW since last BPE_LEVEL_CLR.	

28V Digital Input, Class-DG Amplifier with $\mathsf{IV}_{\mathsf{SENSE}}, \mathsf{Ultra\text{-}Low} \; \mathsf{I}_{\mathsf{Q}}, \; \mathsf{and} \; \mathsf{Brownout} \; \mathsf{Prevention}$

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_ACTIV E_BGN_FLA G	1	Brownout-Protection Engine Active End Maskable Interrupt Flag. Masked by BPE_ACTIVE_BGN_EN and cleared by BPE_ACTIVE_BGN_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of BPE_ACTIVE_BGN_RAW since last BPE_ACTIVE_BGN_CLR or BPE_ACTIVE_BGN_EN is low. 1: BPE_ACTIVE_BGN_EN high and rising edge of BPE_ACTIVE_BGN_RAW since last BPE_ACTIVE_BGN_CLR.
BPE_ACTIV E_END_FLA G	0	Brownout-Protection Engine Active End Maskable Interrupt Flag. Masked by BPE_ACTIVE_END_EN and cleared by BPE_ACTIVE_END_CLR. If IRQ is enabled, an interrupt is generated on a flag bit rising edge.	0: No rising edge of BPE_ACTIVE_END_RAW since last BPE_ACTIVE_END_CLR or BPE_ACTIVE_END_EN is low. 1: BPE_ACTIVE_END_EN high and rising edge of BPE_ACTIVE_END_RAW since last BPE_ACTIVE_END_CLR.

Interrupt Enable 1 (0x2010)

BIT	7	6	5	4	3	2	1	0
Field	THERMSH DN_BGN_E N	THERMSH DN_END_E N	THERMWA RN1_BGN_ EN	THERMWA RN1_END_ EN	THERMFB_ BGN_EN	THERMFB_ END_EN	OTP_FAIL_ EN	SPK_OVC_ EN
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b1	0b0
Access Type	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
THERMSHD N_BGN_EN	7	Enable (unmask) control for THERMSHDN_BGN_FLAG.	0: THERMSHDN_BGN_FLAG cannot go high. 1: THERMSHDN_BGN_FLAG goes high if there is a rising edge on THERMSHDN_BGN_RAW since last THERMSHDN_BGN_CLR.
THERMSHD N_END_EN	6	Enable (unmask) control for THERMSHDN_END_FLAG.	0: THERMSHDN_END_FLAG cannot go high. 1: THERMSHDN_END_FLAG goes high if there is a rising edge on THERMSHDN_END_RAW since last THERMSHDN_END_CLR.
THERMWAR N1_BGN_EN	5	Enable (unmask) control for THERMWARN1_BGN_FLAG.	0: THERMWARN1_BGN_FLAG cannot go high. 1: THERMWARN1_BGN_FLAG goes high if there is a rising edge on THERMWARN1_BGN_RAW since last THERMWARN1_BGN_CLR.
THERMWAR N1_END_EN	4	Enable (unmask) control for THERMWARN1_END_FLAG.	0: THERMWARN1_END_FLAG cannot go high. 1: THERMWARN1_END_FLAG goes high if there is a rising edge on THERMWARN1_END_RAW since last THERMWARN1_END_CLR.
THERMFB_B GN_EN	3	Enable (unmask) control for THERMFB_BGN_FLAG.	0: THERMFB_BGN_FLAG cannot go high. 1: THERMFB_BGN_FLAG goes high if there is a rising edge on THERMFB_BGN_RAW since last THERMFB_BGN_CLR.
THERMFB_E ND_EN	2	Enable (unmask) control for THERMFB_END_FLAG.	0: THERMFB_END_FLAG cannot go high. 1: THERMFB_END_FLAG goes high if there is a rising edge on THERMFB_END_RAW since last THERMFB_END_CLR.
OTP_FAIL_E	1	Enable (unmask) control for OTP_FAIL_FLAG.	0: OTP_FAIL_FLAG cannot go high. 1: OTP_FAIL_FLAG goes high if there is a rising edge on OTP_FAIL_RAW since last OTP_FAIL_CLR.

28V Digital Input, Class-DG Amplifier with $\mathsf{IV}_{\mathsf{SENSE}},$ Ultra-Low $\mathsf{I}_{\mathsf{Q}},$ and Brownout Prevention

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_OVC_E N	0	Enable (unmask) control for SPK_OVC_FLAG.	0: SPK_OVC_FLAG cannot go high. 1: SPK_OVC_FLAG goes high if there is a rising edge on SPK_OVC_RAW since last SPK_OVC_CLR.

Interrupt Enable 2 (0x2011)

BIT	7	6	5	4	3	2	1	0
Field	THERMWA RN2_BGN_ EN	THERMWA RN2_END_ EN	INT_SPKM ON_ERR_E N	INT_CLK_E RR_EN	_	CLK_RECO VER_EN	CLK_ERR_ EN	DMON_ER R_EN
Reset	0b0	0b0	0b0	0x0	_	0x0	0x0	0b0
Access Type	Write, Read	Write, Read	Write, Read	Write, Read	_	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
THERMWAR N2_BGN_EN	7	Enable (unmask) control for THERMWARN2_BGN_FLAG.	0: THERMWARN2_BGN_FLAG cannot go high. 1: THERMWARN2_BGN_FLAG goes high if there is a rising edge on THERMWARN2_BGN_RAW since last THERMWARN2_BGN_CLR.
THERMWAR N2_END_EN	6	Enable (unmask) control for THERMWARN2_END_FLAG.	0: THERMWARN2_END_FLAG cannot go high. 1: THERMWARN2_END_FLAG goes high if there is a rising edge on THERMWARN2_END_RAW since last THERMWARN2_END_CLR.
INT_SPKMO N_ERR_EN	5	Enable (unmask) control for INT_SPKMON_ERR_FLAG.	0: INT_SPKMON_ERR_FLAG cannot go high. 1: INT_SPKMON_ERR_FLAG goes high if there is a rising edge on INT_SPKMON_ERR_RAW since last INT_SPKMON_ERR_CLR.
INT_CLK_ER R_EN	4	Enable (unmask) control for INT_CLK_ERR_FLAG.	0: INT_CLK_ERR_FLAG cannot go high. 1: INT_CLK_ERR_FLAG goes high if there is a rising edge on INT_CLK_ERR_RAW since last INT_CLK_ERR_CLR.
CLK_RECOV ER_EN	2	Enable (unmask) control for CLK_RECOVER_FLAG.	0: CLK_RECOVER_FLAG cannot go high. 1: CLK_RECOVER_FLAG goes high if there is a rising edge on CLK_RECOVER_RAW since last CLK_RECOVER_CLR.
CLK_ERR_E N	1	Enable (unmask) control for CLK_ERR_FLAG.	0: CLK_ERR_FLAG cannot go high. 1: CLK_ERR_FLAG goes high if there is a rising edge on CLK_ERR_RAW since last CLK_ERR_CLR.
DMON_ERR _EN	0	Enable (unmask) control for DMON_ERR_FLAG.	0: DMON_ERR_FLAG cannot go high. 1: DMON_ERR_FLAG goes high if there is a rising edge on DMON_ERR_RAW since last DMON_ERR_CLR.

Interrupt Enable 3 (0x2012)

BIT	7	6	5	4	3	2	1	0
Field	AVDD_UVL O_EN	DVDD_UVL O_EN	PWRUP_D ONE_EN	PWRDN_D ONE_EN	PVDD_UVL O_SHDN_E N	VBAT_UVL O_SHDN_E N	DHT_ACTI VE_BGN_E N	DHT_ACTI VE_END_E N
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
AVDD_UVLO _EN	7	Enable (unmask) control for AVDD_UVLO_FLAG.	0: AVDD_UVLO_FLAG cannot go high. 1: AVDD_UVLO_FLAG goes high if there is a rising edge on AVDD_UVLO_RAW since last AVDD_UVLO_CLR.
DVDD_UVL O_EN	6	Enable (unmask) control for DVDD_UVLO_FLAG.	0: DVDD_UVLO_FLAG cannot go high. 1: DVDD_UVLO_FLAG goes high if there is a rising edge on DVDD_UVLO_RAW since last DVDD_UVLO_CLR.
PWRUP_DO NE_EN	5	Enable (unmask) control for PWRUP_DONE_FLAG.	0: PWRUP_DONE_FLAG cannot go high. 1: PWRUP_DONE_FLAG goes high if there is a rising edge on PWRUP_DONE_RAW since last PWRUP_DONE_CLR.
PWRDN_DO NE_EN	4	Enable (unmask) control for PWRDN_DONE_FLAG.	0: PWRDN_DONE_FLAG cannot go high. 1: PWRDN_DONE_FLAG goes high if there is a rising edge on PWRDN_DONE_RAW since last PWRDN_DONE_CLR.
PVDD_UVLO _SHDN_EN	3	Enable (unmask) control for PVDD_UVLO_SHDN_FLAG.	0: PVDD_UVLO_SHDN_FLAG cannot go high. 1: PVDD_UVLO_SHDN_FLAG goes high if there is a rising edge on PVDD_UVLO_SHDN_RAW since last PVDD_UVLO_SHDN_CLR.
VBAT_UVLO _SHDN_EN	2	Enable (unmask) control for VBAT_UVLO_SHDN_FLAG.	0: VBAT_UVLO_SHDN_FLAG cannot go high. 1: VBAT_UVLO_SHDN_FLAG goes high if there is a rising edge on VBAT_UVLO_SHDN_RAW since last VBAT_UVLO_SHDN_CLR.
DHT_ACTIV E_BGN_EN	1	Enable (unmask) control for DHT_ACTIVE_BGN_FLAG.	0: DHT_ACTIVE_BGN_FLAG cannot go high. 1: DHT_ACTIVE_BGN_FLAG goes high if there is a rising edge on DHT_ACTIVE_BGN_RAW since last DHT_ACTIVE_BGN_CLR.
DHT_ACTIV E_END_EN	0	Enable (unmask) control for DHT_ACTIVE_END_FLAG.	0: DHT_ACTIVE_END_FLAG cannot go high. 1: DHT_ACTIVE_END_FLAG goes high if there is a rising edge on DHT_ACTIVE_END_RAW since last DHT_ACTIVE_END_CLR.

Interrupt Enable 4 (0x2013)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	BPE_L0_E N	BPE_LEVE L_EN	BPE_ACTIV E_BGN_EN	_
Reset	_	_	_	_	0x0	0x0	0x0	0x0
Access Type	_	_	_	_	Write, Read	Write, Read	Write, Read	Write, Read

28V Digital Input, Class-DG Amplifier with $\mathsf{IV}_{\mathsf{SENSE}},$ Ultra-Low $\mathsf{I}_{\mathsf{Q}},$ and Brownout Prevention

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_EN	3	Enable (unmask) control for BPE_L0_FLAG.	0: BPE_L0_FLAG cannot go high. 1: BPE_L0_FLAG goes high if there is a rising edge on BPE_L0_RAW since last BPE_L0_CLR.
BPE_LEVEL _EN	2	Enable (unmask) control for BPE_LEVEL_FLAG.	0: BPE_LEVEL_FLAG cannot go high. 1: BPE_LEVEL_FLAG goes high if there is a rising edge on BPE_LEVEL_RAW since last BPE_LEVEL_CLR.
BPE_ACTIV E_BGN_EN	1	Enable (unmask) control for BPE_ACTIVE_BGN_FLAG.	0: BPE_ACTIVE_BGN_FLAG cannot go high. 1: BPE_ACTIVE_BGN_FLAG goes high if there is a rising edge on BPE_ACTIVE_BGN_RAW since last BPE_ACTIVE_BGN_CLR.
BPE_ACTIV E_END_EN	0	Enable (unmask) control for BPE_ACTIVE_END_FLAG.	0: BPE_ACTIVE_END_FLAG cannot go high. 1: BPE_ACTIVE_END_FLAG goes high if there is a rising edge on BPE_ACTIVE_END_RAW since last BPE_ACTIVE_END_CLR.

Interrupt Flag Clear 1 (0x2015)

BIT	7	6	5	4	3	2	1	0
Field	THERMSH DN_BGN_C LR	THERMSH DN_END_C LR	THERMWA RN1_BGN_ CLR	THERMWA RN1_END_ CLR	THERMFB_ BGN_CLR	THERMFB_ END_CLR	OTP_FAIL_ CLR	SPK_OVC_ CLR
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Write Only	Write Only	Write Only	Write Only	Write Only	Write Only	Write Only	Write Only

BITFIELD	BITS	DESCRIPTION	DECODE
THERMSHD N_BGN_CLR	7	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears THERMSHDN_BGN_STATE and THERMSHDN_BGN_FLAG to zero.
THERMSHD N_END_CLR	6	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears THERMSHDN_END_STATE and THERMSHDN_END_FLAG to zero.
THERMWAR N1_BGN_CL R	5	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears THERMWARN1_BGN_STATE and THERMWARN1_BGN_FLAG to zero.
THERMWAR N1_END_CL R	4	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears THERMWARN1_END_STATE and THERMWARN1_END_FLAG to zero.
THERMFB_B GN_CLR	3	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears THERMFB_BGN_STATE and THERMFB_BGN_FLAG to zero.
THERMFB_E ND_CLR	2	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears THERMFB_END_STATE and THERMFB_END_FLAG to zero.
OTP_FAIL_C LR	1	Clears associated FLAG and STATE bits.	O: Writing zero has no effect. His Writing one clears OTP_FAIL_STATE and OTP_FAIL_FLAG to zero.
SPK_OVC_C LR	0	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears SPK_OVC_STATE and SPK_OVC_FLAG to zero.

28V Digital Input, Class-DG Amplifier with $\mathsf{IV}_{\mathsf{SENSE}},$ Ultra-Low $\mathsf{I}_{\mathsf{Q}},$ and Brownout Prevention

Interrupt Flag Clear 2 (0x2016)

BIT	7	6	5	4	3	2	1	0
Field	THERMWA RN2_BGN_ CLR	THERMWA RN2_END_ CLR	INT_SPKM ON_ERR_C LR	INT_CLK_E RR_CLR	-	CLK_RECO VER_CLR	CLK_ERR_ CLR	DMON_ER R_CLR
Reset	0b0	0b0	0b0	0x0	-	0x0	0x0	0b0
Access Type	Write Only	Write Only	Write Only	Write Only	-	Write Only	Write Only	Write Only

BITFIELD	BITS	DESCRIPTION	DECODE
THERMWAR N2_BGN_CL R	7	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears THERMWARN2_BGN_STATE and THERMWARN2_BGN_FLAG to zero.
THERMWAR N2_END_CL R	6	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears THERMWARN2_END_STATE and THERMWARN2_END_FLAG to zero.
INT_SPKMO N_ERR_CLR	5	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears INT_SPKMON_ERR_STATE and INT_SPKMON_ERR_FLAG to zero.
INT_CLK_ER R_CLR	4	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears INT_CLK_ERR_STATE and INT_CLK_ERR_FLAG to zero.
CLK_RECOV ER_CLR	2	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears CLK_RECOVER_STATE and CLK_RECOVER_FLAG to zero.
CLK_ERR_C LR	1	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears CLK_ERR_STATE and CLK_ERR_FLAG to zero.
DMON_ERR _CLR	0	Clears associated FLAG and STATE bits.	0: Writing zero has no effect. 1: Writing one clears DMON_ERR_STATE and DMON_ERR_FLAG to zero.

Interrupt Flag Clear 3 (0x2017)

BIT	7	6	5	4	3	2	1	0
Field	AVDD_UVL O_CLR	DVDD_UVL O_CLR	PWRUP_D ONE_CLR	PWRDN_D ONE_CLR	PVDD_UVL O_SHDN_C LR	VBAT_UVL O_SHDN_C LR	DHT_ACTI VE_BGN_C LR	DHT_ACTI VE_END_C LR
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Write Only	Write Only	Write Only	Write Only	Write Only	Write Only	Write Only	Write Only

BITFIELD	BITS	DESCRIPTION	DECODE
AVDD_UVLO _CLR	7	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears AVDD_UVLO_STATE and AVDD_UVLO_FLAG to zero.
DVDD_UVL O_CLR	6	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears DVDD_UVLO_STATE and DVDD_UVLO_FLAG to zero.

BITFIELD	BITS	DESCRIPTION	DECODE
PWRUP_DO NE_CLR	5	Clears associated FLAG and STATE bits.	O: Writing zero has no effect. H: Writing one clears PWRUP_DONE_STATE and PWRUP_DONE_FLAG to zero. O: Writing zero has no effect.
PWRDN_DO NE_CLR	4	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears PWRDN_DONE_STATE and PWRDN_DONE_FLAG to zero.
PVDD_UVLO _SHDN_CLR	3	Clears associated FLAG and STATE bits.	O: Writing zero has no effect. H: Writing one clears PVDD_UVLO_SHDN_STATE and PVDD_UVLO_SHDN_FLAG to zero. O: Writing zero has no effect.
VBAT_UVLO _SHDN_CLR	2	Clears associated FLAG and STATE bits.	O: Writing zero has no effect. H: Writing one clears VBAT_UVLO_SHDN_STATE and VBAT_UVLO_SHDN_FLAG to zero.
DHT_ACTIV E_BGN_CLR	1	Clears associated FLAG and STATE bits.	O: Writing zero has no effect. H: Writing one clears DHT_ACTIVE_BGN_STATE and DHT_ACTIVE_BGN_FLAG to zero. O: Writing zero has no effect.
DHT_ACTIV E_END_CLR	0	Clears associated FLAG and STATE bits.	O: Writing zero has no effect. H: Writing one clears DHT_ACTIVE_END_STATE and DHT_ACTIVE_END_FLAG to zero. O: Writing zero has no effect.

Interrupt Flag Clear 4 (0x2018)

BIT	7	6	5	4	3	2	1	0
Field	_	ı	_	_	BPE_L0_CL R	BPE_LEVE L_CLR	BPE_ACTIV E_BGN_CL R	BPE_ACTIV E_END_CL R
Reset	_	-	-	_	0x0	0x0	0x0	0x0
Access Type	_	_	_	_	Write Only	Write Only	Write Only	Write Only

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_CL R	3	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears BPE_L0_STATE and BPE_L0_FLAG to zero.
BPE_LEVEL _CLR	2	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears BPE_LEVEL_STATE and BPE_LEVEL_FLAG to zero.
BPE_ACTIV E_BGN_CLR	1	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears BPE_ACTIVE_BGN_STATE and BPE_ACTIVE_BGN_FLAG to zero.
BPE_ACTIV E_END_CLR	0	Clears associated FLAG and STATE bits.	Writing zero has no effect. Writing one clears BPE_ACTIVE_END_STATE and BPE_ACTIVE_END_FLAG to zero.

IRQ Control (0x201F)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	IRQ_MODE	IRQ_POL	IRQ_EN
Reset	_	_	_	_	_	0b0	0b0	0b0
Access Type	_	_	_	_	_	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
IRQ_MODE	2	Controls the drive mode of the IRQ output.	O: Open-drain output (An external pullup resistor is required). CMOS push-pull output.
IRQ_POL	1	Controls the IRQ output assert polarity.	0: IRQ output is low when any interrupt FLAG bits are high (i.e., active-low). 1: IRQ output is high when any interrupt FLAG bits are high (i.e.,active-high).
IRQ_EN	0	Enables the IRQ Output.	O: IRQ output is disabled and is Hi-Z. I: IRQ output is enabled and controlled by the interrupt controller.

Thermal Warning Threshhold (0x2020)

BIT	7	6	5	4	3	2	1	0
Field	_		THERMWARN1_THRESH[6:0]					
Reset	_		0x46					
Access Type	_				Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
THERMWAR N1_THRESH	6:0	Sets the first thermal-warning threshold temperature.	0x00: 50°C 0x01: 51°C 0x02: 52°C 0x62: 148°C 0x63: 149°C 0x64-0x7F: 150°C

Warning Threshold 2 (0x2021)

BIT	7	6	5	4	3	2	1	0	
Field	_		THERMWARN2_THRESH[6:0]						
Reset	_		0x52						
Access Type	_				Write, Read				

BITFIELD	BITS	DESCRIPTION	DECODE
THERMWAR N2_THRESH	6:0	Sets the second thermal-warning threshold temperature	0x00: 50°C 0x01: 51°C 0x02: 52°C : 0x62: 148°C 0x63: 149°C 0x64-0x7F: 150°C

Thermal Shutdown Threshold (0x2022)

BIT	7	6	5	4	3	2	1	0
Field	_		THERMSHDN_THRESH[6:0]					
Reset	-		0x64					
Access Type	-				Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
THERMSHD N_THRESH	6:0	Sets the thermal-shutdown threshold temperature.	0x00: 50°C 0x01: 51°C 0x02: 52°C : 0x30: 98°C 0x31: 99°C 0x64 to 0x7F: 150°C

Thermal Hysteresis (0x2023)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	THERM_HYST[1:0]	
Reset	_	_	_	_	_	_	0x2	
Access Type	-	_	_	_	_	_	Write,	Read

BITFIELD	BITS	DESCRIPTION	DECODE
THERM_HY ST	1:0	Controls the amount of hysteresis applied to the thermal threshold measurements.	0x0: 2°C 0x1: 5°C 0x2: 7°C 0x3: 10°C

Thermal Foldback Settings (0x2024)

BIT	7	6	5	4	3	2	1	0
Field	THERMFB_HOLD[1:0]		THERMFB_RLS[1:0]		THERMFB_SLOPE2[1:0]		THERMFB_SLOPE1[1:0]	
Reset	0x3		0x0		0x2		0x2	
Access Type	Write,	Read	Write, Read		Write, Read		Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
THERMFB_ HOLD	7:6	The thermal foldback hold time controls how long the device temperature must remain below the configured thermal threshold hysteresis before thermal foldback release begins.	0x0: 0ms 0x1: 20ms 0x2: 40ms 0x3: 80ms
THERMFB_ RLS	5:4	This sets the release rate of the thermal foldback attenuation.	0x0: 3ms/dB 0x1: 10ms/dB 0x2: 100ms/dB 0x3: 300ms/dB
THERMFB_S LOPE2	3:2	This sets the slope of the thermal foldback attenuation when die temperature exceeds THERMWARN2_THRESH.	0x0: 0.25dB/°C 0x1: 0.5dB/°C 0x2: 1.0dB/°C 0x3: 2.0dB/°C

BITFIELD	BITS	DESCRIPTION	DECODE
THERMFB_S LOPE1	1:0	This sets the slope of the thermal foldback attenuation when the die temperature exceeds the thermal-warning1 threshold (THERMWARN1_THRESH) but is lower than the thermal-warning2 threshold (THERMWARN2_THRESH).	0x0: 0.25dB/°C 0x1: 0.5dB/°C 0x2: 1.0dB/°C 0x3: 2.0dB/°C

Thermal Foldback Enable (0x2027)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	THERMFB_ EN
Reset	_	_	_	_	_	_	_	0b1
Access Type	_	_	_	_	_	_	_	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
THERMFB_E N	0	Enables Thermal Foldback.	0: Thermal foldback disabled. 1: Thermal foldback enabled.

Noise Gate/Idle Mode Control (0x2030)

BIT	7	6	5	4	3	2	1	0	
Field		NG_UNMUTE	_THRESH[3:0]		NG_MUTE_THRESH[3:0]				
Reset		0:	κ3		0x2				
Access Type		Write,	Read			Write,	Read		

BITFIELD	BITS	DESCRIPTION	DECODE
NG_UNMUT E_THRESH	7:4	Sets the threshold (number of LSBs toggling) at which the noise gate/idle mode deactivates.	0x0: 1 LSB 0x1: 2 LSBs 0x2: 3 LSBs 0x3: 4 LSBs 0x4: 5 LSBs 0x5: 6 LSBs 0x6: 7 LSBs 0x7: 8 LSBs 0x8: 9 LSBs 0x9: 10 LSBs 0xA to 0xF: Reserved
NG_MUTE_T HRESH	3:0	Sets the threshold (number of LSBs toggling) at which the noise gate/Idle mode is activated.	0x0: 1 LSB 0x1: 2 LSBs 0x2: 3 LSBs 0x3: 4 LSBs 0x4: 5 LSBs 0x5: 6 LSBs 0x6: 7 LSBs 0x7: 8 LSBs 0x8: 9 LSBs 0x9: 10 LSBs 0xA to 0xF: Reserved

Noise Gate/Idle Mode Enables (0x2033)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	IDLE_MOD E_EN	NOISEGAT E_EN
Reset	_	_	_	_	-	-	0x0	0x0
Access Type	_	_	_	_	-	_	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
IDLE_MODE _EN	1	Enables the amplifier idle mode. Idle mode cannot be enabled when the noise gate function is also enabled.	0: Idle mode disabled. 1: Idle mode enabled.
NOISEGATE _EN	0	Enables the noise gate.	Noise gate disabled. Noise gate enabled.

Clock Monitor Control (0x2038)

BIT	7	6	5	4	3	2	1	0
Field	_	СМ	ON_BSELTOL	[2:0]	CM	CMON_AU TORESTAR T_EN		
Reset	-		0b0		0x0			0x0
Access Type	_		Write, Read		Write, Read			Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
CMON_BSE LTOL	6:4	The number of frames of incorrect or correct clock ratio (BCLKs per LRCLK) needed to trigger or recover from a framing error.	0x0: Trigger after 1 incorrect LRCLK frame, recover after 1 correct LRCLK frame. 0x1: Trigger after 2 incorrect LRCLK frames, recover after 16 correct LRCLK frames. 0x2: Trigger after 3 incorrect LRCLK frames, recover after 24 correct LRCLK frame. 0x3: Trigger after 4 incorrect LRCLK frames, recover after 32 correct LRCLK frames. 0x4: Trigger after 5 incorrect LRCLK frames, recover after 40 correct LRCLK frames. 0x5: Trigger after 6 incorrect LRCLK frames, recover after 48 correct LRCLK frames. 0x6: Trigger after 7 incorrect LRCLK frames, recover after 56 correct LRCLK frames, recover after 56 correct LRCLK frames. 0x7: Trigger after 8 incorrect LRCLK frames, recover after 64 correct LRCLK frames.

BITFIELD	BITS	DESCRIPTION	DECODE
CMON_ERR TOL	3:1	Selects the number of incorrect or correct LRCLK periods needed to trigger or recover from a frame clock rate error.	0x0: Trigger after 1 incorrect LRCLK frame, recover after 1 correct LRCLK frame. 0x1: Trigger after 2 incorrect LRCLK frames, recover after 16 correct LRCLK frames. 0x2: Trigger after 3 incorrect LRCLK frames, recover after 24 correct LRCLK frames. 0x3: Trigger after 4 incorrect LRCLK frames, recover after 32 correct LRCLK frames. 0x4: Trigger after 5 incorrect LRCLK frames, recover after 40 correct LRCLK frames. 0x5: Trigger after 6 incorrect LRCLK frames, recover after 48 correct LRCLK frames. 0x6: Trigger after 7 incorrect LRCLK frames, recover after 56 correct LRCLK frames, recover after 56 correct LRCLK frames. 0x7: Trigger after 8 incorrect LRCLK frames, recover after 64 correct LRCLK frames.
CMON_AUT ORESTART_ EN	0	Controls whether or not the device automatically resumes playback when the clocks become valid after the device is disabled due to a clock monitor error.	O: Device does not automatically restart after valid clocks are reapplied. 1: Device automatically restarts after valid clocks are reapplied.

Data Monitor Control (0x2039)

BIT	7	6	5	4	3	2	1	0
Field	_	ı	DMON_MAG_THRES[1:0]		DMON_STUCK_THRES[1 :0]		DMON_DURATION[1:0]	
Reset	_	_	0>	×0	0x0		0>	(0
Access Type	_	ı	Write, Read		Write, Read		Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
DMON_MAG _THRES	5:4	Sets the data magnitude error threshold that the input PCM amplitude level is compared against. If the input signal is above this threshold for longer than the DMON_DURATION, a data monitor error is asserted.	0x0: -30.1030dB (5 bits) 0x1: -24.0824dB (4 bits) 0x2: -18.0618dB (3 bits) 0x3: -12.0412dB (2 bits)
DMON_STU CK_THRES	3:2	Sets the data stuck error threshold that the input PCM amplitude level is compared against. If the input signal is stuck at the same value above this threshold for longer than the DMON_DURATION, a data monitor error is asserted.	0x0: 15-bits (-90.3090 dBFS) 0x1: 13-bits (-78.2678 dBFS) 0x2: 11-bits (-66.2266 dBFS) 0x3: 9-bits (-54.1854 dBFS)
DMON_DUR ATION	1:0	Sets the time duration over which the data monitor must consecutively detect erroneous input PCM data before asserting a data monitor error.	0x0: 64ms 0x1: 256ms 0x2: 1024ms 0x3: 4096ms

Speaker Monitor Threshold (0x203A)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	SPKMON_THRESH[3:0]			
Reset	_	_	_	_	0x3			
Access Type	_	_	_	_	Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
SPKMON_T HRESH	3:0	Sets the speaker power threshold. If the signal power recovered by the circuit is above this threshold, the speaker monitor error is asserted. Minimum threshold is 0.25V and maximum is 4V, 0.25V per step.	0x0: 0.25V 0x1: 0.5V 0.25V per step 0xE: 3.75V 0xF: 4.0V

Enable Controls (0x203F)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	SPKMON_ EN	DMON_MA G_EN	DMON_ST UCK_EN	CMON_EN
Reset	_	_	_	_	0x1	0x1	0x1	0x1
Access Type	_	_	_	_	Write, Read	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE		
SPKMON_E N	3	Enables the internal speaker protection monitor.	0x0: Disable internal speaker data monitor. 0x1: Enable internal speaker data monitor.		
DMON_MAG _EN	2	Enables the data monitor circuit to monitor PCM input data for large magnitude (DC) audio.	Data magnitude check disabled. Data magnitude check enabled.		
DMON_STU CK_EN	1	Enables the data monitor circuit to monitor PCM input for stuck data.	Data stuck-at monitor disabled. Data stuck-at monitor enabled.		
CMON_EN	0	Enables the clock monitor to monitor PCM input clocks for clock errors.	Clock monitor disabled. Clock monitor enabled.		

Pin Config (0x2040)

BIT	7	6	5	4	3	2	1	0
Field	LV_EN_DRV[1:0]		ICC_DRV[1:0]		IRQ_DRV[1:0]		DOUT_DRV[1:0]	
Reset	0x1		0x1		0x1		0>	c 1
Access Type	Write,	Read	Write, Read		Write,	Read	Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
LV_EN_DRV	7:6	Configures the output drive strength of the LV_EN pin.	0x0: Reduced drive mode. 0x1: Normal drive mode. 0x2: High drive mode. 0x3: Maximum drive mode.
ICC_DRV	5:4	Configures the output drive strength of the ICC pin.	00: Reduced drive mode. 01: Normal drive mode. 10: High drive mode. 11: Maximum drive mode.

BITFIELD	BITS	DESCRIPTION	DECODE		
IRQ_DRV	3:2	Configures the output drive strength of the IRQ pin.	00: Reduced drive mode.01: Normal drive mode.10: High drive mode.11: Maximum drive mode.		
DOUT_DRV	1:0	Configures the output drive strength of the DOUT pin.	00: Reduced drive mode. 01: Normal drive mode. 10: High drive mode. 11: Maximum drive mode.		

PCM Mode Config (0x2041)

BIT	7	6	5	4	3	2	1	0
Field	PCM_CHANSZ[1:0]		PCM_FORMAT[2:0]			PCM_TX_I NTERLEAV E	PCM_CHA NSEL	PCM_TX_E XTRA_HIZ
Reset	0x3		0x0		0x0	0b0	0b0	
Access Type	Write, Read			Write, Read		Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_CHAN SZ	7:6	Configures the PCM data word size for each channel.	00: Reserved 01: 16-bit 10: 24-bit 11: 32-bit
PCM_FORM AT	5:3	Selects the PCM data format.	0x0: I2S Mode 0x1: Left-justified 0x2: Reserved 0x3: TDM Mode 0 (0 BCLK delay from LRCLK) 0x4: TDM Mode 1 (1 BCLK delay from LRCLK) 0x5: TDM Mode 2 (2 BCLK delay from LRCLK) 0x6 to 0x7: Reserved
PCM_TX_IN TERLEAVE	2	Controls whether or not I/V sense data assigned to the same channel is frame interleaved on the PCM data output (DOUT).	Disable Interleave mode. Enable Interleave mode.
PCM_CHAN SEL	1	Selects which LRCLK edge starts a new frame (channel 0 or slot 0).	O: I ² S and LJ mode: Falling LRCLK edge starts a new frame. In TDM modes: Rising LRCLK edge starts a new frame. 1: In I ² S and LJ mode: Rising LRCLK edge starts a new frame. In TDM modes: Falling LRCLK edge starts a new frame.
PCM_TX_EX TRA_HIZ	0	Select whether DOUT is driven to zero or Hi-Z during extra BCLK cycles.	Drive DOUT to zero for extra BCLK cycles. Drive DOUT to Hi-Z for extra BCLK cycles.

PCM Clock Setup (0x2042)

BIT	7	6	5	4	3	2	1	0	
Field	_	1	_	PCM_BCLK EDGE	PCM_BSEL[3:0]				
Reset	_	_	-	0b0	0x4				
Access Type	_	_	_	Write, Read	Write, Read				

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_BCLKE DGE	4	Selects the active BCLK edge.	O: Input data captured and output data valid on rising edge of BCLK. 1: Input data captured and output data valid on falling edge of BCLK.
PCM_BSEL	3:0	Selects the number of BCLKs per LRCLK expected by the PCM Interface.	0x0: Reserved 0x1: Reserved 0x2: 32 0x3: 48 0x4: 64 0x5: 96 0x6: 128 0x7: 192 0x8: 256 0x9: 384 0xA: 512 0xB: 320 0xC: 250 0xD: 125 0xE to 0xF: Reserved

PCM Sample Rate Setup 1 (0x2043)

BIT	7	6	5	4	3	2	1	0	
Field		IVADC_	SR[3:0]		PCM_SR[3:0]				
Reset		0:	x8		0x8				
Access Type		Write,	Read			Write,	Read		

BITFIELD	BITS	DESCRIPTION	DECODE
IVADC_SR	7:4	Sets the sample rate of the I/V Sense ADC path.	0x0: 8kHz 0x1: 11.025kHz 0x2: 12kHz 0x3: 16kHz 0x4: 22.05kHz 0x5: 24kHz 0x6: 32kHz 0x7: 44.1kHz 0x8: 48kHz 0x9: 88.2kHz 0xA: 96kHz 0xB: 176.4kHz 0xC: 192kHz 0xD to 0xF: Reserved

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_SR	3:0	Sets the sample rate of the PCM interface. This corresponds to the expected LRCLK frequency.	0x0: 8kHz 0x1: 11.025kHz 0x2: 12kHz 0x3: 16kHz 0x4: 22.05kHz 0x5: 24kHz 0x6: 32kHz 0x7: 44.1kHz 0x8: 48kHz 0x9: 88.2kHz 0xA: 96kHz 0xB: 176.4kHz 0xC: 192kHz 0xD to 0xF: Reserved

PCM TX Control 1 (0x2044)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	PCM_VMON_SLOT[5:0]						
Reset	_	_		0x0					
Access Type	-	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE		
PCM_VMON _SLOT	5:0	Selects the data output (DOUT) slots for the voltage sense output data. In non-TDM mode, only Slot 0/1 and Slot 1/2 are valid.	0x0: Slot 00/01 0x1: Slot 01/02 0x2: Slot 02/03 0x22 to 0x3D: 0x3E: Slot 62/63 0x3F: Reserved		

PCM TX Control 2 (0x2045)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	PCM_IMON_SLOT[5:0]						
Reset	_	_		0x0					
Access Type	_	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_IMON_ SLOT	5:0	IMON Data Output Slot Select. IMON data requires two slots. In non-TDM mode, only Slot 0/1 and Slot 1/2 are valid.	0x0: Slot 00/01 0x1: Slot 01/02 0x2: Slot 02/03 0x22 to 0x3D: 0x3E: Slot 62/63 0x3F: Reserved

PCM TX Control 3 (0x2046)

BIT	7	6	5	4	3	2	1	0	
Field	1	_	PCM_SUPPLY1_SLOT[5:0]						
Reset	-	-		0x0					
Access Type	_	-			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE		
PCM_SUPPL Y1_SLOT	5:0	PCM Slot Select for Supply1 Measurement ADC Data (ADC) Output. Supply1 ADC data requires two slots.	0x0: Slot 00/01 0x1: Slot 01/02 0x2: Slot 02/03 0x22 to 0x3D: 0x3E: Slot 62/63 0x3F: Reserved		

PCM TX Control 4 (0x2047)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	PCM_SUPPLY2_SLOT[5:0]						
Reset	_	_		0x0					
Access Type	_	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_SUPPL Y2_SLOT	5:0	PCM Slot Select for Supply2 Measurement ADC Data (ADC) Output. Supply2 ADC data requires two slots.	0x0: Slot 00/01 0x1: Slot 01/02 0x2: Slot 02/03 0x22 to 0x3D: 0x3E: Slot 62/63 0x3F: Reserved

PCM TX Control 5 (0x2048)

BIT	7	6	5	4	3	2	1	0	
Field	_	_		PCM_DHT_ATN_SLOT[5:0]					
Reset	-	-		0x0					
Access Type	_	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_DHT_A TN_SLOT	5:0	DHT Attenuation Data Output Slot Select. DHT Attenuation data requires two slots.	0x0: Slot 00/01 0x1: Slot 01/02 0x2: Slot 02/03 0x22 to 0x3D: 0x3E: Slot 62/63 0x3F: Reserved

PCM TX Control 6 (0x2049)

BIT	7	6	5	4	3	2	1	0	
Field	_	_		PCM_STATUS_SLOT[5:0]					
Reset	_	_		0x0					
Access Type	_	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_STATU S_SLOT	5:0	Device Status Data Output Slot Select. Device status requires two slots.	0x00: Slot 00/01 0x01: Slot 01/02 0x02 to 0x3D: 0x3E: Slot 62/63 0x3F: Reserved

PCM TX Control 7 (0x204A)

BIT	7	6	5	4	3	2	1	0	
Field	_	_		PCM_DSP_MONITOR_SLOT[5:0]					
Reset	_	_		0x0					
Access Type	_	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_DSP_ MONITOR_S LOT	5:0	DSP Monitor Data Output Slot Select. DSP montior data requires 4 slots.	0x0: Slot 00/01/02/03 0x1: Slot 01/02/03/04 0x2: Slot 02/03/04/05 0x3 to 0x3B: 0x3C: Slot 60/61/62/63 0x3D: Reserved 0x3E: Reserved 0x3F: Reserved

PCM TX Control 8 (0x204B)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	PCM_BPE_SLOT[5:0]						
Reset	_	_		0x0					
Access Type	_	_		Write, Read					

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_BPE_S LOT	5:0	BPE State Output Slot Select. BPE state requires one slot.	0x0: Slot 00 0x1: Slot 01 0x2: Slot 02 0x22 to 0x3D: 0x3E: Slot 62 0x3F: Slot 62

PCM TX Control 9 (0x204C)

BIT	7	6	5	4	3	2	1	0	
Field	_	_		PCM_THERM_SLOT[5:0]					
Reset	_	_		0x0					
Access Type	_	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_THER M_SLOT	5:0	PCM Slot Select for Thermal Measurement ADC Data (ADC) Output. Thermal ADC data requires two slots.	0x0: Slot 00/01 0x1: Slot 01/02 0x2: Slot 02/03 0x22 to 0x3D: 0x3E: Slot 62/63 0x3F: Reserved

PCM TX Control 10 (0x204D)

BIT	7	6	5	4	3	2	1	0	
Field	_	_		PCM_ICC_SLOT[5:0]					
Reset	_	_		0x0					
Access Type	_	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_ICC_S LOT	5:0	Selects the data output (DOUT) slots for the ICC output data. In non-TDM mode, only Slot 00/01 and Slot 01/02 are valid. If IV _{SENSE} is enabled, ICC over DOUT only works when PCM_CHANSZ is set to 32 bits, PCM_TX_INTERLEAVE is enabled, and PCM_ICC_SLOT is set to the same as PCM_VMON_SLOT. In TDM mode, the ICC needs 3 slots. PCM_CHANSZ has to be greater than 16 bits, and the PCM_ICC_SLOT has to set in a number that is shown below: If PCM_CHANSZ = 24 bits, then PCM_ICC_SLOT is divisible by 3. If PCM_CHANSZ = 32 bits, then PCM_ICC_SLOT is divisible by 4.	0x0: Slot 00/01 0x1: Slot 01/02 0x2: Slot 02/03 0x22 to 0x3D: 0x3E: Slot 62/63 0x3F: Reserved

PCM Tx HiZ Control 1 (0x204E)

BIT	7	6	5	4	3	2	1	0	
Field		PCM_TX_SLOT_HIZ[63:56]							
Reset		0xFF							
Access Type				Write,	Read				

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_TX_SL OT_HIZ	7:0	Configures the unused PCM data output slots to transmit either Hi-Z or 0.	Value: Decode 0: Output 0 on idle slots from 63 to 56. 1: Output Hi-Z on slots from 63 to 56.

PCM Tx HiZ Control 2 (0x204F)

BIT	7	6	5	4	3	2	1	0	
Field		PCM_TX_SLOT_HIZ[55:48]							
Reset		0xFF							
Access Type				Write,	Read				

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_TX_SL OT_HIZ	7:0	Configures the unused PCM slots to set them to Hi-Z or 0.	0: Output 0 on idle slots from 55 to 48. 1: Output Hi-Z on slots from 55 to 48.

PCM Tx HiZ Control 3 (0x2050)

BIT	7	6	5	4	3	2	1	0	
Field		PCM_TX_SLOT_HIZ[47:40]							
Reset		0xFF							
Access Type				Write,	Read				

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_TX_SL OT_HIZ	7:0	Configures the unused PCM slots to set them all to Hi-Z or 0.	0: Output 0 on idle slots from 47 to 40. 1: Output Hi-Z on slots from 47 to 40.

PCM Tx HiZ Control 4 (0x2051)

BIT	7	6	5	4	3	2	1	0	
Field		PCM_TX_SLOT_HIZ[39:32]							
Reset		0xFF							
Access Type		Write, Read							

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_TX_SL OT_HIZ	7:0	Configures the unused PCM slots to set them all to Hi-Z or 0.	0: Output 0 on idle slots from 39 to 32. 1: Output Hi-Z on slots from 39 to 32.

PCM Tx HiZ Control 5 (0x2052)

BIT	7	6	5	4	3	2	1	0	
Field		PCM_TX_SLOT_HIZ[31:24]							
Reset		0xFF							
Access Type				Write,	Read				

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_TX_SL OT_HIZ	7:0	Configures the unused PCM slots to set them all to Hi-Z or 0.	0: Output 0 on slots from 31 to 24. 1: Output Hi-Z on idle slots from 31 to 24.

PCM Tx HiZ Control 6 (0x2053)

BIT	7	6	5	4	3	2	1	0	
Field		PCM_TX_SLOT_HIZ[23:16]							
Reset		0xFF							
Access Type				Write,	Read				

BITFIELD	ELD BITS DESCRIPTION		DECODE
PCM_TX_SL OT_HIZ	7:0	Configures the unused PCM slots to set them all to Hi-Z or 0.	0: Output 0 on idle slots from 23 to 16. 1: Output Hi-Z on slots from 23 to 16.

PCM Tx HiZ Control 7 (0x2054)

BIT	7	6	5	4	3	2	1	0		
Field		PCM_TX_SLOT_HIZ[15:8]								
Reset		0xFF								
Access Type				Write,	Read					

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_TX_SL OT_HIZ	7:0	Configures the unused PCM slots to set them all to Hi-Z or 0.	0: Output 0 on slots from 15 to 8. 1: Output Hi-Z on idle slots from 15 to 8.

PCM Tx HiZ Control 8 (0x2055)

BIT	7	6	5	4	3	2	1	0		
Field		PCM_TX_SLOT_HIZ[7:0]								
Reset		0xFF								
Access Type		Write, Read								

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_TX_SL OT_HIZ	7:0	Configures the unused PCM slots to set them all to Hi-Z or 0.	0: Output 0 on idle slots from 7 to 0. 1: Output Hi-Z on slots from 7 to 0.

PCM RX Source 1 (0x2057)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	PCM_DMMIX_CFG[1:0]	
Reset	_	-	-	_	-	_	0x0	
Access Type	_	-	_	_	_	_	Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_DMMI X_CFG	1:0	Determines the behavior of the mono mixer circuit.	0x0: Output of monomixer is Channel 0. 0x1: Output of monomixer is Channel 1. 0x2: Output of monomixer is (Channel 0 +Channel1)/2. 0x3: Reserved

PCM RX Source 2 (0x2058)

BIT	7	6	5	4	3	2	1	0	
Field	PC	CM_DMMIX_CH	H1_SOURCE[3	3:0]	PCM_DMMIX_CH0_SOURCE[3:0]				
Reset		0)	c 1		0x0				
Access Type		Write,	Read			Write,	Read		

BITFIELD	BITS	DESCRIPTION	DECODE		
PCM_DMMI X_CH1_SOU RCE	7:4	Selects the PCM data input channel that is routed to the channel 1 of the digital mono mixer.	0x0: PCM Input Channel 0 0x1: PCM Input Channel 1 0x2: PCM Input Channel 2: 0xE: PCM Input Channel 14 0xF: PCM Input Channel 15		
PCM_DMMI X_CH0_SOU RCE	3:0	Selects the PCM data input channel that is routed to the channel 0 of the digital mono mixer.	0x0: PCM Input Channel 0 0x1: PCM Input Channel 1 0x2: PCM Input Channel 2: 0xE: PCM Input Channel 14 0xF: PCM Input Channel 15		

PCM Bypass Source (0x2059)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	PCM_BYPASS_SOURCE[3:0]			
Reset	-	_	_	_	0x0			
Access Type	_	-	_	_	Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_BYPA SS_SOURC E	3:0	Selects the PCM data input channel that is routed to the speaker audio processing bypass path.	0x0: PCM Input Channel 0 0x1: PCM Input Channel 1 0x2: PCM Input Channel 2: 0xE: PCM Input Channel 14 0xF: PCM Input Channel 15

PCM TX Source Enables (0x205C)

BIT	7	6	5	4	3	2	1	0
Field	PCM_BPE_ EN	PCM_STAT US_EN	PCM_DHT_ ATN_EN	PCM_SUPP LY2_EN	PCM_SUPP LY1_EN	PCM_DSP MONITOR_ EN	PCM_IMON _EN	PCM_VMO N_EN
Reset	0x0	0x0	0x0	0x0	0x0	0x0	0x0	0x0
Access Type	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_BPE_E N	7	Enables transmit of the Brownout-Prevention Engine (BPE) state on the assigned data output (DOUT) slot. This output data can be transmitted only in TDM mode.	0: Disable BPE state transmit. 1: Enable BPE state transmit.
PCM_STATU S_EN	6	Enables transmit of the device status on the assigned data output (DOUT) slots. This output data can be transmitted only in TDM mode.	Disable device status transmit. Enable device status transmit.
PCM_DHT_A TN_EN	5	Enables transmit of the applied DHT attenuation on the assigned data output (DOUT) slot. This output data can be transmitted only in TDM mode.	Disable DHT attenuation data transmit. Enable DHT attenuation data transmit.
PCM_SUPPL Y2_EN	4	Enables transmit of the measured VBAT supply voltage on the assigned data output (DOUT) slot. This output data can be transmitted only in TDM mode.	Disable VBAT supply voltage data transmit. Enable VBAT supply voltage data transmit.
PCM_SUPPL Y1_EN	3	Enables transmit of the measured PVDD supply voltage on the assigned data output (DOUT) slot. This output data can be transmitted only in TDM mode.	Disable PVDD supply voltage data transmit. Enable PVDD supply voltage data transmit.
PCM_DSPM ONITOR_EN	2	Enables transmit of the playback path DSP output data on the assigned data output (DOUT) slot.	Disable playback path data transmit. Enable playback path data transmit.
PCM_IMON_ EN	1	Enables transmit of the current sense output data on the assigned data output (DOUT) slot.	Disable current sense data transmit. Enable current sense data transmit.
PCM_VMON _EN	0	Enables transmit of the voltage sense output data on the assigned data output (DOUT) slot.	Disable voltage sense data transmit. Enable voltage sense data transmit.

PCM TX Source Enables 2 (0x205D)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	PCM_THER M_EN
Reset	_	-	-	_	-	_	-	0x0
Access Type	_	_	_	_	_	_	_	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_THER M_EN	0	Enables transmit of the measured temperature on the assigned data output (DOUT) slot. This output data can be transmitted only in TDM mode.	Disable temperature data transmit. Enable temperature data transmit.

PCM Rx Enables (0x205E)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	-	_	PCM_BYP_ EN	PCM_RX_E N
Reset	_	_	_	_	-	_		0b0
Access Type	_	_	-	_	-	_	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_BYP_E N	1	Enables the PCM data input to the speaker amplifier via the bypass path. This path bypasses the speaker playback path audio processing features like volume control, gains, DHT, BPE, and thermal foldback.	0x0: Audio processing bypass path disabled. 0x1: Audio processing bypass path enabled.
PCM_RX_E N	0	Enables the speaker amplifier playback path.	PCM data input disabled. PCM data input enabled.

PCM Tx Enables (0x205F)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	PCM_TX_E N
Reset	-	-	-	-	-	-	-	0b0
Access Type	_	_	_	_	_	_	_	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
PCM_TX_EN	0	Enables the data output (DOUT) of the PCM interface.	PCM data output disabled. PCM data output enabled.

PCM Tx Supply Select (0x2060)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	_	_	_	_	SUPPLY_SELECT[1:0]		
Reset	_	_	_	_	-	_	Ob	0b0	
Access Type	_	-	_	-	П	_	Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
SUPPLY_SE LECT	1:0	Supply selection for the measurement ADC output to be sent on the DOUT channel.	0: PCM data output disabled. 1: PCM data output enabled.

ICC Rx Enables A (0x2070)

BIT	7	6	5	4	3	2	1	0
Field	ICC_RX_C H7_EN	ICC_RX_C H6_EN	ICC_RX_C H5_EN	ICC_RX_C H4_EN	ICC_RX_C H3_EN	ICC_RX_C H2_EN	ICC_RX_C H1_EN	ICC_RX_C H0_EN
Reset	0b0							
Access Type	Write, Read							

BITFIELD	BITS	DESCRIPTION	DECODE
ICC_RX_CH 7_EN	7	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 7 is disabled. 1: ICC receive channel 7 is enabled.
ICC_RX_CH 6_EN	6	Configures whether or not the ICC interface accepts data from this channel.	O: ICC receive channel 6 is disabled. ICC receive channel 6 is enabled.
ICC_RX_CH 5_EN	5	Configures whether or not the ICC interface accepts data from this channel.	O: ICC receive channel 5 is disabled. ICC receive channel 5 is enabled.
ICC_RX_CH 4_EN	4	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 4 is disabled. 1: ICC receive channel 4 is enabled.
ICC_RX_CH 3_EN	3	Configures whether or not the ICC interface accepts data from this channel.	O: ICC receive channel 3 is disabled. ICC receive channel 3 is enabled.
ICC_RX_CH 2_EN	2	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 2 is disabled. 1: ICC receive channel 2 is enabled.
ICC_RX_CH 1_EN	1	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 1 is disabled. 1: ICC receive channel 1 is enabled.
ICC_RX_CH 0_EN	0	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 0 is disabled. 1: ICC receive channel 0 is enabled.

ICC Rx Enables B (0x2071)

BIT	7	6	5	4	3	2	1	0
Field	ICC_RX_C H15_EN	ICC_RX_C H14_EN	ICC_RX_C H13_EN	ICC_RX_C H12_EN	ICC_RX_C H11_EN	ICC_RX_C H10_EN	ICC_RX_C H9_EN	ICC_RX_C H8_EN
Reset	0b0	0b0	0b0	0b0	0b0	0b0	0b0	0b0
Access Type	Write, Read	Write, Read	Write, Read					

BITFIELD	BITS	DESCRIPTION	DECODE		
ICC_RX_CH 15_EN	7	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 15 is disabled. 1: ICC receive channel 15 is enabled.		
ICC_RX_CH 14_EN	6	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 14 is disabled. 1: ICC receive channel 14 is enabled.		
ICC_RX_CH 13_EN	5	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 13 is disabled. 1: ICC receive channel 13 is enabled.		
ICC_RX_CH 12_EN	4	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 12 is disabled. 1: ICC receive channel 12 is enabled.		
ICC_RX_CH 11_EN	3	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 11 is disabled. 1: ICC receive channel 11 is enabled.		
ICC_RX_CH 10_EN	2	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 10 is disabled. 1: ICC receive channel 10 is enabled.		
ICC_RX_CH 9_EN	1	Configures whether or not the ICC interface accepts data from this channel.	0: ICC receive channel 9 is disabled. 1: ICC receive channel 9 is enabled.		

BITFIELD	BITS	DESCRIPTION	DECODE
ICC_RX_CH 8_EN	0	Configures whether or not the ICC interface accepts data from this channel.	O: ICC receive channel 8 is disabled. ICC receive channel 8 is enabled.

ICC Tx Control (0x2072)

BIT	7	6	5	4	3	2	1	0
Field	_	ICC_INTER LEAVE_MO DE	ICC_DATA_ SEL	_		ICC_TX_I	DEST[3:0]	
Reset	_	0x0	0x0	_		0:	x0	
Access Type	_	Write, Read	Write, Read	_		Write,	Read	

BITFIELD	BITS	DESCRIPTION	DECODE
ICC_INTERL EAVE_MOD E	6	Select whether the ICC pin transmits DHT and thermal foldback data in interleaving fashion when the PCM data word size (data width) is only 16-bits. This has no effect when the data word size is 24- or 32-bits.	0: ICC transmits either DHT or thermal data based on ICC_DATA_SEL. 1: ICC transmits in interleaved mode which DHT and thermal data are sent alternatively.
ICC_DATA_ SEL	5	Select whether the ICC pin transmits DHT or thermal foldback data when the PCM data word size (data width) is only 16-bits. This has no effect when the data word size is 24-or 32-bits.	0: ICC transmits DHT data + BPE state. 1: ICC transmits thermal foldback data + BPE state. state.
ICC_TX_DE ST	3:0	Selects the device transmit channel for ICC data.	0x0: ICC Channel 0 0x1: ICC Channel 1 0xE: ICC Channel 14 0xF: ICC Channel 15

ICC Enables (0x207F)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	ICC_OVER _DOUT_EN		ICC_TX_EN
Reset	_	_	_	_	_	0b0	0b0	0x0
Access Type	_	_	_	_	_	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
ICC_OVER_ DOUT_EN	2	Enables ICC link data sent over the PCM DOUT pin.	ICC link over DOUT disabled. ICC link over DOUT enabled.
ICC_LINK_E N	1	Enables ICC link between devices.	0: ICC link disabled. 1: ICC link enabled.
ICC_TX_EN	0	Select whether the ICC pin transmitter is enabled/disabled.	ICC transmit disabled. ICC transmit enabled.

Tone Generator and DC Config (0x2083)

BIT	7	6	5	4	3	2	1	0
Field	_	_	TONE_AMP	LITUDE[1:0]	TONE_CONFIG[3:0]			
Reset	_	_	0x0		0x4			
Access Type	_	_	Write,	Write, Read		Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
TONE_AMPL ITUDE	5:4	Sets the sine wave amplitude. This register is not used when programming the tone generator to output DC signals.	0x0: -6dBFS 0x1: -4.8dBFS 0x2: 0dBFS 0x3: Reserved
TONE_CON FIG	3:0	Configures the output of the tone generator. For signal outputs, the frequency is a division of the sample rate (f _S).	0x0: DC value programmed by TONE_DC[23:0] 0x1: DC = 0x0000 = 0 0x2: DC = +FullScale/2 0x3: DC = -FullScale/2 0x4: 1kHz tone at all sample rates 0x5: fs/4 0x6: fs/6 0x7 to 0xF: Reserved

Tone Generator DC Level 1 (0x2084)

BIT	7	6	5	4	3	2	1	0
Field		TONE_DC[23:16]						
Reset		0x0						
Access Type		Write, Read						

BITFIELD	BITS	DESCRIPTION
TONE_DC	7:0	Sets the tone generator DC output level as a signed binary relative to full-scale.

Tone Generator DC Level 2 (0x2085)

BIT	7	6	5	4	3	2	1	0
Field		TONE_DC[15:8]						
Reset		0x0						
Access Type		Write, Read						

BITFIELD	BITS	DESCRIPTION
TONE_DC	7:0	Sets the tone generator DC output level as a signed binary relative to full-scale.

Tone Generator DC Level 3 (0x2086)

BIT	7	6	5	4	3	2	1	0	
Field		TONE_DC[7:0]							
Reset		0x0							
Access Type				Write,	Read				

BITFIELD	BITS	DESCRIPTION
TONE_DC	7:0	Sets the tone generator DC output level as a signed binary relative to full-scale.

Tone Generator Enable (0x208F)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	PINK_NOIS E_EN	TONE_EN
Reset	_	_	_	_	_	_	0b0	0b0
Access Type	_	_	_	_	_	_	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
PINK_NOISE _EN	1	Enables pink noise data output to the speaker amplifier path.	Pink noise disabled. Pink noise enabled.
TONE_EN	0	Enables the tone generator. When enabled, it replaces the PCM interface as the input to the speaker amplifier path.	0: Tone generator disabled. 1: Tone generate enabled.

AMP volume control (0x2090)

BIT	7	6	5	4	3	2	1	0
Field				SPK_V	OL[7:0]			
Reset				0>	k 0			
Access Type				Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_VOL	7:0	Sets the digital volume level of the speaker amplifier path.	0x00: 0dB 0x01: -0.5dB 0x02: -1.0dB : (-0.5dB steps) 0x7C: -62.0dB 0x7D: -62.5dB 0x7E: -63dB : (-0.5dB steps) 0xB4: -90dB 0xB5 - 0xFE: Reserved 0xFF: Mute

AMP Path Gain (0x2091)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	SPK_GAIN_MAX[4:0]				
Reset	_	_	_	0x12				
Access Type	_	_	_			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_GAIN_ MAX	4:0	Sets the maximum peak output voltage level (V _{MPO}) for the speaker path (no-load). Values in dB are relative to the baseline speaker path DAC full-scale output level of 0.49dBV.	0x00: 2.98V _P (6dB) 0x01: 3.35V _P (7dB) 0x02: 3.76V _P (8dB) 0x03: 4.22V _P (9dB) 0x04: 4.73V _P (10dB) 0x05: 5.31V _P (11dB) 0x06: 5.96V _P (12dB) 0x07: 6.68V _P (13dB) 0x08: 7.50V _P (14dB) 0x09: 8.41V _P (15dB) 0x0A: 9.44V _P (16dB) 0x0B: 10.59V _P (17dB) 0x0C: 11.88V _P (18dB) 0x0D: 13.33V _P (19dB) 0x0E: 14.96V _P (20dB) 0x0F: 16.79V _P (21dB) 0x10: 18.83V _P (22dB) 0x11: 21.13V _P (23dB) 0x12: 23.71V _P (24dB) 0x13: 26.60V _P (25dB) 0x14: 29.85V _P (26dB) 0x15: 33.49V _P (27dB) 0x16-0x1F: Reserved

AMP DSP Config (0x2092)

BIT	7	6	5	4	3	2	1	0
Field	_	SPK_WBA ND_FILT_E N	SPK_SAFE _EN	SPK_VOL_ RMPDN_B YPASS	SPK_VOL_ RMPUP_BY PASS	SPK_INVE RT	SPK_DITH_ EN	SPK_DCBL K_EN
Reset	_	0x0	0x1	0b0	0b0	0b0	0b1	0b1
Access Type	_	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_WBAN D_FILT_EN	6	Enables the wideband filters in the speaker amplifier path with increased passband for sample rates higher than 50kHz.	Higher passband filters disabled. Higher passband filters enabled.
SPK_SAFE_ EN	5	The safe mode bit protects any speaker connected to the device on power-up. When this setting is enabled, the SPK_VOL and SPK_GAIN_MAX settings are ignored, and the amplifier output is set to -18dBFS.	Speaker safe mode disabled. Speaker safe mode enabled.
SPK_VOL_R MPDN_BYP ASS	4	Controls whether the speaker amplifier path volume is internally ramped down during shutdown and during volume changes.	0: Volume ramp enabled. 1: Volume ramp bypassed.

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_VOL_R MPUP_BYP ASS	3	Controls whether the speaker amplifier path volume is internally ramped up during startup and during volume changes.	Volume ramp enabled. Volume ramp bypassed.
SPK_INVER T	2	Inverts the speaker amplifier path output.	O: Output is normal. Output is inverted.
SPK_DITH_ EN	1	Selects whether or not dither is applied to data in the speaker amplifier path.	0: Dither disabled. 1: Dither enabled.
SPK_DCBLK _EN	0	Controls the DC blocking filter in the speaker amplifier path.	DC blocking filter disabled. DC blocking filter enabled.

SSM Configuration (0x2093)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	TRI_SSM_ EN	_	TRI_SSM_MOD[1:0]	
Reset	_	_	_	_	0x1	_	0x0	
Access Type	_	_	_	_	Write, Read	_	Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
TRI_SSM_E N	3	Enables spread-spectrum clocking in the triangle wave generator.	Spread-spectrum clocking is disabled. Spread-spectrum clocking is enabled.
TRI_SSM_M OD	1:0	Selects the modulation index for the Class-D amplifier's triangle wave spread-spectrum clock.	0x0: ±1.5% variation 0x1: ±3.0% variation 0x2: ±4.5% variation 0x3: ±6.0% variation

SPK Class DG Threshold (0x2094)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	_	SPK_DG_THRES[4:0]					
Reset	_	_	_		0x12				
Access Type	_	-	-			Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_DG_TH RES	4:0	Sets the DG mode fixed peak signal level threshold (active when SPK_DG_SEL = 0x0 or 0x2).	0x00: 3.8V 0x01: 3.7V 0x02: 3.6V 0x03 to 0x1D: (0.1V steps) 0x1E: 0.8V 0x1F: 0.7V

SPK Class DG Headroom (0x2095)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	SPK_DG_SEL[1:0]		SPK_DG_HEADROOM[3:0]				
Reset	_	_	0x1		0x7				
Access Type	-	_	Write,	Read		Write,	Read		

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_DG_SE L	5:4	Selects the method used for speaker amplifier DG mode operation.	0x0: Class-DG mode uses a fixed peak signal level threshold (SPK_DG_THRES). 0x1: Class-DG mode uses supply headroom relative to measured VBAT voltage (SPK_DG_HEADROOM). 0x2: Class-DG mode uses the lower of fixed peak signal level threshold (SPK_DG_THRES) and VBAT supply headroom (SPK_DG_HEADROOM). 0x3: Reserved
SPK_DG_HE ADROOM	3:0	Sets the DG mode headroom relative to the measured V _{VBAT} supply level (active when SPK_DG_SEL = 0x1 or 0x2).	0x0: 0V 0x1: 0.25V 0x2: 0.5V 0x3 to 0xD: (0.25V steps) 0xE: 3.5V 0xF: 3.75V

SPK Class DG Hold Time (0x2096)

BIT	7	6	5	4	3	2	1	0	
Field	_	SPK_0	OG_PEAK_HY	ST[2:0]	SPK_DG_HOLD_TIME[3:0]				
Reset	_		0x1			0x7			
Access Type	_		Write, Read			Write,	Read		

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_DG_PE AK_HYST	6:4	Sets the signal peak hysteresis relative to the measured V _{VBAT} supply level. To switch from D to G, signal peak must be less than VBAT - hysteresis.	0x0: 0.5dB 0x1: 1.0dB 0x2: 1.5dB 0x3: 2.0dB 0x4: 2.5dB 0x5: 3.0dB 0x6: 4.0dB 0x7: 5.0dB
SPK_DG_H OLD_TIME	3:0	Sets the speaker amplifier DG mode hold time. When the peak signal level falls below the DG mode threshold for longer than this time, VBAT is selected as the active amplifier supply.	0x0: 0.15ms 0x1: 0.25ms 0x2: 0.5ms 0x3: 1.0ms 0x4: 2.5ms 0x5: 5.0ms 0x6: 10ms 0x7: 20ms 0x8: 30ms 0x9: 40ms 0xA: 50ms 0xB: 125ms 0xC: 250ms 0xD: 500ms 0xE: 750ms 0xF: 1.0s

SPK Class DG Delay (0x2097)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	SPK_DG_DELAY[5:0]						
Reset	_	_		0x0					
Access Type	_	_			Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_DG_DE LAY	5:0	Selects the speaker amplifier path signal delay for DG mode operation. Delays the audio output by N samples (N x fs).	0x0: No Delay 0x1: Delay 1 sample 0x2: Delay 2 samples 0x3 to 0x1D: (1 sample steps) 0x1E: Delay 30 samples 0x1F: Delay 31 samples 0x20: Delay 32 samples

SPK Class DG Mode (0x2098)

BIT	7	6	5	4	3	2	1	0
Field	_	-	_	_	_	_	SPK_MODE[1:0]	
Reset	_	_	_	_	_	_	0;	(0
Access Type	_	_	_	_	_	_	Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_MODE	1:0	Selects the speaker amplifier operating mode.	0x0: DG mode is enabled. 0x1: DG mode is disabled, and the amplifier is always supplied from the PVDD pin. 0x2: DG Mode is disabled, and the amplifier is supplied from the VBAT pin when supply conditions are met. 0x3: Reserved

SPK Class DG VBAT Level (0x2099)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	VBATLOW_OK_LVL[2:0]		
Reset	_	_	_	_	_	0x3		
Access Type	_	_	_	_	-	Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
VBATLOW_ OK_LVL	2:0	Sets the threshold for the VBAT level below which the amplifier is forced to operate in PVDD mode, i.e., the active amplifier supply is PVDD only.	0x0: 2.5V 0x1: 2.6V 0x2: 2.7V 0x3: 2.8V 0x4: 2.9V 0x5: 3.0V 0x6: Reserved 0x7: Reserved

SPK Edge Control (0x209A)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	TRI_FSW2 X_MODE	_	_
Reset	_	_	_	_	_	0x0	-	_
Access Type	_	_	_	_	_	Write, Read	_	_

BITFIELD	BITS	DESCRIPTION	DECODE
TRI_FSW2X _MODE	2	Controls the nominal switching frequency of the speaker amplifier.	Normal tri-wave oscillation frequency. 2X tri-wave oscillation frequency.

SPK Path Wideband Only Enable (0x209B)

BIT	7	6	5	4	3	2	1	0
Field	_	_	-	_	_	_	_	SPK_WIDE BAND_ONL Y_EN
Reset	_	_	-	_	_	_	_	0b00
Access Type	_	_	-	_	_	_	_	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_WIDEB AND_ONLY_ EN	0	When enabled, only a wideband signal is sent to the amplifier.	0x0: Ultrasound signal mode disabled. 0x1: Ultrasound signal mode enabled.

SPK Edge Control 1 (0x209C)

BIT	7	6	5	4	3	2	1	0	
Field	SPK_EN_T URNOFF_S LEW	-	-	_	SPK_SL_RATE_GMODE[3:0]				
Reset	0x0	_	_	_	0x3				
Access Type	Write, Read	_	-	_	Write, Read				

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_EN_TU RNOFF_SLE W	7	Enables turn-off slewing of power FETs.	Power FET turn-off slewing disabled. Power FET turn-off slewing enabled.
SPK_SL_RA TE_GMODE	3:0	These bits control the on/off time of the high-side power FET connected to the VBAT supply pin. This in effect, strongly controls the rise time at OUTx nodes in the VBAT mode and weakly controls the fall time at OUTx nodes in VBAT mode, as fall time is strongly controlled by SPK_SL_RATE_LS<3:0>.	

SPK Edge Control 2 (0x209D)

BIT	7	6	5	4	3	2	1	0	
Field		SPK_SL_RA	ATE_LS[3:0]		SPK_SL_RATE_HS[3:0]				
Reset		0>	кF		0xC				
Access Type		Write,	Read			Write,	Read		

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_SL_RA TE_LS	7:4	These bits control the on/off time of the low side power FET. This in effect strongly controls fall time at OUTx node, and weakly controls rise time at OUTx nodes. Rise times are strongly controlled by SPK_SL_RATE_GMODE in VBAT mode, and SPK_SL_RATE_HS in PVDD mode.	0x0000: Slowest rise time. 0x0101: Slower rise time than default. 0x1010: Default rise time. 0x1111: Faster than default rise time.
SPK_SL_RA TE_HS	3:0	These bits control the on/off time of high side power FET connected to the PVDD supply pin. This in effect controls strongly rise time at OUTx nodes, and weakly controls fall time of OUTx nodes in PVDD mode. Fall time is strongly controlled by SPK_SL_RATE_LS.	0x0000: Slowest rise time. 0x0101: Slower rise time than default. 0x1010: Default rise time. 0x1111: Faster than default rise time.

Amp Clip Gain (0x209E)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	_	_	SPK_GAIN[3:0]				
Reset	_	_	_	_	0x0				
Access Type	_	_	_	_		Write,	Read		

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_GAIN	3:0	Sets the digital clip gain level of the speaker amplifier path.	0x00: 0dB 0x01: 0.5dB 0x02: 1.0dB 0x03: 1.5dB 0x04: 2.0dB 0x05: 2.5dB 0x06: 3.0dB 0x07: 3.5dB 0x08: 4.0dB 0x09: 5.0dB 0x0A: 6.0dB 0x0B to 0x0F: Reserved

Bypass Path Config (0x209F)

BIT	7	6	5	4	3	2	1	0
Field	_	_	-	-	_	_	BYP_WBA ND_FILT_E N	BYP_INVE RT
Reset	_	_	-	-	_	_	0x0	0b0
Access Type	_	_	_	-	_	_	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
BYP_WBAN D_FILT_EN	1	Enables the wideband filters with increased passband for sample rates higher than 50kHz in the amplifier audio processing bypass path.	0x0: Higher passband filters disabled. 0x1: Higher passband filters enabled.
BYP_INVER T	0	Inverts the bypass amplifier path output.	O: Output is normal. Output is inverted.

AMP enables (0x20AF)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	SPK_FB_E N	SPK_EN
Reset	_	_	_	_	_	_	0b0	0b0
Access Type	_	_	_	_	_	_	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
SPK_FB_EN	1	Enables PCM data output from the end of the speaker amplifier path DSP.	Speaker amplifier path DSP feedback disabled. Speaker amplifier path DSP feedback enabled.
SPK_EN	0	Enables the speaker amplifier path.	Speaker amplifier is disabled. Speaker amplifier is enabled.

Meas ADC Sample Rate (0x20B0)

BIT	7	6	5	4	3	2	1	0
Field	MEAS_ADC_VDDH_SR[1: 0]		MEAS_ADC_TEMP_SR[1: 0]		MEAS_ADC_PVDD_SR[1: 0]		MEAS_ADC_	_VBAT_SR[1:)]
Reset	0:	0x0		0x3		0x0		k 0
Access Type	Write,	Read	Write,	Read	Write, Read		Write,	Read

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ VDDH_SR	7:6	Configures the sample rate of the VDDH channel of the measurement ADC.	00: 300kHz 01: 150kHz 10: 75kHz 11: 37.5kHz
MEAS_ADC_ TEMP_SR	5:4	Configures the sample rate of the thermal channel of the measurement ADC.	0x0: 300kHz 0x1: 150kHz 0x2: 75kHz 0x3: 37.5kHz
MEAS_ADC_ PVDD_SR	3:2	Configures the sample rate of the PVDD channel of the measurement ADC.	00: 300kHz 01: 150kHz 10: 75kHz 11: 37.5kHz
MEAS_ADC_ VBAT_SR	1:0	Configures the sample rate of the VBAT channel of the measurement ADC.	0x0: 300kHz 0x1: 150kHz 0x2: 75kHz 0x3: 37.5kHz

Meas ADC PVDD Config (0x20B1)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	MEAS_ADC _PVDD_FIL T_EN	MEAS_ADC_PVDD_FILT_COEFF[3:0]			
Reset	_	_	_	0x0	0x0			
Access Type	_	_	_	Write, Read	Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ PVDD_FILT_ EN	4	Controls whether filtering is applied to the PVDD channel output.	0: Filter is bypassed. 1: Filter is applied.
MEAS_ADC_ PVDD_FILT_ COEFF	3:0	Sets the PVDD channel lowpass filter bandwidth.	Value: Decode 0x0: 0.4kHz (Across all sample rates) 0x1: 2.5kHz (Across all sample rates) 0x2: 7.5kHz (Across all sample rates) 0x3: 50kHz (Only 150kHz and 300kHz sample rate) 0x4: 150kHz (Only 300kHz sample rate) 0x5 to 0xF: Reserved

Meas ADC VBAT Config (0x20B2)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	MEAS_ADC _VBAT_FIL T_EN	MEAS_ADC_VBAT_FILT_COEFF[3:0]			
Reset	_	_	_	0x0	0x00			
Access Type	_	_	-	Write, Read	Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ VBAT_FILT_ EN	4	Controls whether filtering is applied to the VBAT channel output.	0: Filter is bypassed. 1: Filter is applied.
MEAS_ADC_ VBAT_FILT_ COEFF	3:0	Sets the VBAT channel lowpass filter bandwidth.	Value: Decode 0x0: 0.4kHz (Across all sample rates) 0x1: 2.5kHz (Across all sample rates) 0x2: 7.5kHz (Across all sample rates) 0x3: 50kHz (Only 150kHz & 300kHz sample rate) 0x4: 150kHz (Only 300kHz sample rate) 0x5 to 0xF: Reserved

Meas ADC Thermal Config (0x20B3)

BIT	7	6	5	4	3	2	1	0
Field	_	1	_	MEAS_ADC _TEMP_FIL T_EN	MEAS_ADC_TEMP_FILT_COEFF[3:0]			
Reset	_	_	_	0x0	0x00			
Access Type	_	-	_	Write, Read	Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ TEMP_FILT_ EN	4	Controls whether filtering is applied to the thermal channel output.	0: Filter is bypassed. 1: Filter is applied.
MEAS_ADC_ TEMP_FILT_ COEFF	3:0	Sets the thermal channel lowpass filter bandwidth.	Value: Decode 0x0: 0.4kHz (Across all sample rates) 0x1: 2.5kHz (Across all sample rates) 0x2: 7.5kHz (Across all sample rates) 0x3: 50kHz (Only 150kHz and 300kHz sample rates) 0x4: 150kHz (Only 300kHz sample rate) 0x5 to 0xF: Reserved

Meas ADC VDDH Config (0x20B4)

BIT	7	6	5	4	3	2	1	0
Field	_	ı	_	MEAS_ADC _VDDH_FIL T_EN	MEAS_ADC_VDDH_FILT_COEFF[3:0]			
Reset	_	-	_	0x0	0x00			
Access Type	_	-	_	Write, Read	Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE		
MEAS_ADC_ VDDH_FILT_ EN	4	Controls whether filtering is applied to the VDDH channel output.	0: Filter is bypassed. 1: Filter is applied.		
MEAS_ADC_ VDDH_FILT_ COEFF	3:0	Sets the VDDH channel lowpass filter bandwidth.	Value: Decode 0x0: 0.4kHz (Across all sample rates) 0x1: 2.5kHz (Across all sample rates) 0x2: 7.5kHz (Across all sample rates) 0x3: 50kHz (Only 150kHz and 300kHz sample rates) 0x4: 150kHz (Only 300kHz sample rate) 0x5 to 0xF: Reserved		

Meas ADC Readback Control 1 (0x20B5)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	-	MEAS_ADC _VDDH_RD _MODE	_		MEAS_ADC _PVDD_RD _MODE
Reset	_	_	_	_	0x0	0x0	0x0	0x0
Access Type	_	_	_	_	Write, Read	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ VDDH_RD_ MODE	3	Controls whether the thermal ADC channel output readback is updated automatically or manually after each conversion is completed.	O: Measurement ADC channel readback data is automatically updated. 1: Initiates a measurement and locks the result into the measurement ADC channel readback register.
MEAS_ADC_ THERM_RD _MODE	2	Controls whether the thermal ADC channel output readback is updated automatically or manually after each conversion is completed.	Measurement ADC channel readback data is automatically updated. Initiates a measurement and locks the result into the measurement ADC channel readback register.

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ VBAT_RD_M ODE	1	Controls whether the VBAT ADC channel output readback is updated automatically or manually after each conversion is completed.	O: Measurement ADC channel readback data is automatically updated. Initiates a measurement and locks the result into the measurement ADC channel readback register.
MEAS_ADC_ PVDD_RD_ MODE	0	Controls whether the PVDD ADC channel output readback is updated automatically or manually after each conversion is completed.	O: Measurement ADC channel readback data is automatically updated. Initiates a measurement and locks the result into the measurement ADC channel readback register.

Meas ADC Readback Control 2 (0x20B6)

BIT	7	6	5	4	3	2	1	0
Field	_	_	-	_	MEAS_ADC _VDDH_RD _UPD	_		MEAS_ADC _PVDD_RD _UPD
Reset	-	-	-	_	0x0	0x0	0x0	0x0
Access Type	_	_	-	_	Write Only	Write Only	Write Only	Write Only

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ VDDH_RD_ UPD	3	Write 1 to initiate a measurement and lock the result into the measurement ADC VDDH channel readback register.	No effect. Initiates a measurement and locks the result into the measurement ADC channel readback register.
MEAS_ADC_ THERM_RD _UPD	2	Write 1 to initiate a measurement and lock the result into the measurement ADC thermal channel readback register.	No effect. Initiates a measurement and locks the result into the measurement ADC channel readback register.
MEAS_ADC_ VBAT_RD_U PD	1	Write 1 to initiate a measurement and lock the result into the measurement ADC VBAT channel readback register.	No effect. Initiates a measurement and locks the result into the measurement ADC channel readback register.
MEAS_ADC_ PVDD_RD_U PD	0	Write 1 to initiate a measurement and lock the result into the measurement ADC PVDD channel readback register.	No effect. I: Initiates a measurement and locks the result into the measurement ADC channel readback register.

Meas ADC PVDD Readback MSB (0x20B7)

BIT	7	6	5	4	3	2	1	0
Field	MEAS_ADC_PVDD_DATA[8:1]							
Reset	0x0							
Access Type	Read Only							

BITFIELD	BITS	DESCRIPTION
MEAS_ADC_PVDD_DA	7:0	Provides the measured PVDD value. To convert the 9-bit code into a real voltage, use the following:
		Measured V _{PVDD} (V) = MEAS_ADC_PVDD_DATA[8:0] x 0.054703125V

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

Meas ADC PVDD Readback LSB (0x20B8)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	MEAS_ADC _PVDD_DA TA[0]
Reset	_	_	_	_	_	_	_	0x0
Access Type	_	_	_	_	_	_	_	Read Only

BITFIELD	BITS	DESCRIPTION
MEAS_ADC_PVDD_DA	0	Provides the measured PVDD value. To convert the 9-bit code into a real voltage, use the following:
IA		Measured V _{PVDD} (V) = MEAS_ADC_PVDD_DATA[8:0] x 0.054703125V

Meas ADC VBAT Readback MSB (0x20B9)

BIT	7	6	5	4	3	2	1	0		
Field		MEAS_ADC_VBAT_DATA[8:1]								
Reset	0x0									
Access Type		Read Only								

BITFIELD	BITS	DESCRIPTION
MEAS_ADC_VBAT_DA	7:0	Provides the measured VBAT value. To convert the 9-bit code into a real voltage, use the following: Measured V _{VBAT} (V) = MEAS_ADC_VBAT_DATA[8:0] x 0.0113965V

Meas ADC VBAT Readback LSB (0x20BA)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	MEAS_ADC _VBAT_DA _TA[0]
Reset	_	_	_	_	_	_	_	0x0
Access Type	_	_	_	_	_	_	_	Read Only

BITFIELD	BITS	DESCRIPTION
MEAS_ADC_VBAT_DA	0	Provides the measured VBAT value. To convert the 9-bit code into a real voltage, use the following:
TA		Measured V _{VBAT} (V) = MEAS_ADC_VBAT_DATA[8:0] x 0.0113965V

Meas ADC Temp Readback MSB (0x20BB)

BIT	7	6	5	4	3	2	1	0		
Field		MEAS_ADC_THERM_DATA[8:1]								
Reset		0x0								
Access Type		Read Only								

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

BITFIELD	BITS	DESCRIPTION
MEAS_ADC_THERM_ DATA	7:0	Provides the measured temperature value. To convert the 9-bit code into a real temperature, use the following: Measured Temperature (°C) = (MEAS_ADC_THERM_DATA[8:0] x 1.0°C) - 252°C

Meas ADC Temp Readback LSB (0x20BC)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	-	MEAS_ADC _THERM_D ATA[0]
Reset	_	_	_	_	_	_	-	0x0
Access Type	_	_	_	_	_	_	_	Read Only

BITFIELD	BITS	DESCRIPTION
MEAS_ADC_THERM_ DATA	0	Provides the measured temperature value. To convert the 9-bit code into a real temperature, use the following: Measured Temperature (°C) = (MEAS_ADC_THERM_DATA[8:0] x 1.0°C) - 252°C

Meas ADC VDDH Readback MSB (0x20BD)

BIT	7	6	5	4	3	2	1	0		
Field		MEAS_ADC_VDDH_DATA[8:1]								
Reset		0x0								
Access Type		Read Only								

BITFIELD	BITS	DESCRIPTION
MEAS_ADC_VDDH_DA	7:0	Provides the measured VDDH value. To convert the 9-bit code into a real voltage, use the following:
IA		Measured V _{VDDH} (V) = MEAS_ADC_VDDH_DATA[8:0] x 0.054703125V

Meas ADC VDDH Readback LSB (0x20BE)

BIT	7	6	5	4	3	2	1	0
Field	-	_	_	_	_	_	_	MEAS_ADC _VDDH_DA TA[0]
Reset	_	_	_	_	_	_	_	0x0
Access Type	_	_	_	_	_	_	_	Read Only

BITFIELD	BITS	DESCRIPTION
MEAS_ADC_VDDH_DA	0	Provides the measured VDDH value. To convert the 9-bit code into a real voltage, use the following:
IA		Measured V _{VDDH} (V) = MEAS_ADC_VDDH_DATA[8:0] x 0.054703125V

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

Meas ADC Lowest PVDD Readback MSB (0x20BF)

BIT	7	6	5	4	3	2	1	0	
Field		LOWEST_PVDD_DATA[8:1]							
Reset		0xFF							
Access Type		Read Only							

BITFI	ELD	BITS	DESCRIPTION
LOWEST_PV	'DD_DATA	7:0	Provides the lowest measured PVDD value. To convert the 9-bit code into a real voltage, use the following: Measured $V_{PVDD}(V) = MEAS_ADC_PVDD_DATA[8:0] \times 0.054703125V$

Meas ADC Lowest PVDD Readback LSB (0x20C0)

BIT	7	6	5	4	3	2	1	0
Field	-	_	_	_	_	_	_	LOWEST_P VDD_DATA [0]
Reset	_	_	_	_	_	_	_	0x1
Access Type	_	_	_	_	_	_	_	Read, Ext

BITFIELD	BITS	DESCRIPTION
LOWEST_PVDD_DATA	0	Provides the lowest measured PVDD value. To convert the 9-bit code into a real voltage, use the following:
		Measured V_{PVDD} (V) = MEAS_ADC_PVDD_DATA[8:0] x 0.054703125V

Meas ADC Lowest VBAT Readback MSB (0x20C1)

BIT	7	6	5	4	3	2	1	0	
Field		LOWEST_VBAT_DATA[8:1]							
Reset		0xFF							
Access Type		Read Only							

BITFIELD	BITS	DESCRIPTION
LOWEST_VBAT_DATA		Provides the measured VBAT value. To convert the 9-bit code into a real voltage, use the following: Measured V _{VBAT} (V) = MEAS_ADC_VBAT_DATA[8:0] x 0.0113965V

Meas ADC Lowest VBAT Readback LSB (0x20C2)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	1	_	-	LOWEST_V BAT_DATA[0]
Reset	_	-	_	_	ı	_	I	0x1
Access Type	_	_	_	_	-	_	_	Read, Ext

BITFIELD	BITS	DESCRIPTION
LOWEST_VBAT_DATA	0	Provides the measured VBAT value. To convert the 9-bit code into a real voltage, use the following: Measured V _{VBAT} (V) = MEAS_ADC_VBAT_DATA[8:0] x 0.0113965V

Meas ADC Lowest VDDH Readback MSB (0x20C3)

BIT	7	6	5	4	3	2	1	0	
Field		LOWEST_VDDH_DATA[8:1]							
Reset		0xFF							
Access Type		Read Only							

BITFIELD	BITS	DESCRIPTION
LOWEST_VDDH_DATA		Provides the lowest measured VDDH value. To convert the 9-bit code into a real voltage, use the following: Measured V _{VDDH} (V) = MEAS_ADC_VDDH_DATA[8:0] x 0.054703125V

Meas ADC Lowest VDDH Readback LSB (0x20C4)

BIT	7	6	5	4	3	2	1	0
Field	_	_	-	ı	-	-	l	LOWEST_V DDH_DATA [0]
Reset	_	_	_	-	_	_	_	0x1
Access Type	_	_	_	-	_	_	-	Read, Ext

BITFIELD	BITS	DESCRIPTION
LOWEST_VDDH_DATA	0	Provides the lowest measured VDDH value. To convert the 9-bit code into a real voltage, use the following: Measured V _{VDDH} (V) = MEAS_ADC_VDDH_DATA[8:0] x 0.054703125V

Meas ADC Highest Thermal Readback MSB (0x20C5)

BIT	7	6	5	4	3	2	1	0
Field	HIGHEST_THERM_DATA_MSB[7:0]							
Reset		0x00						
Access Type		Read Only						

BITFIELD	BITS	DESCRIPTION
HIGHEST_THERM_DA TA_MSB	7:0	Provides the highest measured thermal value. To convert the 9-bit code into a real temperature, use the following: Highest Measured Temperature (°C) = (HIGHEST_THERM_DATA[8:0] x 1.0° C) - 252°C

Meas ADC Highest Thermal Readback LSB (0x20C6)

BIT	7	6	5	4	3	2	1	0
Field	-	_	_	_	_	_	_	HIGHEST_ THERM_DA TA_LSB
Reset	_	_	_	_	_	_	_	0x0
Access Type	_	_	_	_	_	_	_	Read, Ext

BITFIELD	BITS	DESCRIPTION
HIGHEST_THERM_DA TA_LSB	0	Provides the highest measured thermal value. To convert the 9-bit code into a real temperature, use the following: Highest Measured Temperature (°C) = (HIGHEST_THERM_DATA[8:0] x 1.0°C) - 252°C

Meas ADC Optimal Mode (0x20C7)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	MEAS_ADC_ EL[OPT_AVE_S 1:0]		OPT_MODE[0]
Reset	_	_	_	_	0x1 0x0		(0	
Access Type	_	_	_	_	Write, Read Write, Re		Read	

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ OPT_AVE_S EL	3:2	When MEAS_ADC_OPT_MODE is enabled, the optimized channel's moving average can be set by this register.	0x0: Bypass 0x1: 2 samples 0x2: 4 samples 0x3: Reserved
			0x0:
			Measurement ADC runs at regular mode.
MEAS_ADC_ OPT_MODE	1:0	Enables the measurement ADC optimal mode. When it is set, the BPE power source (depend on BPE_SRC_SEL) runs at the highest rate, the unselected power source runs at a medium rate, and the thermal runs at 37.5kHz fixed. The MEAS_ADC_xxx_SR has no effect in an optimal mode.	0x1: Measurement ADC runs at optimal mode 1, BPE power source at 600kHz, second power source at 300kHz, and thermal at 37.5kHz. 0x2: Measurement ADC runs at optimal mode 2, BPE power source at 900kHz, second power source at 75kHz, and thermal at 37.5kHz. 0x3: Reserved

Meas ADC Config (0x20C8)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	MEAS_ADC _VDDH_EN	MEAS_ADC _VBAT_EN	MEAS_ADC _PVDD_EN
Reset	_	_	-	_	-	0x0	0x0	0x0
Access Type	_	_	_	_	_	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
MEAS_ADC_ VDDH_EN	2	Manually enables the measurement ADC VDDH channel.	0: Do not manually enable the measurement ADC channel (may be automatically enabled) 1: Manually force the measurement ADC channel to be enabled anytime the device is in the active state
MEAS_ADC_ VBAT_EN	1	Manually enables the measurement ADC VBAT channel.	O: Do not manually enable the measurement ADC channel (may be automatically enabled) 1: Manually force the measurement ADC channel to be enabled anytime the device is in the active state
MEAS_ADC_ PVDD_EN	0	Manually enables the measurement ADC PVDD channel.	0: Do not manually enable the measurement ADC channel (may be automatically enabled) 1: Manually force the measurement ADC channel to be enabled anytime the device is in the active state

DHT Configuration 1 (0x20D0)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	DHT_VROT_PNT[3:0]			
Reset	_	_	_	_	0x0			
Access Type	_	_	_	_	Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
DHT_VROT_ PNT	3:0	Sets the DRC rotation point.	0x0: 0dBFS 0x1: -1dBFS 0x2: -2dBFS 0x3: -3dBFS 0x4: -4dBFS 0x5: -5dBFS 0x6: -6dBFS 0x7: -8dBFS 0x8: -10dBFS 0x9: -12dBFS 0xA: -15dBFS 0xB: Reserved 0xC: Reserved 0xC: Reserved 0xC: Reserved 0xF: Reserved 0xF: Reserved

Limiter Configuration 1 (0x20D1)

BIT	7	6	5	4	3	2	1	0
Field	_	-	_	DHT_HR[4:0]				
Reset	_	_	_	0x8				
Access Type	-	ı	_	Write, Read				

BITFIELD	BITS	DESCRIPTION	DECODE
DHT_HR	4:0	Selects the DHT supply headroom for the DRC and limiter functions.	0x0: -20% 0x1: -17.5% 0x2: -15% 0x3: -12.5% 0x4: -10% 0x5: -7.5% 0x6: -5.0% 0x7: -2.5% 0x8: 0% 0x9: +2.5% 0xA: +5.0% 0xB: +7.5% 0xC: +10% 0xD: +12.5% 0xE: +15% 0xF: +17.5% 010: +20%

Limiter Configuration 2 (0x20D2)

BIT	7	6	5	4	3	2	1	0
Field	_	_	DHT_LIM_THRESH[4:0]				DHT_LIM_ MODE	
Reset	_	_		0x0				
Access Type	_	_	Write, Read					Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE		
DHT_LIM_T HRESH	5:1	Selects the fixed threshold level for signal level limiter mode (SLL). Has no effect in signal distortion limiter mode (SDL).	00000: 0dBFS 00001: -1dBFS 00010: -2dBFS : (-1dBFS steps) 01110: -14dBFS 01111: -15dBFS 10000 to 11111: Reserved		
DHT_LIM_M ODE	0	Selects whether the DHT limiter is in signal distortion or signal level limiter mode.	Signal Distortion Limiter mode where limiter threshold tracks supply Signal Level Limiter mode where limiter uses fixed thresholds		

DHT Configuration 2 (0x20D3)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	DHT_MAX_ATN[4:0]				
Reset	_	_	_	0x14				
Access Type	-	_	_	Write, Read				

BITFIELD	BITS	DESCRIPTION	DECODE
DHT_MAX_A TN	4:0	Selects the maximum attenuation that can be applied to the audio signal by the DHT.	0x0: Reserved 0x1: -1dB 0x2: -2dB 0x3: -3dB 0x4: -4dB 0x5: -5dB 0x6: -6dB 0x7: -7dB 0x8: -8dB 0x9: -9dB 0xA: -10dB 0xB: -11dB 0xC: -12dB 0xD: -13dB 0xE: -14dB 0xF: -15dB 0xF: -15dB 0x1: -16dB 0x1: -17dB 0x1: -16dB 0x1: -17dB 0x1: -17dB 0x1: -18dB

DHT Configuration 3 (0x20D4)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	DHT_ATK_RATE[3:0]			
Reset	_	-	-	-	0x2			
Access Type	-	_	_	_		Write,	Read	

BITFIELD	BITS	DESCRIPTION	DECODE
DHT_ATK_R ATE	3:0	Selects the DHT attack rate.	0x0: 20µs/dB 0x1: 40µs/dB 0x2: 80µs/dB 0x3: 160µs/dB 0x4: 320µs/dB 0x5: 640µs/dB 0x6: 1.28ms/dB 0x7: 2.56ms/dB 0x8: 5.12ms/dB 0x9: 10.24ms/dB 0xA: 20.48ms/dB 0xB: 40.96ms/dB 0xC: 81.92ms/dB 0xD: 163.84ms/dB 0xE: Reserved 0xF: Reserved

DHT Configuration 4 (0x20D5)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	DHT_RLS_RATE[3:0]			
Reset	_	_	_	_	0x4			
Access Type	_	_	_	_		Write,	Read	

BITFIELD	BITS	DESCRIPTION	DECODE
DHT_RLS_R ATE	3:0	Selects the DHT release rate.	0x0: 1.67ms/dB 0x1: 3.33ms/dB 0x2: 6.67ms/dB 0x3: 13.33ms/dB 0x4: 26.67ms/dB 0x5: 53.33ms/dB 0x6: 106.67ms/dB 0x7: 213.33ms/dB 0x8: 426.67ms/dB 0x9: 853.33ms/dB 0x9: 853.33ms/dB 0xA: 1706.67ms/dB 0xB: 3413.33ms/dB 0xC: 6826.67ms/dB 0xD: 13653.33ms/dB 0xC: Reserved 0xF: Reserved

DHT Supply Hysteresis Configuration (0x20D6)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	DHT_SUPPLY_HYST[2:0]			DHT_SUPP LY_HYST_ EN
Reset	_	_	_	_	0x3			0x1
Access Type	_	_	_	_	Write, Read		Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
DHT_SUPPL Y_HYST	3:1	Selects the supply hysteresis for DHT attenuation release when supply increases.	0x0: 1 LSB 0x1: 2 LSB 0x2: 3 LSB 0x3: 4 LSB 0x4: 6 LSB 0x5: 8 LSB 0x6: 10 LSB 0x7: 12 LSB
DHT_SUPPL Y_HYST_EN	0	Select whether PVDD DHT hysteresis is enabled or disabled.	0: DHT is disabled 1: DHT is enabled

DHT Enable (0x20DF)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	DHT_EN
Reset	_	_	_	_	_	-	_	0x0
Access Type	_	_	_	_	_	_	_	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
DHT_EN	0	Select whether DHT is enabled or disabled	0: DHT is disabled. 1: DHT is enabled.

I_V Sense Path Config (0x20E0)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	IVADC_WB AND_FILT_ EN	IVADC_DIT H_EN	IVADC_I_D CBLK_EN	IVADC_V_ DCBLK_EN
Reset	_	_	_	_	0x0	0b1	0b1	0b1
Access Type	_	_	_	_	Write, Read	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
IVADC_WBA ND_FILT_EN	3	Enables the wideband filters with increased passband for sample rates higher than 50kHz in the IV ADC path.	0x0: Higher passband filters disabled. 0x1: Higher passband filters enabled.
IVADC_DITH _EN	2	Select whether or not dither is applied to the I/V sense ADC path.	0: Dither disabled. 1: Dither enabled.
IVADC_I_DC BLK_EN	1	Enables the DC blocking filter in the current sense ADC path.	0: DC blocker disabled. 1: DC blocker enabled.
IVADC_V_D CBLK_EN	0	Enables the DC blocking filter in the voltage sense ADC path.	0: DC blocker disabled. 1: DC blocker enabled.

I V Sense Path Enables (0x20E4)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	IVADC_IM_ EN	IVADC_I_E N	IVADC_V_E N
Reset	_	-	-	_	-	0b0	0b0	0b0
Access Type	_	_	_	_	_	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
IVADC_IM_E N	2	Enables the speaker current and voltage sense ADC path. When this bit is set to 1, the current sense ADC and voltage sense ADC paths are powered up if the device is in the active state (EN = 1) during idle mode.	O: Speaker current sense ADC and voltage sense ADC paths are disabled during idle mode. 1: Speaker current sense ADC and voltage sense ADC paths are enabled during idle mode.
IVADC_I_EN	1	Enables the speaker current sense ADC path. When this bit is set to 1, the current sense ADC path is powered up if the device is in the active state (EN = 1).	Speaker current sense ADC path disabled. Speaker current sense ADC path enabled.

BITFIELD	BITS	DESCRIPTION	DECODE
IVADC_V_E N	0	Enables the speaker voltage sense ADC path. When this bit is set to 1, the voltage sense ADC path is powered up if the device is in the active state (EN = 1).	Speaker voltage sense ADC path disabled. Speaker voltage sense ADC path enabled.

BPE State (0x20E5)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	BPE_STATE[2:0]		
Reset	_	-	_	-	-	0x0		
Access Type	_	_	_	_	_		Read Only	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_STATE	2:0	Current level of brownout controller. Reads back 000 when EN = 0.	000: Brownout inactive - normal operation 001: Level 3 010: Level 2 011: Level 1 100: Level 0 101 to 111: Reserved

BPE L3 Threshold MSB (0x20E6)

BIT	7	6	5	4	3	2	1	0
Field		BPE_L3_VTHRESH[8:1]						
Reset		0x0						
Access Type				Write,	Read			

BITFIELD	BITS	DESCRIPTION
		BPE_Ln_VTHRESH[8:0] sets the trigger level for each threshold in the brownout controller.
BPE_L3_VTHRESH	7:0	See the Measurement ADC CH0 (PVDD) Result register to set these levels. A value of 0000 0000 (all zeros) means that state is not used and is entirely bypassed.

BPE L3 Threshold LSB (0x20E7)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	-	_	BPE_L3_VT HRESH[0]
Reset	_	_	_	_	_	-	_	0x0
Access Type	_	_	_	_	_	-	_	Write, Read

BITFIELD	BITS	DESCRIPTION
BPE_L3_VTHRESH	0	

BPE L2 Threshold MSB (0x20E8)

BIT	7	6	5	4	3	2	1	0	
Field		BPE_L2_VTHRESH[8:1]							
Reset				0:	(0				
Access Type				Write,	Read				

BITFIELD	BITS	DESCRIPTION
		BPE_Ln_VTHRESH[8:0] Sets the trigger level for each threshold in the brownout controller.
BPE_L2_VTHRESH	7:0	See the Measurement ADC CH0 (PVDD) Result register to set these levels. A value of 0000 0000 (all zeros) means that state is not used and is entirely bypassed.

BPE L2 Threshold LSB (0x20E9)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	BPE_L2_VT HRESH[0]
Reset	_	_	_	_	_	_	_	0x0
Access Type	_	_	_	_	_	_	_	Write, Read

BITFIELD	BITS	DESCRIPTION
BPE_L2_VTHRESH	0	

BPE L1 Threshold MSB (0x20EA)

BIT	7	6	5	4	3	2	1	0
Field		BPE_L1_VTHRESH[8:1]						
Reset	0x0							
Access Type	Write, Read							

BITFIELD	BITS	DESCRIPTION
		BPE_Ln_VTHRESH[8:0] Sets the trigger level for each threshold in the brownout controller.
BPE_L1_VTHRESH	7:0	See the Measurement ADC CH0 (PVDD) Result register to set these levels. A value of 0000 0000 (all zeros) means that state is not used and is entirely bypassed.

BPE L1 Threshold LSB (0x20EB)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	BPE_L1_VT HRESH[0]
Reset	_	_	_	_	_	_	_	0x0
Access Type	_	_	_	_	_	_	_	Write, Read

MAX98397

28V Digital Input, Class-DG Amplifier with $\mathsf{IV}_{\mathsf{SENSE}}, \mathsf{Ultra\text{-}Low} \; \mathsf{I}_{\mathsf{Q}}, \; \mathsf{and} \; \mathsf{Brownout} \; \mathsf{Prevention}$

BITFIELD	BITS	DESCRIPTION
BPE_L1_VTHRESH	0	

BPE L0 Threshold MSB (0x20EC)

BIT	7	6	5	4	3	2	1	0
Field		BPE_L0_VTHRESH[8:1]						
Reset	0x0							
Access Type	Write, Read							

BITFIELD	BITS	DESCRIPTION
		BPE_Ln_VTHRESH[7:0] Sets the trigger level for each threshold in the brownout controller.
BPE_L0_VTHRESH	7:0	See the Measurement ADC CH0 (PVDD) Result register to set these levels. BA value of 0000 0000 (all zeros) means that state is not used and is entirely bypassed (no hold times). Level 0 cannot be bypassed by writing all zeros.

BPE L0 Threshold LSB (0x20ED)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	BPE_L0_VT HRESH[0]
Reset	_	_	-	_	-	-	-	0x0
Access Type	_	_	_	_	-	_	_	Write, Read

BITFIELD	BITS	DESCRIPTION
BPE_L0_VTHRESH	0	

BPE L3 Dwell and Hold Time (0x20EE)

BIT	7	6	5	4	3	2	1	0
Field	_	_	BPE_L3_DWELL[2:0]			BPE_L3_HOLD[2:0]		
Reset	_	_	0x0				0x0	
Access Type	-	-	Write, Read				Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L3_DW ELL	5:3	Sets the BPE level 3 gain attenuation dwell time.	0x0: 0μs 0x1: 100μs 0x2: 250μs 0x3: 500μs 0x4: 1000μs 0x5: 2000μs 0x6: 4000μs 0x7: 8000μs

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L3_HO LD	2:0	Sets the BPE level 3 gain attenuation hold time.	0x0: 0ms 0x1: 10ms 0x2: 100ms 0x3: 250ms 0x4: 500ms 0x5: 1000ms 0x6: 2000ms 0x7: Infinite

BPE L2 Dwell and Hold Time (0x20EF)

BIT	7	6	5	4	3	2	1	0
Field	_		BPE_L2_DWELL[2:0]			BPE_L2_HOLD[2:0]		
Reset	_	-	0x0			0x0		
Access Type	_	-		Write, Read			Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L2_DW ELL	5:3	Sets the BPE level 2 gain attenuation dwell time.	0x0: 0μs 0x1: 100μs 0x2: 250μs 0x3: 500μs 0x4: 1000μs 0x5: 2000μs 0x6: 4000μs 0x7: 8000μs
BPE_L2_HO LD	2:0	Sets the BPE level 2 gain attenuation hold time.	0x0: 0ms 0x1: 10ms 0x2: 100ms 0x3: 250ms 0x4: 500ms 0x5: 1000ms 0x6: 2000ms 0x7: Infinite

BPE L1 Dwell and Hold Time (0x20F0)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	BPE_L1_DWELL[2:0]			BPE_L1_HOLD[2:0]			
Reset	_	-		0x0			0x0		
Access Type	_	_		Write, Read			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L1_DW ELL	5:3	Sets the BPE level 1 gain attenuation dwell time.	0x0: 0μs 0x1: 100μs 0x2: 250μs 0x3: 500μs 0x4: 1000μs 0x5: 2000μs 0x6: 4000μs 0x7: 8000μs

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L1_HO LD	2:0	Sets the BPE level 1 gain attenuation hold time.	0x0: 0ms 0x1: 10ms 0x2: 100ms 0x3: 250ms 0x4: 500ms 0x5: 1000ms 0x6: 2000ms 0x7: Infinite

BPE L0 Hold Time (0x20F1)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	BPE_L0_HOLD[2:0]		
Reset	_	_	_	_	-	0x0		
Access Type	_	_	_	_	-	Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_HO	2:0	Sets the BPE level 0 gain attenuation hold time.	0x0: 0ms 0x1: 10ms 0x2: 100ms 0x3: 250ms 0x4: 500ms 0x5: 1000ms 0x6: 2000ms 0x7: Infinite

BPE L3 Attack and Release Step (0x20F2)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	BPE_L3_STEP[3:0]			
Reset	_	_	_	_	0x0			
Access Type	_	_	_	_	Write, Read			

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L3_ST EP	3:0	Sets the BPE level 3 gain attenuation step size.	0x0: 0.0625dB 0x1: 0.125dB 0x2: 0.1875dB 0x3: 0.25dB 0x4: 0.375dB 0x5: 0.5dB 0x6: 0.75dB 0x7: 1.0dB 0x8: 1.5dB 0x9: 2.0dB 0xA: 2.5dB 0xB: 3.0dB 0xC: 4.0dB 0xD: 5.0dB 0xE: 5.5dB 0xF: 6.0dB

BPE L2 Attack and Release Step (0x20F3)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	_	_	BPE_L2_STEP[3:0]				
Reset	_	_	_	_	0x0				
Access Type	_	_	_	_		Write,	Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L2_ST EP	3:0	Sets the BPE level 2 gain attenuation step size.	0x0: 0.0625dB 0x1: 0.125dB 0x2: 0.1875dB 0x3: 0.25dB 0x4: 0.375dB 0x5: 0.5dB 0x6: 0.75dB 0x7: 1.0dB 0x8: 1.5dB 0x9: 2.0dB 0xA: 2.5dB 0xB: 3.0dB 0xC: 4.0dB 0xD: 5.0dB 0xC: 5.5dB 0xC: 5.5dB

BPE L1 Attack and Release Step (0x20F4)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	_	_	BPE_L1_STEP[3:0]				
Reset	_	_	_	_	0x0				
Access Type	_	_	_	_	Write, Read				

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L1_ST EP	3:0	Sets the BPE level 1 gain attenuation step size.	0x0: 0.0625dB 0x1: 0.125dB 0x2: 0.1875dB 0x3: 0.25dB 0x4: 0.375dB 0x5: 0.5dB 0x6: 0.75dB 0x7: 1.0dB 0x8: 1.5dB 0x9: 2.0dB 0xA: 2.5dB 0xB: 3.0dB 0xC: 4.0dB 0xC: 4.0dB 0xD: 5.0dB 0xE: 5.5dB 0xF: 6.0dB

BPE L0 Attack and Release Step (0x20F5)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	BPE_L0_STEP[3:0]			
Reset	_	_	-	_	0x0			
Access Type	_	_	_	_		Write,	Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_ST EP	3:0	Sets the BPE level 0 gain attenuation step size.	Value: Decode 0x0: 0.0625dB 0x1: 0.125dB 0x2: 0.1875dB 0x3: 0.25dB 0x4: 0.375dB 0x5: 0.5dB 0x6: 0.75dB 0x7: 1.0dB 0x8: 1.5dB 0x9: 2.0dB 0xA: 2.5dB 0xB: 3.0dB 0xC: 4.0dB 0xC: 4.0dB 0xC: 5.5dB 0xE: 5.5dB

BPE L3 Max Gain Attn (0x20F6)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	BPE_L3_MAXATTN[4:0]				
Reset	_	_	-	0x0				
Access Type	_	_	_			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L3_MA XATTN	4:0	Sets the BPE level 3 maximum gain attenuation.	0x0: 0dB 0x1: -1dB 0x2: -2dB 0x3: -3dB 0x4 0x1D:(-1dB steps) 0x1E: -30dB 0x1F: -31dB

BPE L2 Max Gain Attn (0x20F7)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	BPE_L2_MAXATTN[4:0]				
Reset	_	-	_	0x0				
Access Type	_	_	_			Write, Read		

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L2_MA XATTN	4:0	Sets the BPE level 2 maximum gain attenuation.	0x0: 0dB 0x1: -1dB 0x2: -2dB 0x3: -3dB 0x4 0x1D:(-1dB steps) 0x1E: -30dB 0x1F: -31dB

BPE L1 Max Gain Attn (0x20F8)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	BPE_L1_MAXATTN[4:0]				
Reset	_	_	_	0x0				
Access Type	_	_	-			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L1_MA XATTN	4:0	Sets the BPE level 1 maximum gain attenuation.	0x0: 0dB 0x1: -1dB 0x2: -2dB 0x3: -3dB 0x4 0x1D:(-1dB steps) 0x1E: -30dB 0x1F: -31dB

BPE L0 Max Gain Attn (0x20F9)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	BPE_L0_MAXATTN[4:0]				
Reset	_	_	_	0x0				
Access Type	_	_	_			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_MA XATTN	4:0	Sets the BPE level 0 maximum gain attenuation.	0x0: 0dB 0x1: -1dB 0x2: -2dB 0x3: -3dB 0x4 0x1D:(-1dB steps) 0x1E: -30dB 0x1F: -31dB

BPE L3 Gain Attack and RIs Rates (0x20FA)

BIT	7	6	5	4	3	2	1	0
Field	_	_	BPE_	L3_GAIN_RL	S[2:0]	BPE_L3_GAIN_ATK[2:0]		
Reset	_	_		0x0		0x0		
Access Type	-	_		Write, Read			Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L3_GAI N_RLS	5:3	Sets the BPE level 3 gain attenuation release rate.	0x0: 5ms/step 0x1: 10ms/step 0x2: 25ms/step 0x3: 50ms/step 0x4: 100ms/step 0x5: 250ms/step 0x6: 500ms/step 0x7: 1000ms/step
BPE_L3_GAI N_ATK	2:0	Sets the BPE level 3 gain attenuation attack rate.	0x0: 2.5µs/step 0x1: 5µs/step 0x2: 10µs/step 0x3: 25µs/step 0x4: 50µs/step 0x5: 100µs/step 0x6: 250µs/step 0x7: 500µs/step

BPE L2 Gain Attack and Rls Rates (0x20FB)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	BPE_L2_GAIN_RLS[2:0]			BPE_L2_GAIN_ATK[2:0]			
Reset	_	_		0x0			0x0		
Access Type	_	_		Write, Read			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L2_GAI N_RLS	5:3	Sets the BPE level 2 gain attenuation release rate.	0x0: 5ms/step 0x1: 10ms/step 0x2: 25ms/step 0x3: 50ms/step 0x4: 100ms/step 0x5: 250ms/step 0x6: 500ms/step 0x7: 1000ms/step
BPE_L2_GAI N_ATK	2:0	Sets the BPE level 2 gain attenuation attack rate.	0x0: 2.5µs/step 0x1: 5µs/step 0x2: 10µs/step 0x3: 25µs/step 0x4: 50µs/step 0x5: 100µs/step 0x6: 250µs/step 0x7: 500µs/step

BPE L1 Gain Attack and RIs Rates (0x20FC)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	BPE_L1_GAIN_RLS[2:0]			BPE_L1_GAIN_ATK[2:0]			
Reset	_	_		0x0			0x0		
Access Type	-	_		Write, Read			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L1_GAI N_RLS	5:3	Sets the BPE level 1 gain attenuation release rate.	0x0: 5ms/step 0x1: 10ms/step 0x2: 25ms/step 0x3: 50ms/step 0x4: 100ms/step 0x5: 250ms/step 0x6: 500ms/step 0x7: 1000ms/step
BPE_L1_GAI N_ATK	2:0	Sets the BPE level 1 gain attenuation attack rate.	0x0: 2.5µs/step 0x1: 5µs/step 0x2: 10µs/step 0x3: 25µs/step 0x4: 50µs/step 0x5: 100µs/step 0x6: 250µs/step 0x7: 500µs/step

BPE L0 Gain Attack and Rls Rates (0x20FD)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	BPE_	_L0_GAIN_RL	5[2:0]	BPE_L0_GAIN_ATK[2:0]			
Reset	_	_		0x0			0x0		
Access Type	_	_		Write, Read			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_GAI N_RLS	5:3	Sets the BPE level 0 gain attenuation release rate.	0x0: 5ms/step 0x1: 10ms/step 0x2: 25ms/step 0x3: 50ms/step 0x4: 100ms/step 0x5: 250ms/step 0x6: 500ms/step 0x7: 1000ms/step
BPE_L0_GAI N_ATK	2:0	Sets the BPE level 0 gain attenuation attack rate.	0x0: 2.5µs/step 0x1: 5µs/step 0x2: 10µs/step 0x3: 25µs/step 0x4: 50µs/step 0x5: 100µs/step 0x6: 250µs/step 0x7: 500µs/step

BPE L3 Limiter Config (0x20FE)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	BPE_L3_LIM[3:0]			
Reset	_	_	_	_	0x0			
Access Type	-	_	_	_		Write,	Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L3_LIM	3:0	Sets the limiter threshold for BPE level 3.	0x0: 0dBFS 0x1: -1dBFS 0x2: -2dBFS 0x3: -3dBFS 0x4: -4dBFS 0x5: -5dBFS 0x6: -6dBFS 0x7: -7dBFS 0x8: -8dBFS 0x9: -9dBFS 0xA: -10dBFS 0xB: -11dBFS 0xC: -12dBFS 0xD: -13dBFS 0xE: -14dBFS 0xF: -15dBFS

BPE L2 Limiter Config (0x20FF)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	BPE_L2_LIM[3:0]			
Reset	_	_	_	_	0x0			
Access Type	_	_	_	_		Write,	Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L2_LIM	3:0	Sets the limiter threshold for BPE level 2.	0x0: 0dBFS 0x1: -1dBFS 0x2: -2dBFS 0x3: -3dBFS 0x4: -4dBFS 0x5: -5dBFS 0x6: -6dBFS 0x7: -7dBFS 0x8: -8dBFS 0x9: -9dBFS 0xA: -10dBFS 0xB: -11dBFS 0xB: -11dBFS 0xC: -12dBFS 0xD: -13dBFS 0xE: -14dBFS 0xF: -15dBFS

BPE L1 Limiter Config (0x2100)

BIT	7	6	5	4	3	2	1	0
Field	_	-	_	_	BPE_L1_LIM[3:0]			
Reset	_	_	_	_	0x0			
Access Type	_	-	_	_		Write,	Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L1_LIM	3:0	Sets the limiter threshold for BPE level 1.	0x0: 0dBFS 0x1: -1dBFS 0x2: -2dBFS 0x3: -3dBFS 0x4: -4dBFS 0x5: -5dBFS 0x6: -6dBFS 0x7: -7dBFS 0x8: -8dBFS 0x9: -9dBFS 0xA: -10dBFS 0xB: -11dBFS 0xC: -12dBFS 0xD: -13dBFS 0xE: -14dBFS 0xF: -15dBFS

BPE L0 Limiter Config (0x2101)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	BPE_L0_LIM[3:0]			
Reset	_	_	_	-	0x0			
Access Type	_	_	_	_		Write,	Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_LIM	3:0	Sets the limiter threshold for BPE level 0.	0x0: 0dBFS 0x1: -1dBFS 0x2: -2dBFS 0x3: -3dBFS 0x4: -4dBFS 0x5: -5dBFS 0x6: -6dBFS 0x7: -7dBFS 0x8: -8dBFS 0x9: -9dBFS 0xA: -10dBFS 0xB: -11dBFS 0xC: -12dBFS 0xD: -13dBFS 0xE: -14dBFS 0xF: -15dBFS

BPE L3 Limiter Attack and Release Rates (0x2102)

BIT	7	6	5	4	3	2	1	0
Field	_	_	BPE_L3_LIM_RLS[2:0]			BPE_L3_LIM_ATK[2:0]		
Reset	_	_	0x0				0x0	
Access Type	-	_		Write, Read			Write, Read	

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L3_LIM _RLS	5:3	Sets the BPE level 3 limiter release rate.	0x0: 5ms/step 0x1: 10ms/step 0x2: 25ms/step 0x3: 50ms/step 0x4: 100ms/step 0x5: 250ms/step 0x6: 500ms/step 0x7: 1000ms/step
BPE_L3_LIM _ATK	2:0	Sets the BPE level 3 limiter attack rate.	0x0: 2.5µs/step 0x1: 5µs/step 0x2: 10µs/step 0x3: 25µs/step 0x4: 50µs/step 0x5: 100µs/step 0x6: 250µs/step 0x7: 500µs/step

BPE L2 Limiter Attack and Release Rates (0x2103)

BIT	7	6	5	4	3	2	1	0
Field	_	_	BPE	_L2_LIM_RLS	[2:0]	BPE_L2_LIM_ATK[2:0]		
Reset	_	-	0x0			0x0		
Access Type	_	-		Write, Read			Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L2_LIM _RLS	5:3	Sets the BPE level 2 limiter release rate.	0x0: 5ms/step 0x1: 10ms/step 0x2: 25ms/step 0x3: 50ms/step 0x4: 100ms/step 0x5: 250ms/step 0x6: 500ms/step 0x7: 1000ms/step
BPE_L2_LIM _ATK	2:0	Sets the BPE level 2 limiter attack rate.	0x0: 2.5µs/step 0x1: 5µs/step 0x2: 10µs/step 0x3: 25µs/step 0x4: 50µs/step 0x5: 100µs/step 0x6: 250µs/step 0x7: 500µs/step

BPE L1 Limiter Attack and Release Rates (0x2104)

BIT	7	6	5	4	3	2	1	0	
Field	_	_	BPE	_L1_LIM_RLS	[2:0]	BPE_L1_LIM_ATK[2:0]			
Reset	_	_		0x0			0x0		
Access Type	-	_		Write, Read			Write, Read		

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L1_LIM _RLS	5:3	Sets the BPE level 1 limiter release rate.	0x0: 5ms/step 0x1: 10ms/step 0x2: 25ms/step 0x3: 50ms/step 0x4: 100ms/step 0x5: 250ms/step 0x6: 500ms/step 0x7: 1000ms/step
BPE_L1_LIM _ATK	2:0	Sets the BPE level 1 limiter attack rate.	0x0: 2.5µs/step 0x1: 5µs/step 0x2: 10µs/step 0x3: 25µs/step 0x4: 50µs/step 0x5: 100µs/step 0x6: 250µs/step 0x7: 500µs/step

BPE L0 Limiter Attack and Release Rates (0x2105)

BIT	7	6	5	4	3	2	1	0
Field	_	_	BPE_L0_LIM_RLS[2:0]			BPE_L0_LIM_ATK[2:0]		
Reset	_	_	0x0			0x0		
Access Type	_	_		Write, Read			Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_L0_LIM _RLS	5:3	Sets the BPE level 0 limiter release rate.	0x0: 5ms/step 0x1: 10ms/step 0x2: 25ms/step 0x3: 50ms/step 0x4: 100ms/step 0x5: 250ms/step 0x6: 500ms/step 0x7: 1000ms/step
BPE_L0_LIM _ATK	2:0	Sets the BPE level 0 limiter attack rate.	0x0: 2.5µs/step 0x1: 5µs/step 0x2: 10µs/step 0x3: 25µs/step 0x4: 50µs/step 0x5: 100µs/step 0x6: 250µs/step 0x7: 500µs/step

BPE Threshold Hysteresis (0x2106)

BIT	7	6	5	4	3	2	1	0
Field		BPE_VTHRESH_HYST[7:0]						
Reset		0x0						
Access Type				Write,	Read			

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_VTHRE SH_HYST	7:0	Sets the hysteresis to move up to the next level in the brownout controller. See the measurement ADC PVDD or VBAT channel result register to set these levels.	00000000: No hysteresis 00000001: 1 LSB of hysteresis 00000010: 2 LSBs of hysteresis : 1 LSB steps 11111101: 253 LSBs of hysteresis 11111110: 254 LSBs of hysteresis 11111111: 255 LSBs of hysteresis

BPE Infinite Hold Clear (0x2107)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	BPE_HLD_ RLS
Reset	_	_	_	_	_	_	_	
Access Type	_	_	_	_	_	_	_	Write Only

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_HLD_R LS	0	Manually releases the BPE controller when infinite hold is enabled.	0x0: Writing 0 has no effect. 0x1: Releases brownout-protection engine controller from infinite hold.

BPE Supply Source (0x2108)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	BPE_SRC_SEL[1:0]	
Reset	_	_	_	_	_	_	0x0	
Access Type	_	_	_	_	_	_	Write, Read	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_SRC_S EL	1:0	This bit selects the measurement ADC channel that is the input to the brownout-protection engine controller.	0x0: Measurement ADC PVDD channel is the input to the BPE controller. 0x1: Measurement ADC VBAT channel is the input to the BPE controller. 0x2: Measurement ADC VDDH channel is the input to the BPE controller.

BPE Lowest State (0x2109)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	BPE_LOWEST[2:0]		
Reset	_	_	_	_	_	0x0		
Access Type	_	_	_	_	_		Read, Ext	

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_LOWE ST	2:0	Returns the lowest level the brownout- protection engine has transitioned to. Upon reading the register it is updated to show the current level of the brownout controller.	000: Brownout inactive - normal operation 001: Level 3 010: Level 2 011: Level 1 100: Level 0 101 to 111: Reserved

BPE Lowest Gain (0x210A)

BIT	7	6	5	4	3	2	1	0		
Field		BPE_LOWEST_GAIN[7:0]								
Reset		0x0								
Access Type				Read	i, Ext					

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_LOWE ST_GAIN	7:0	Returns the lowest gain (highest gain attenuation) of the brownout-protection engine. Upon reading the register, it is updated to show the current gain attenuation applied by the BPE. Gain format: 5-bit integer and 3-bit fraction. The integer part is 1dB per step, while the fractional part is 1/8dB per step.	000: Brownout inactive - normal operation 001: Level 3 010: Level 2 011: Level 1 100: Level 0 101 to 111: Reserved

BPE Lowest Limiter (0x210B)

BIT	7	6	5	4	3	2	1	0		
Field		BPE_LOWEST_LIMIT[7:0]								
Reset		0x0								
Access Type				Read	i, Ext					

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_LOWE ST_LIMIT	7:0	Return the lowest limiter setting applied by the brownout-protection engine. Upon reading the register, it is updated to show the current limiter setting of the BPE. Limiter format: 4-bit integer and 4-bit fraction. The integer part is 1dB per step, while the fractional part is 1/16dB per step.	000: Brownout inactive - normal operation 001: Level 3 010: Level 2 011: Level 1 100: Level 0 101 to 111: Reserved

BPE Enable (0x210D)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	BPE_LIM_E N	BPE_EN
Reset	_	-	-	_	-	-	0x0	0x0
Access Type	_	_	_	_	_	_	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
BPE_LIM_E N	1	Enables BPE limiter function.	0x0: BPE limiter disabled. 0x1: BPE limiter enabled.
BPE_EN	0	Enables the BPE function.	0x0: BPE Disabled. 0x1: BPE Enabled.

Auto-Restart Behavior (0x210E)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	OVC_AUTO RESTART_ EN	THERM_AU TORESTAR T_EN	_	PVDD_AUT ORESTART _EN
Reset	_	_	_	_	0b0	0b0	0b0	0b0
Access Type	_	_	_	_	Write, Read	Write, Read	Write, Read	Write, Read

BITFIELD	BITS	DESCRIPTION	DECODE
OVC_AUTO RESTART_E N	3	Controls whether or not the speaker amplifier is automatically reenabled after an overcurrent fault condition.	O: Overcurrent recovery is in manual mode. Overcurrent recovery is in auto mode.
THERM_AU TORESTART _EN	2	Controls whether or not the device automatically returns to the active state when the die temperature recovers from thermal shutdown.	Thermal shutdown recovery is in manual mode. Thermal shutdown recovery is in auto mode.
VBAT_AUTO RESTART_E N	1	Controls whether or not the device automatically returns to the active state when VBAT recovers from UVLO event.	0: VBAT UVLO recovery is in manual mode. 1: VBAT UVLO recovery is in auto mode.
PVDD_AUT ORESTART_ EN	0	Controls whether or not the device automatically returns to the active state when PVDD recovers from UVLO event.	0: PVDD UVLO recovery is in manual mode. 1: PVDD UVLO recovery is in auto mode.

Global Enable (0x210F)

BIT	7	6	5	4	3	2	1	0
Field	_	_	_	_	_	_	_	EN
Reset	-	_	-	-	_	-	-	0x0
Access Type	_	_	_	_	_	_	_	Write, Read, Ext

BITFIELD	BITS	DESCRIPTION	DECODE
EN	0	Disable or enable all blocks and reset all logic except the I ² C interface and control registers.	

Revision ID (0x22FF)

BIT	7	6	5	4	3	2	1	0
Field		REV_ID[7:0]						
Reset		0x43						
Access Type		Read Only						

BITFIELD	BITS	DESCRIPTION	DECODE
REV_ID	7:0	Revision of the device. Updated at every device revision.	0x43: Device Revision

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

Applications Information

Layout and Grounding

Proper layout and grounding are essential for optimum performance. Use at least four PCB layers and add thermal vias to the ground/power plane close to the device to ensure good thermal performance and high-end output power. Good grounding improves audio performance and prevents switching noise from coupling into the audio signal. Ground the power signals and the analog signals of the IC separately at the system ground plane, to prevent switching interference from corrupting sensitive analog signals. Place the recommended supply decoupling capacitors as close as possible to the IC. The PVDD to PGND connection must be kept short and should have minimum trace length and loop area to ensure optimal Noise, THD+N, and EMI performance. Use wide, low-resistance output, supply and ground traces. As load impedance decreases, the current drawn from the device outputs increase. At higher current, the resistance of the output traces decreases the power delivered to the load. For example, if 2W is delivered from the speaker output to a 4Ω load through a $100m\Omega$ trace, 49mW is consumed in the trace. If power is delivered through a $10m\Omega$ trace, only 5mWis consumed in the trace. Wide output, supply, and ground traces also improve the power dissipation of the device. The device is inherently designed for excellent RF immunity. For best performance, add ground fills around all signal traces on the top and bottom PCB planes. It is advisable to follow the layout of the MAX98397 EV kit as closely as possible in the application. Thermal and performance measurements shown in the MAX98397 EV kit data sheet were measured with a 6-layer board (θ_{JA} = 28°C/W). As a result, the EV kit performance is likely better than what can be achieved with a JEDEC standard board.

Recommended External Components

Table 13 shows the recommended external components. See the Typical Application Circuit for more details.

Table 13. Component List

BUMP	VALUE	SIZE	VOLTAGE RATING (V)	DIELECTRIC
PVDD	220µF ± 20%	_	50	Alum-Elec
PVDD	10μF ± 10%	1206	50	X5R
PVDD	1µF ± 10%	0603	50	X5R
PVDD	0.1µF ± 10%	0402	50	X7R
VBAT	1µF	0402	16	X5R
VBAT	10µF	0603	25	X5R
DVDD	1µF ± 20%	0201	6.3	X5R
AVDD	1µF ± 20%	0201	6.3	X5R
VBOOTP	0.1µF ± 10%	0402	16	X7R
VBOOTN	0.1µF ± 10%	0402	16	X7R

Bootstrap Capacitors

The output stage of the MAX98397 uses nMOS power FETs as high-side drivers to provide high output power with high efficiency in a small package. A bootstrap capacitor connected between the OUTx pin and VBOOTx pin acts as a floating power supply for the gate driver of the high-side nMOS power FET of the corresponding OUTx pin. During normal operation, the bootstrap capacitor gets charged when the PWM output forces the OUTx pin low i.e., the low-side nMOS power FET of the corresponding OUTx pin is on. As the high-side power FET of the OUTx pin turns on, OUTx and the corresponding VBOOTx pin voltages rise due to capacitive action, thus providing the required high-side driver voltage. The necessary charge to turn on the high-side power FET comes from the bootstrap capacitor, and hence every time the high-side power FET turns on, it loses charge which needs to be replenished during the next low-side turn-on. Thus, it is important to choose a bootstrap capacitor value that can sustain this switching action i.e., large enough to not lose too much charge during high-side turn-on, and any other supervisory circuit biased from the bootstrap capacitor supply.

However, there is an upper limit to how large the bootstrap capacitor can be, apart from being too large on the PCB. During hard-clipping at the output of the Class-D amplifier, the high-side power FET of the OUTx pin can remain on for

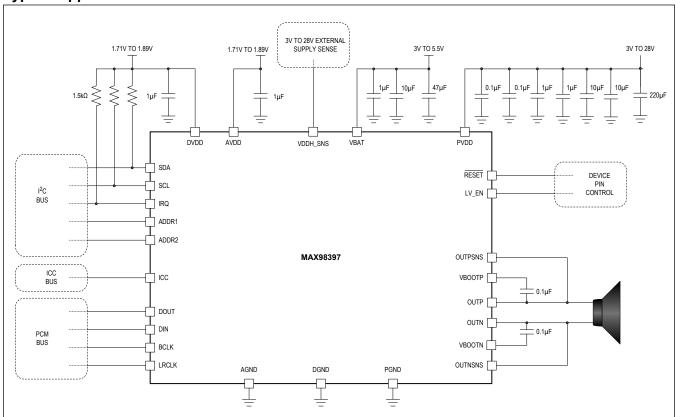
28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

hundreds of microseconds. This causes the bootstrap capacitor to continue to lose charge due to charge consumption by internal circuitry and capacitance leakage. When the bootstrap capacitor voltage becomes too low, it forces a small cycle of low-side turn-on to replenish the charge on the bootstrap capacitor. This is called a refresh cycle and care much be taken to ensure that a large capacitor value does not force a refresh cycle at a rate that affects the audio band.

It is recommended to use a 0.1µF, 16V capacitor as a bootstrap capacitor with the MAX98397 and to place the capacitor as close to the pins as possible to minimize the loop between the OUTx and VBOOTx pins.

Typical Application Circuits

Typical Application Circuit



Ordering Information

PART NUMBER	TEMP RANGE	PIN-PACKAGE
MAX98397EWB+	-40°C to +85°C	35 WLP
MAX98397EWB+T	-40°C to +85°C	35 WLP

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

MAX98397

28V Digital Input, Class-DG Amplifier with IV_{SENSE}, Ultra-Low I_Q, and Brownout Prevention

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	10/23	Release for Market Intro	_



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Analog Devices Inc.:

MAX98397EWB+T MAX98397EVSYS#